

ASUS CONFIDENTIAL

MODEL NAME : *Elsa*

PCB NO : ???

ASUS P/N : ???

Lanai Discrete VGA nVidia NB8M Schematics Document

uFCPGA Mobile Merom
Intel Crestline-PM + ICH8M

2007-03-19

REV : 1.2(DELL: X02)

MB PCB	
Part Number	Description
DA80004H0L	PCB 00B LA-3071P REV0 M/B

BOM NO. ???
PCB P/N: ???

<Variant Name>

PROJECT: **Lanai**

REVISION
1.2

DATE: *Monday, March 19, 2007*
SHEET **1** OF **69**

DESCRIPTION: *Cover Page*

SCHEMATIC FILE NAME :
RELEASE DATE :

DESIGN ENGINEER :
Terry Lin

LANAI: DISCRETE

CLOCK
CK410M+LP
PG 21

POWER

POWER SEQUENCE LOGIC	PG 51
POWER CHARGER	PG 57
POWER CONTROL SWITCH	PG 49
DISCHARGE PATH	PG 49
+3.3V_SUS/+5V_SUS/+3.3V_RUN +5V/+3.3V/+1.8V/+1.25V_RUN	

POWER CON. PG 59

Merom
(478 Micro-FCPGA)
PG 7,8
(Symbol Rev.09)

POWER

POWER I/O	PG 55
+1.5V_RUN/+1.05V_VCCP	
REGULATOR	PG 58
+VCC_GFX_CORE/+1.25V_RUN	
POWER VCORE	PG 53
POWER SYSTEM	PG 54
5V_ALW & 3.3V_ALW	
REGULATOR	PG 56
+1.8V_SUS/+0.9V_DDR_VTT	

Panel Connector PG 28

nVIDIA G86M
PCI EXPRESS GFX
PG 22,23,24,25,26,27

Crestline
1299 uFCBGA
PG 9,10,11,12,13,14
(Symbol Rev.09)

IO Board

CRT CONN. VGA

TV CONN. TVOUT

USB CONN.x2 USB2.0 (P2,3)

MINI-CARD WLAN PCIEx1 (Lane2)

MINI-CARD WWAN USB2.0 (P9)

D.B CON PG 50

SIM CARD Board

AUDIO/AMP PG 44,45,46

MDC PG 36

S/PDIF TO TV CONN. PG 30

DIGITAL MIC. PG 28

Speaker CON PG 46

WtoB CON PG 46

Audio Jacks *3

JACK Board

RJ11 Board

ICH8-M
676 BGA
PG 15,16,17,18
(Symbol Rev.09)

USB2.0 (P0,P1) USB CONN. PG 39 USB Board

PCIE (Lane6)

PCI

PCIE (Lane4)

USB2.0 (P6)

USB2.0 (P7)

CARD READER 1394/R5C833 PG 32,33,34

BCM5906KMLG QFN-68 PG 47

RJ45/Magnetic PG 48

EXPRESS-CARD R5538 PG 35

USB2.0 (P5) CAMERA PG 28

SATA SATA-HDD PG 31

IDE CD-ROM PG 31

Bluetooth PG 41

SIO MEC5025 128KB Flash TMKBC 128 Pins VTQFP PG 37

SIO ECE5011 Expander USB 2.0 Hub (4) 128 Pins VTQFP PG 38

CIR PG 41

FLASH PG 40

Touchpad CON. PG 41

FAN & THERMAL EMC4001 PG 43

USER INTERFACE PG 42

SNIFFER PG 42

CAPBTN CON. PG 40

INDEX

Pg#	Description	DNI LIST
01	Cover Page	
02	Schematic Block Diagram	
03	INDEX	
04	Bus connection	
05	SMBUS BLOCK	
06	Power Rail	
07-08	CPU (Merom 、 Penryn)	
09-14	Crestline	
15-18	ICH8M	
19-20	DDRII SO-DIMM(533MHz 、 667MHz)	
21	Clock Generator (CK410M+LP)	
22-27	VGA (nVIADA - G86M & GDDR3)	
28	LVDS CON & Camera & DMIC	
29	RGB CON	
30	TV OUT CON	
31	SATA(HDD & CD_ROM)	
32-34	MEDIA CARD READER / 1394 (R5C833)	
35	PCI-Express Card	
36	MDC CONN	
37	EC (MEC5025)	
38	SIO (ECE5011)	
39	USB PORT x 2	
40	FLASH & RTC & CAPBTN CONN	
41	TOUCH PAD & BT & CIR & LID	
42	SWITCH & LED	
43	HARDWARE MONITOR (EMC4001)	
44-46	AUDIO CODEC & AMP	
47	LOM BCM5906	
48	Magnetics and RJ-45	
49	Power Control Switch	
50	BtoB CON	
51	Power Sequence Logic	
52	XDP	
53-59	Power Circuit	
60	SCREW PAD	
61	Change list (1)	
62	Change list (2)	
63	Change list (3)	

Pg#	Description	DNI LIST
64	Power circuit Change list	
R01	Modem board cover page	
R02	RJ-11 CONN	
R03	Modem board Change list	
U01	USB board cover page	
U02	USB PORT (SINGLE * 2)	

<Variant Name>

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DESCRIPTION: INDEX

SCHEMATIC FILE NAME :
RELEASE DATE :

DESIGN ENGINEER :
Terry Lin

Footprint Definition	
Resistor	Footprint is 0402 if there is no description
Capacitor	Footprint is 0402 if there is no description
Ferrite Bead	Footprint is 0603 if there is no description

Layout Note

For all of ESD diode, they should be placed as close as possible to connectors and the signals from connectors should be routed to ESD diodes first. There is no branch or via before diodes

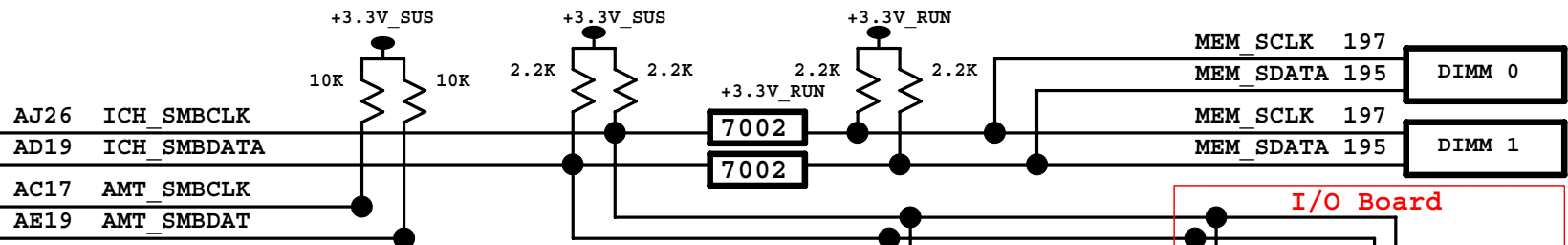
PCI TABLE			
PCI DEVICE	IDSEL	REQ#/GNT#	PIRQ
R5C833	PCI_AD17	PCI_REQ1# PCI_GNT1#	PCI_PIRQC# PCI_PIRQD#

PCI Express TABLE	
Lane 1	WWAN / Mini Card
Lane 2	WLAN / Mini Card
Lane 3	
Lane 4	ExpressCard
Lane 5	
Lane 6	LAN BCM5906KMLG

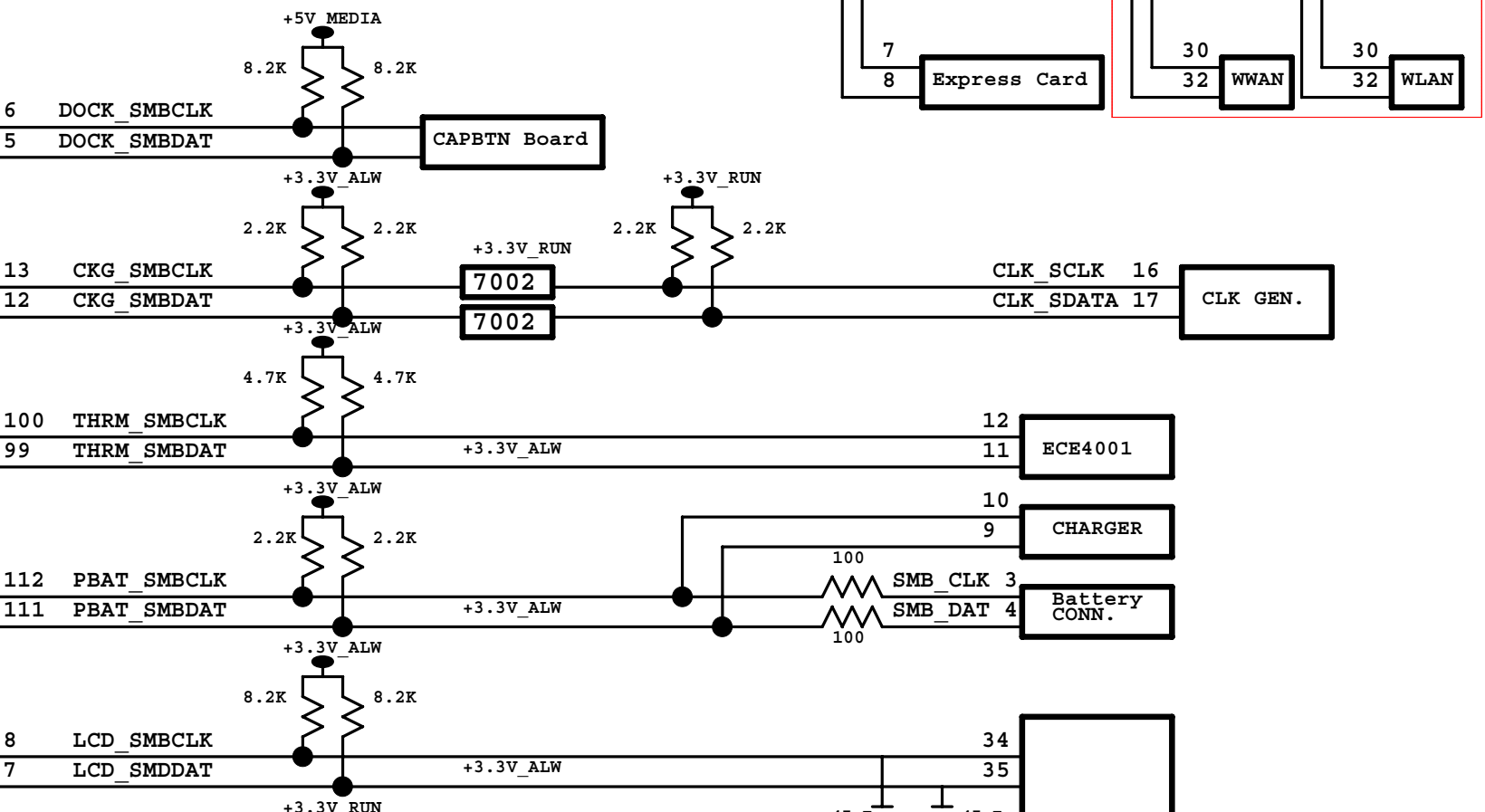
USB TABLE	
ICH8-0 (EHCI#1)	User1 (Single port , in USB BD)
ICH8-1 (EHCI#1)	User2 (Single port , in USB BD)
ICH8-2 (EHCI#1)	User3 (Dual port-bottom , in I/O BD)
ICH8-3 (EHCI#1)	User4 (Dual port-top , in I/O BD)
ICH8-4 (EHCI#1)	
ICH8-5 (EHCI#1)	Camera
ICH8-6 (EHCI#2)	ExpressCard
ICH8-7 (EHCI#2)	BT Module
ICH8-8 (EHCI#2)	
ICH8-9 (EHCI#2)	WWAN / Mini Card

Note : No USB for WLAN

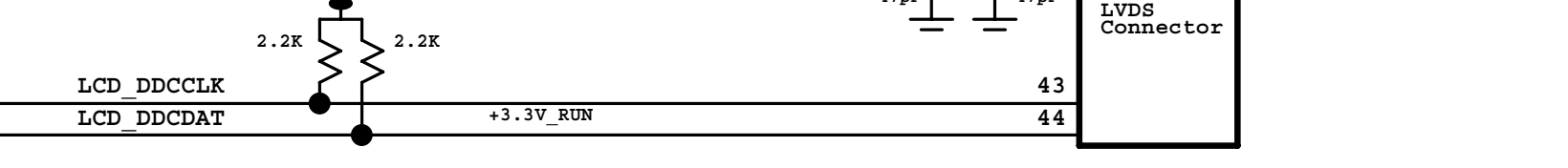
ICH8-M

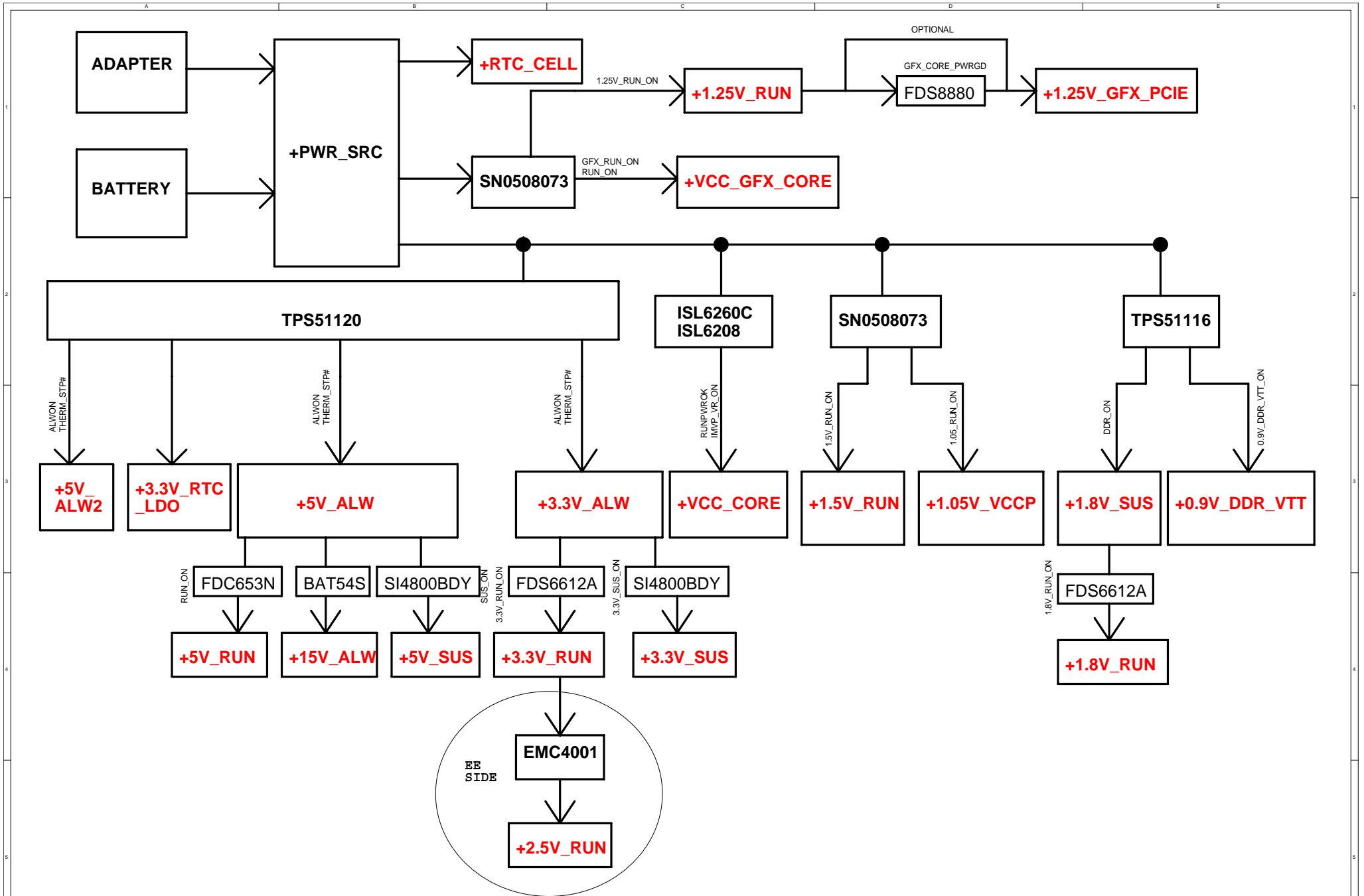


**SIO
MEC5025**



VGA





<Variant Name>

PROJECT: Lanai

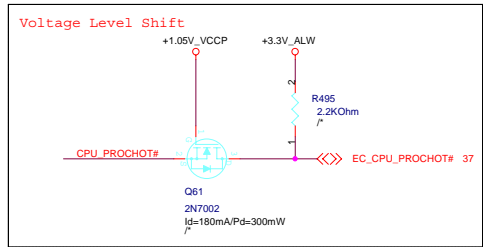
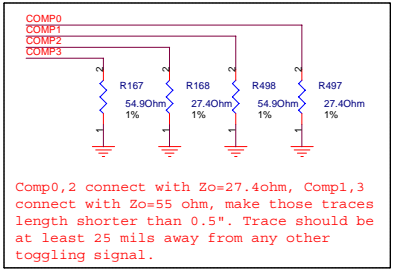
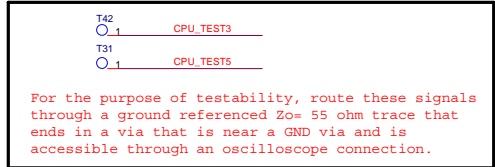
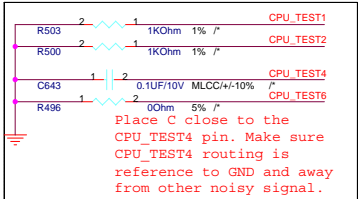
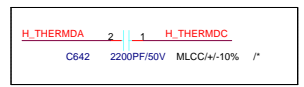
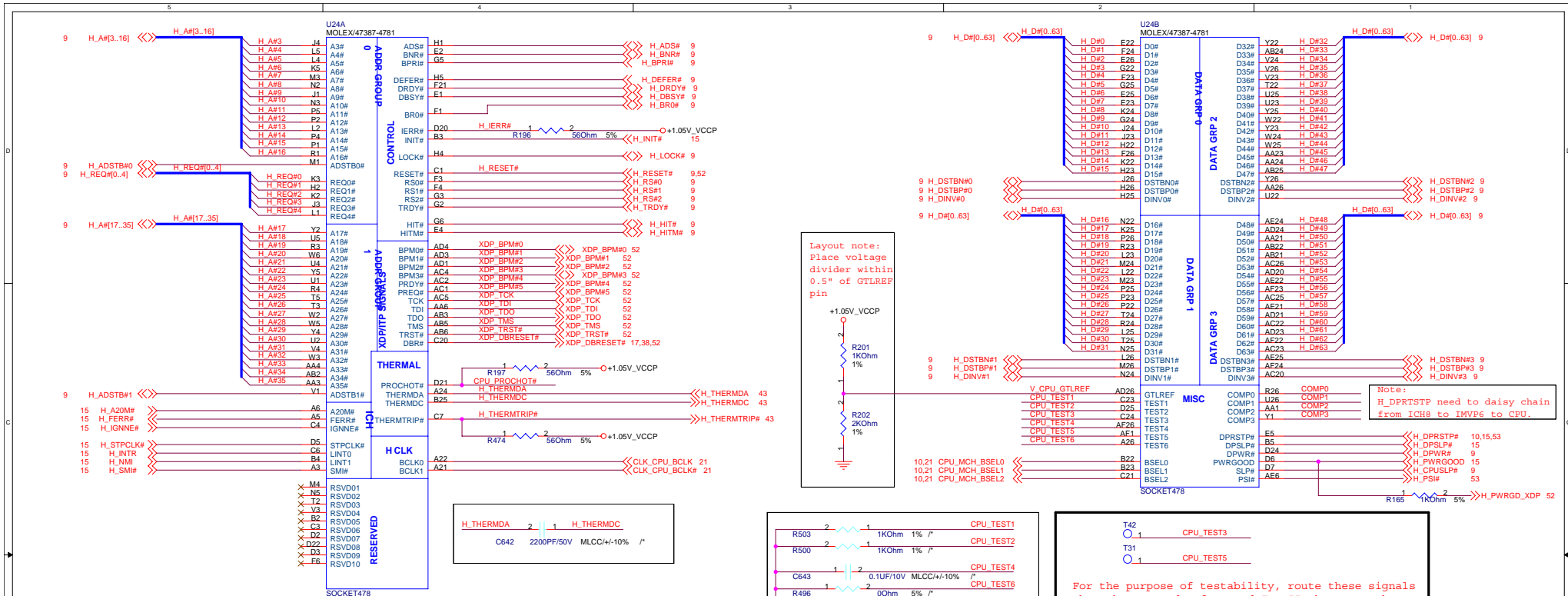
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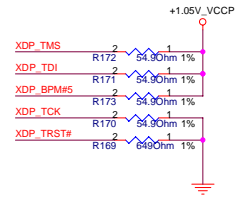
DESCRIPTION: Power Rail

SCHEMATIC FILE NAME :
RELEASE DATE :

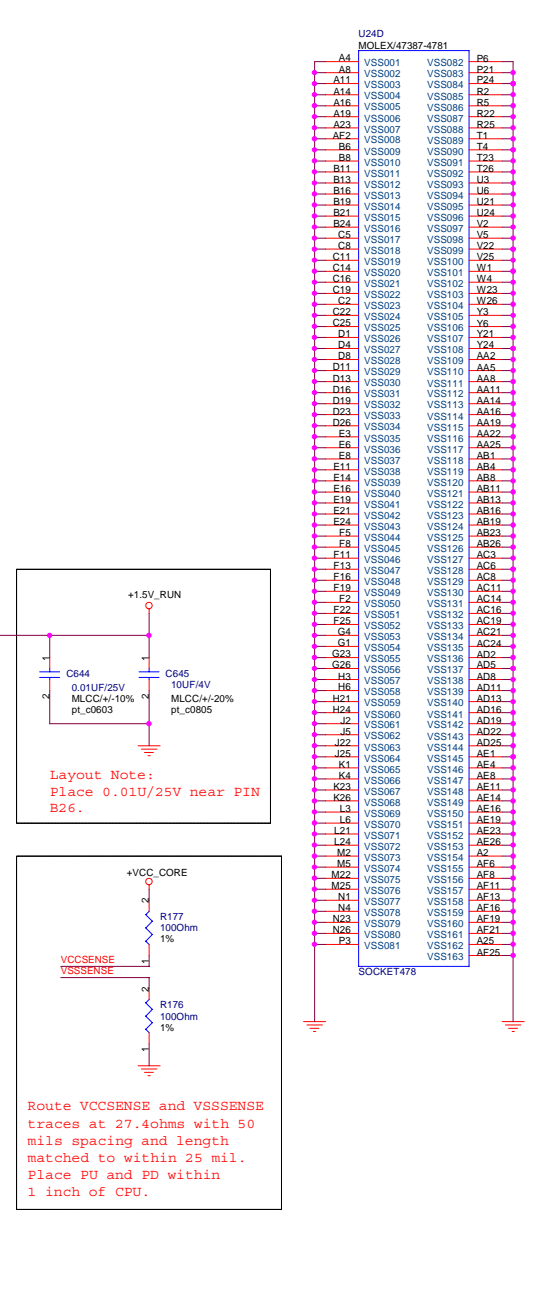
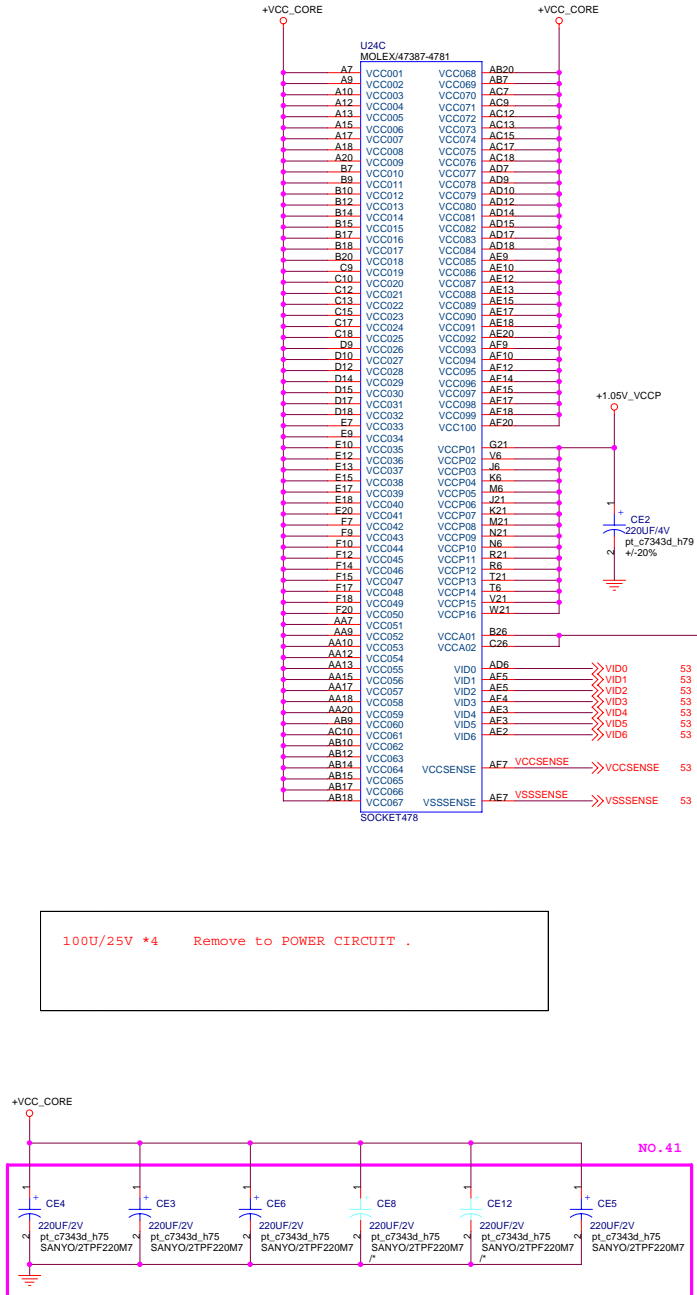
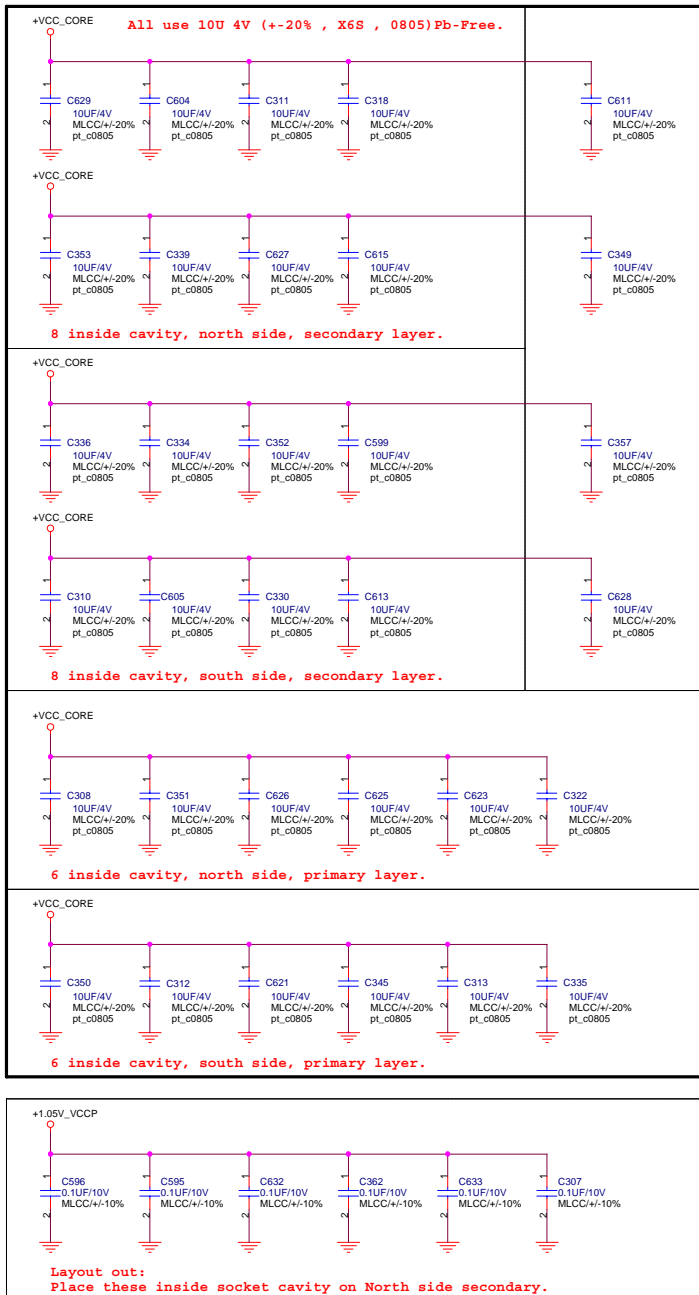
DESIGN ENGINEER :
Eric Ko



FSB	BCLK	BSEL2	BSEL1	BSEL0
533	133	0	0	1
667	166	0	1	1
800	200	0	1	0



<Variant Name>



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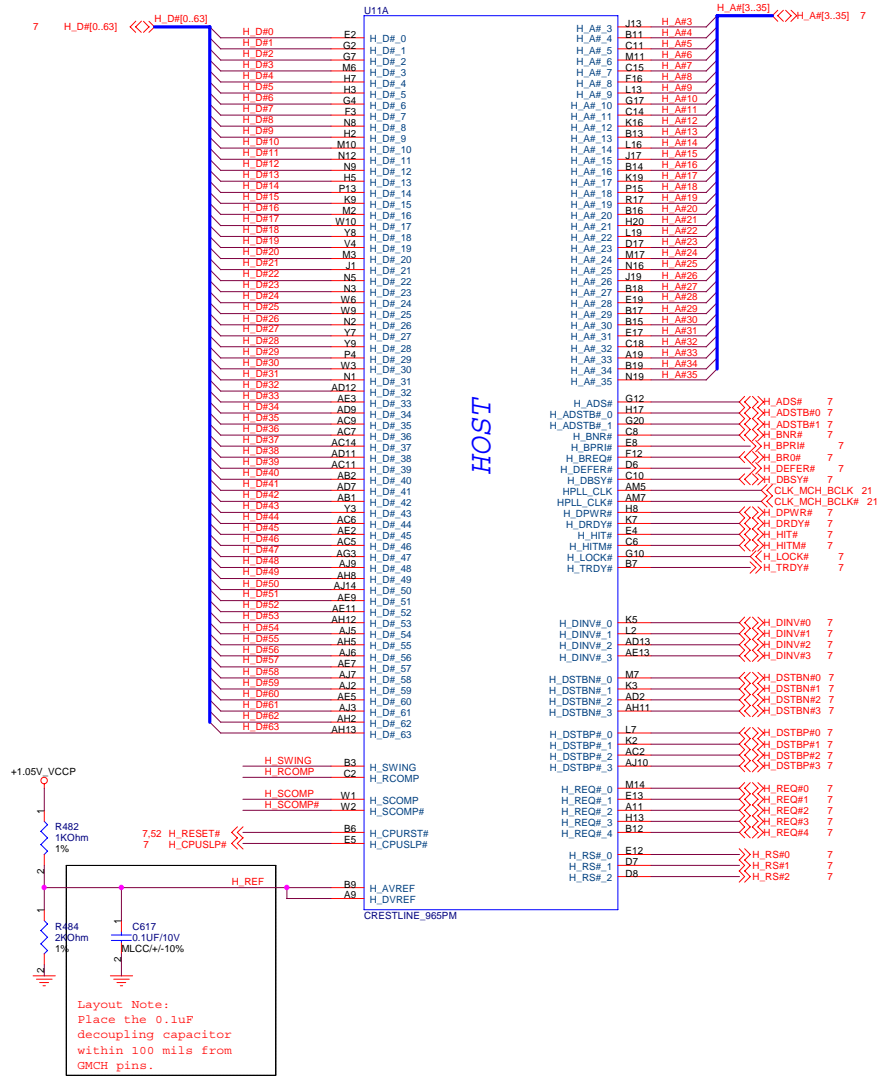
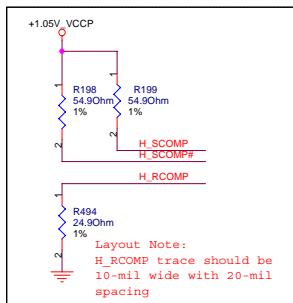
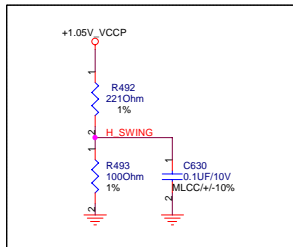
DESCRIPTION: Merom CPU (2)

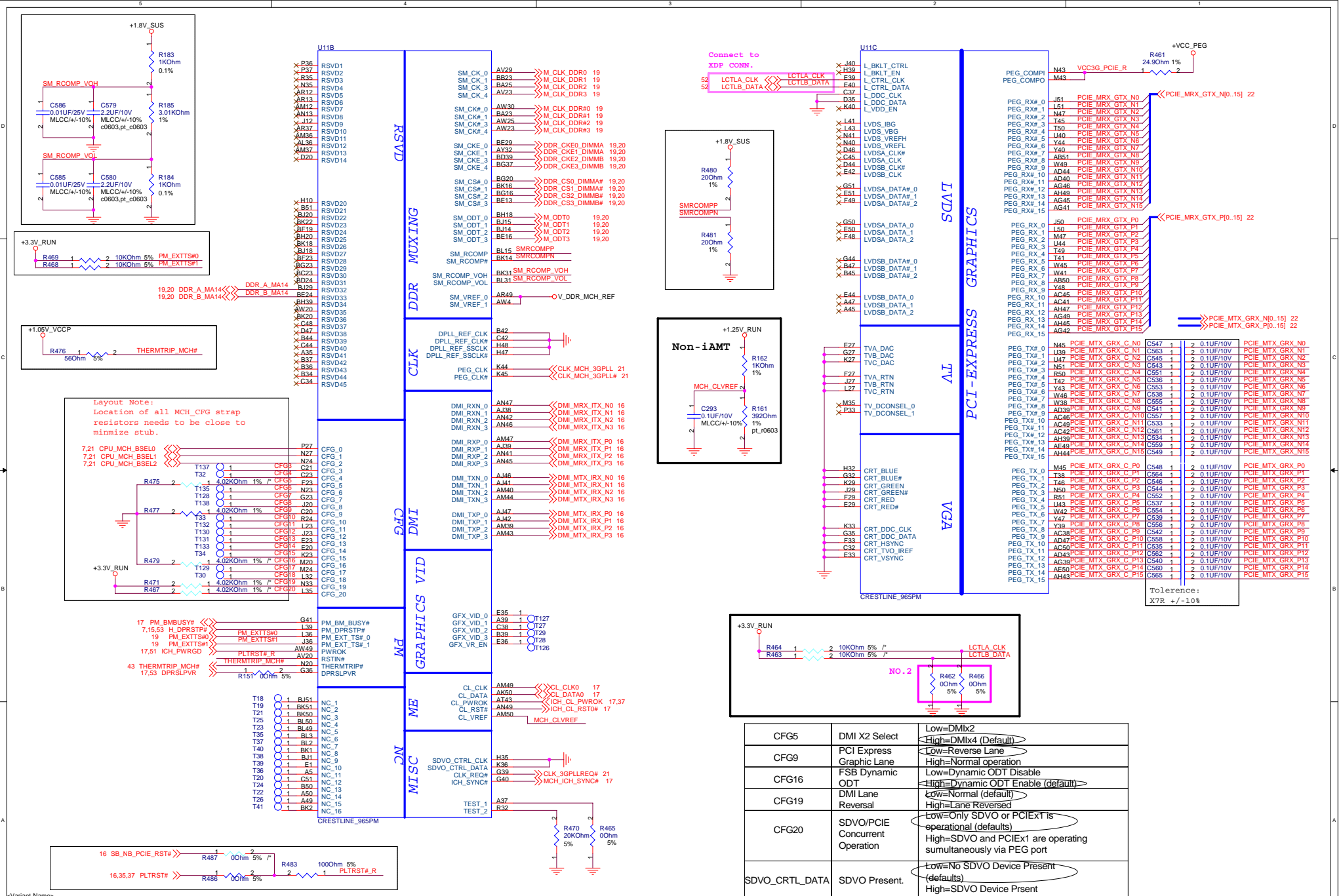
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DESIGN ENGINEER: Terry Lin

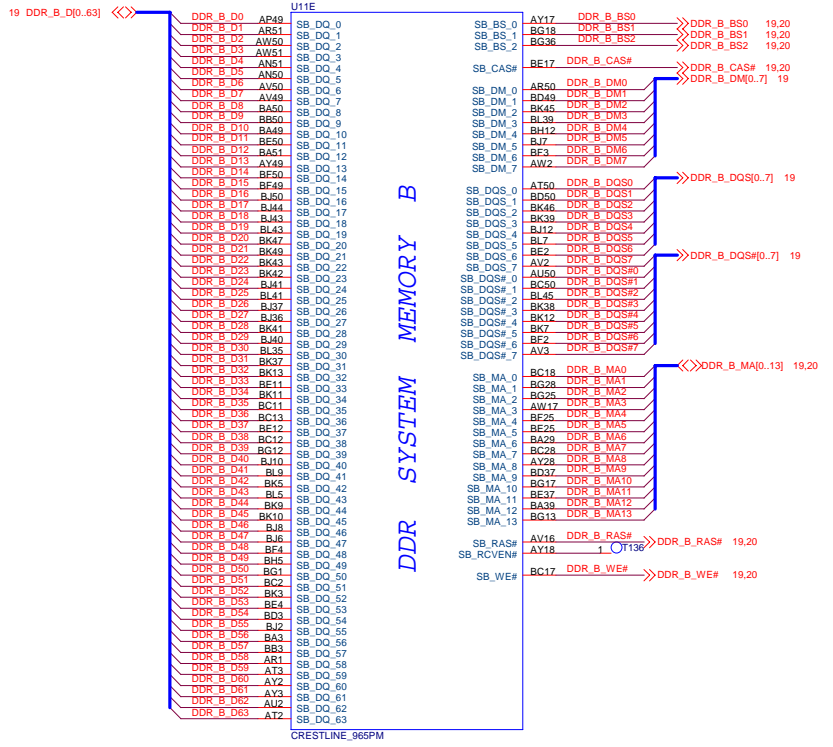
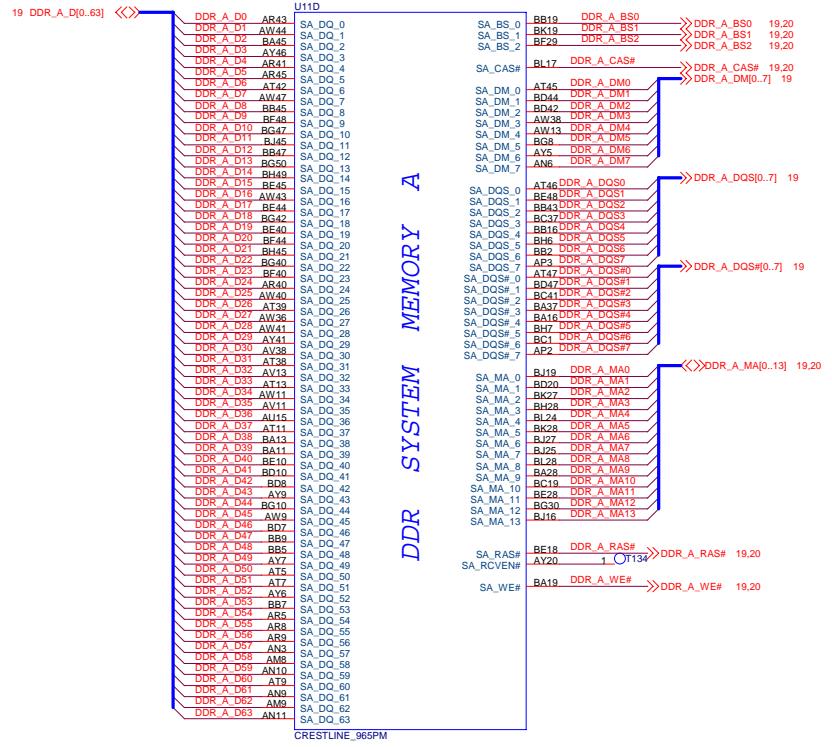
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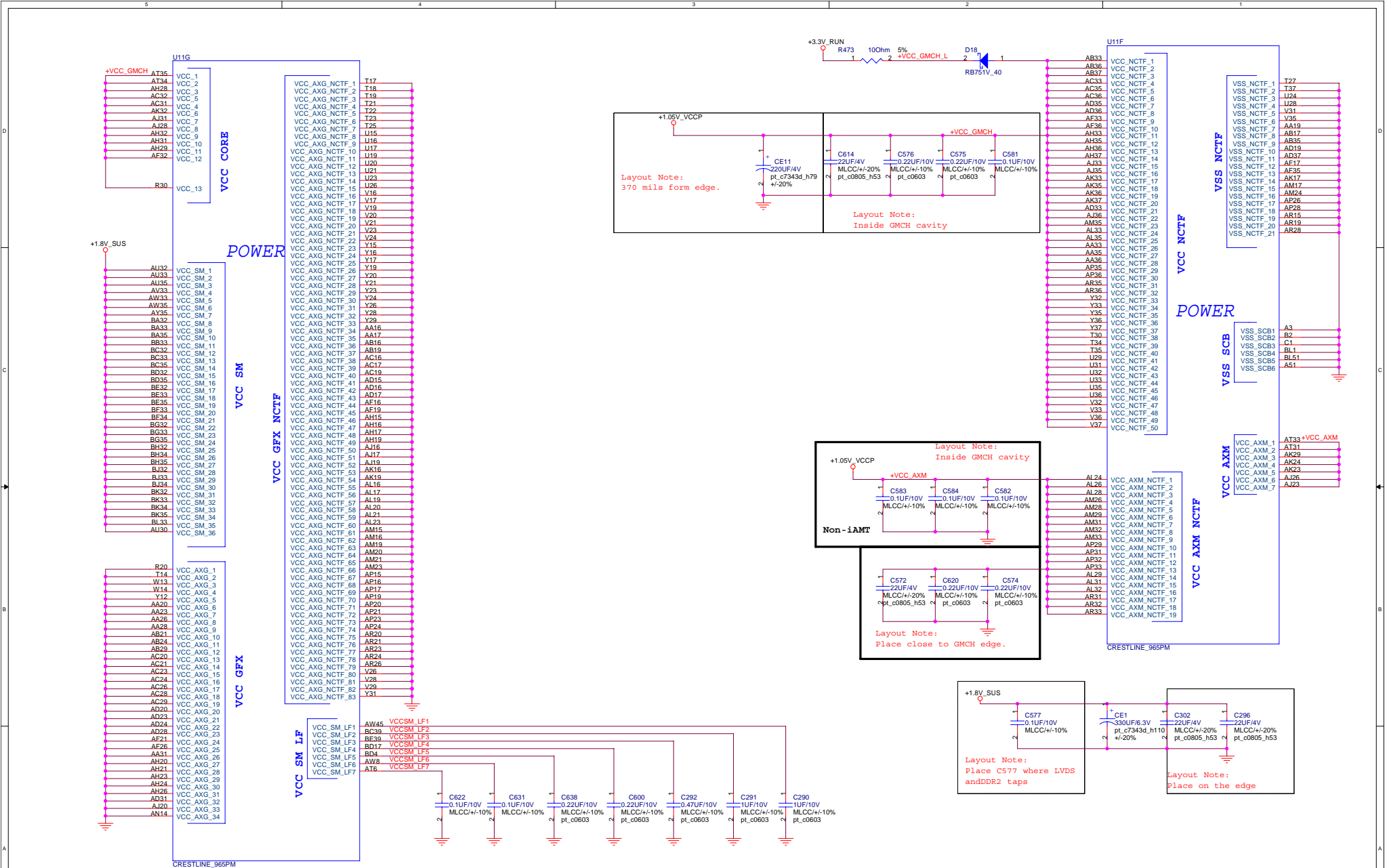
RELEASE DATE:



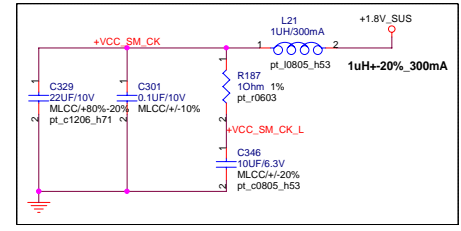
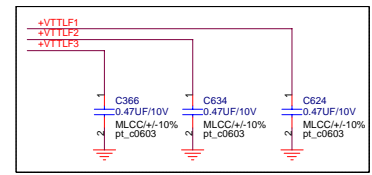
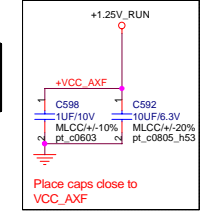
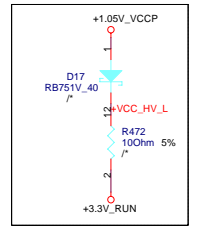
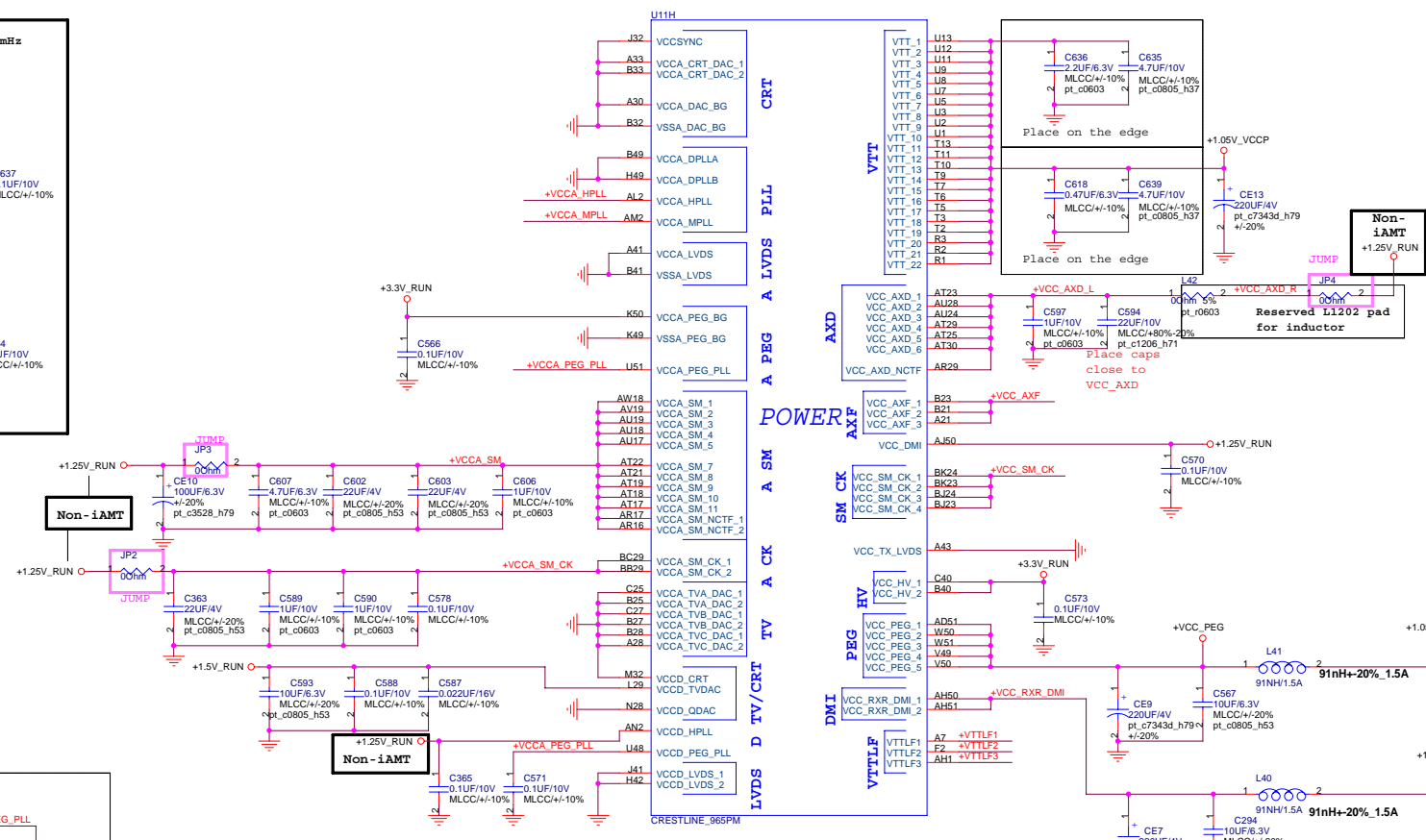
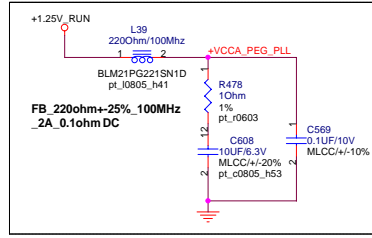
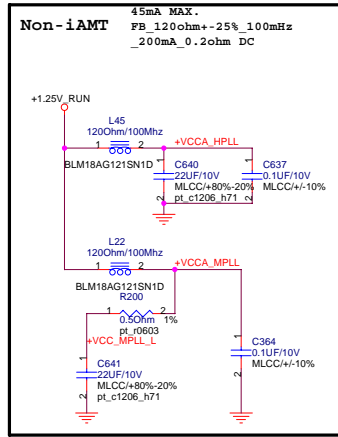


CFG5	DMI X2 Select	Low=DMiX2 High=DMiX4 (Default)
CFG9	PCI Express Graphic Lane	Low=Reverse Lane High=Normal operation
CFG16	FSB Dynamic ODT	Low=Dynamic ODT Disable High=Dynamic ODT Enable (default)
CFG19	DMI Lane Reversal	Low=Normal (default) High=Lane Reversed
CFG20	SDVO/PCIe Concurrent Operation	Low=Only SDVO or PCIe1 is operational (defaults) High=SDVO and PCIe1 are operating simultaneously via PEG port
SDVO_CRTL_DATA	SDVO Present	Low=No SDVO Device Present (defaults) High=SDVO Device Present

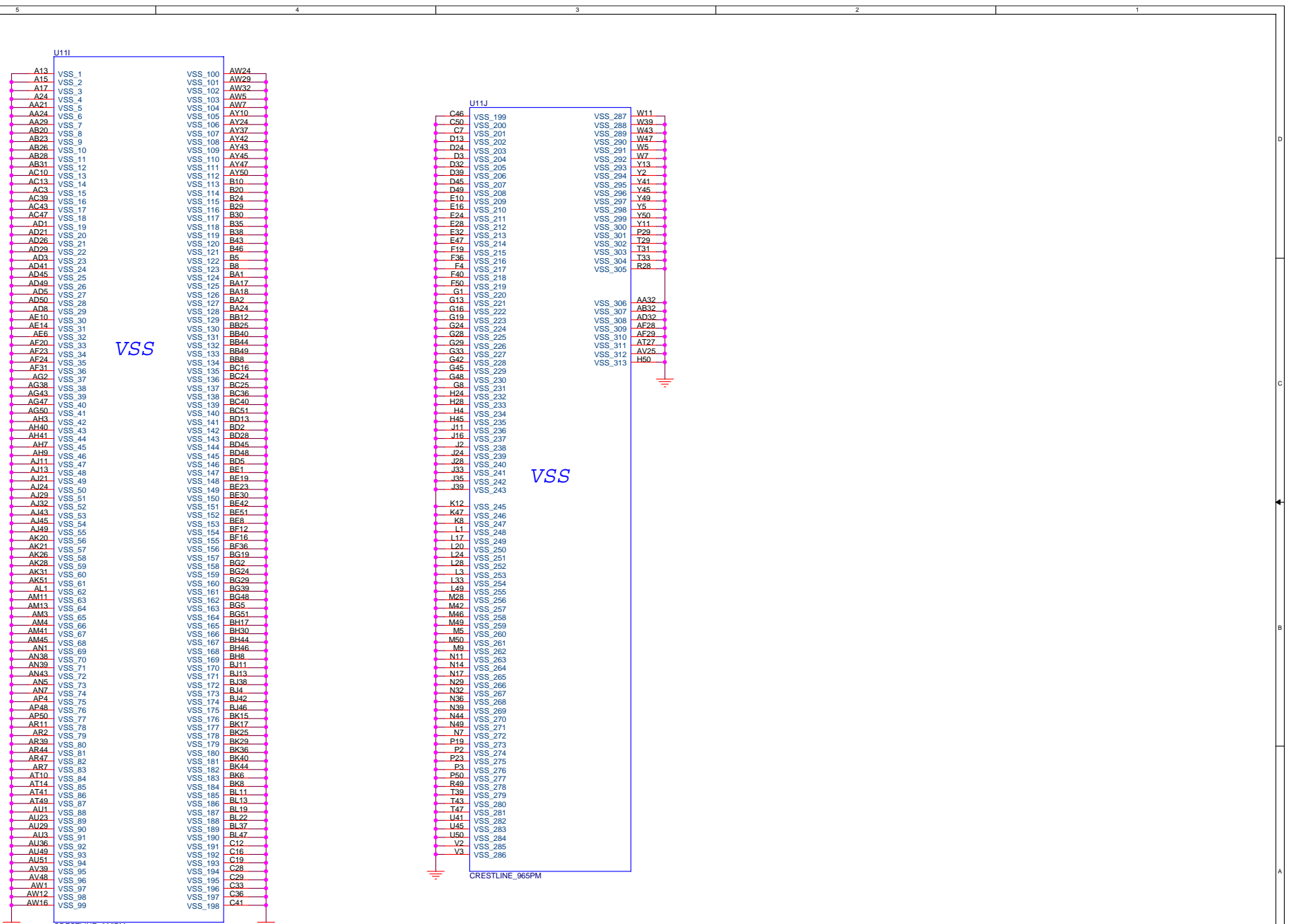




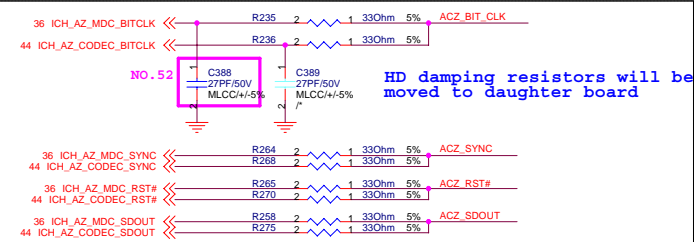
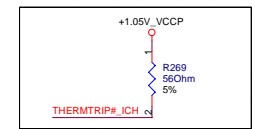
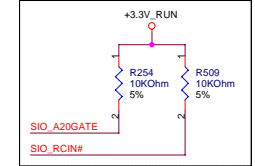
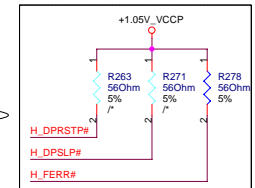
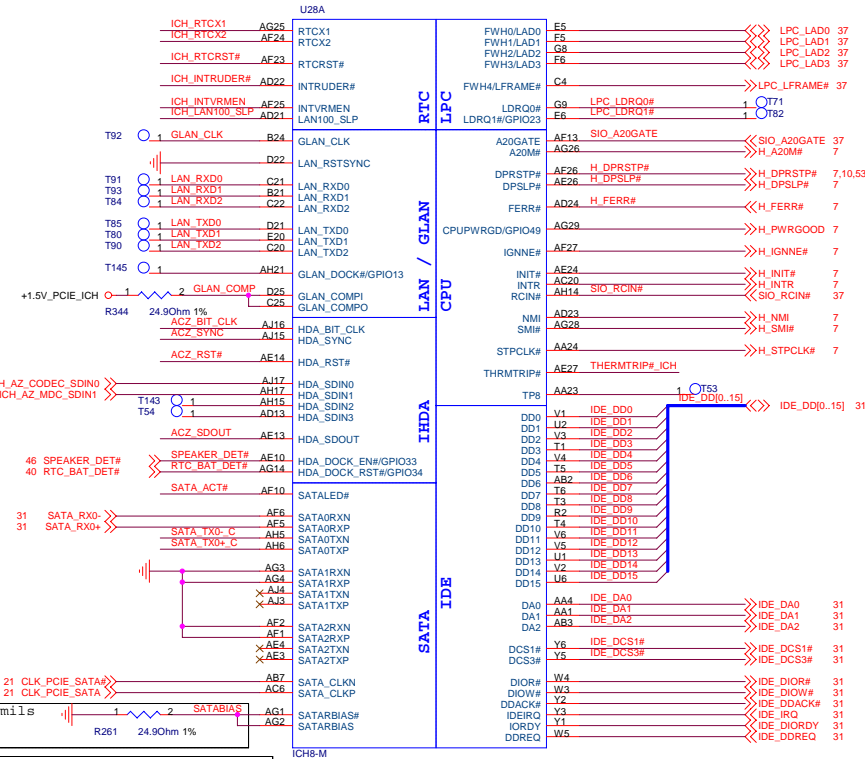
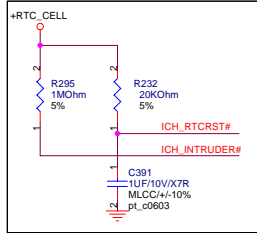
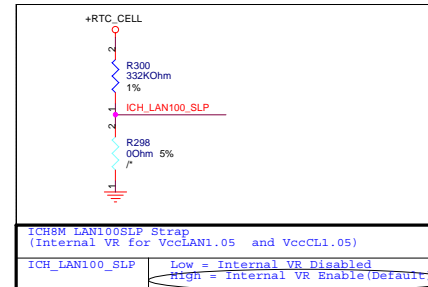
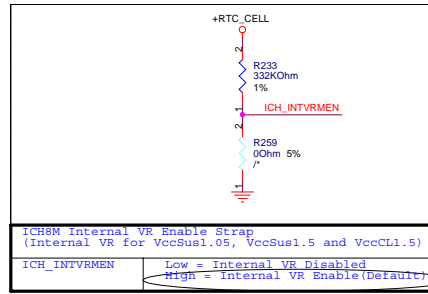
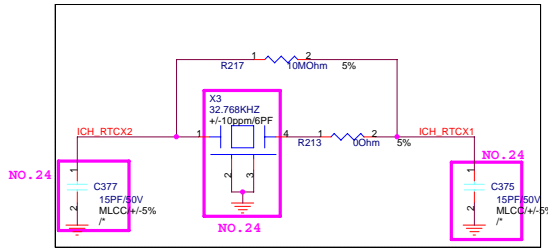
PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHMATIC FILE NAME :	DESIGN ENGINEER :
	1.2	SHEET 12 OF 69	Crestline (VCC, NCTF)	<OrgName>	Ivan Chou
				RELEASE DATE :	



Variant Name:	PROJECT: Lanai	REVISION: 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: Crestline (POWER)	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER: Ivan Chou
		SHEET 13 OF 69			RELEASE DATE:	

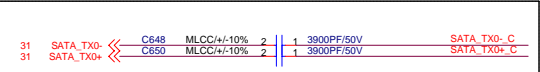


<Variant Name> PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
	1.2	SHEET 14 OF 69	Crestline (VSS)	RELEASE DATE :		Ivan Chou

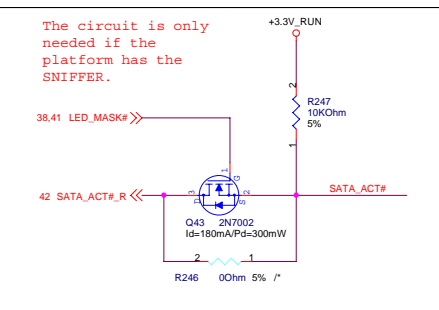


HD damping resistors will be moved to daughter board

Place all series terms close to ICH8 except for SDIN input lines, which should be close to source. Placement of R235, R264, R265, R258 should equal distance to the T split trace point as R236, R268, R270, R275 respective. Basically, keep the same distance from T for all series termination resistors.

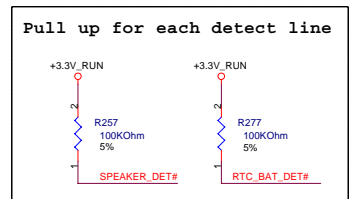


Distance between the ICH-8 M and cap on the "P" signal should be identical distance between the ICH-8 M and cap on the "N" signal for same pair.

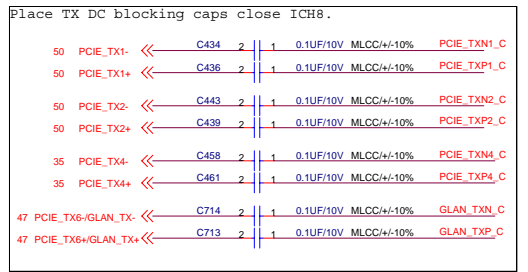
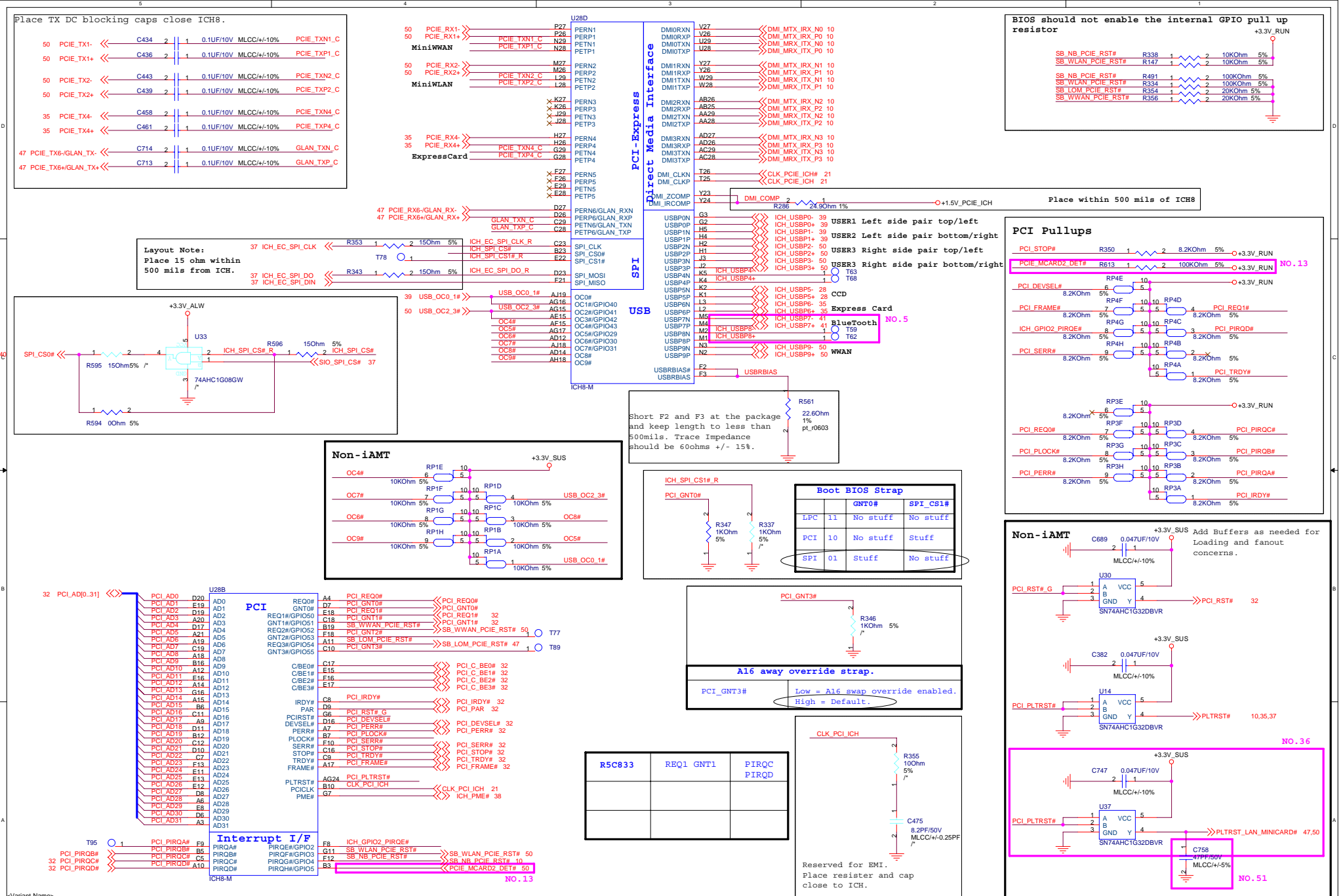


XOR Chain Entrance strap

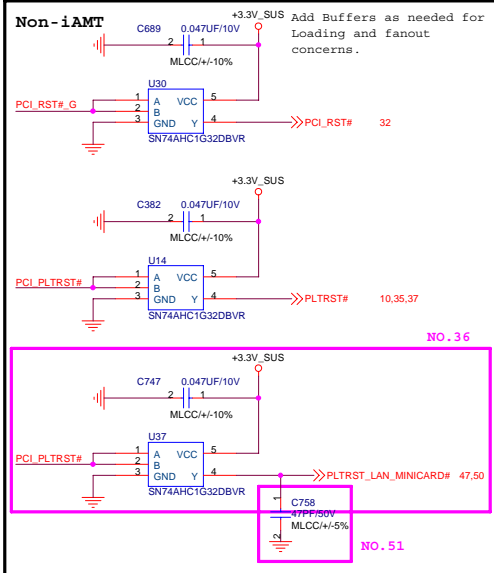
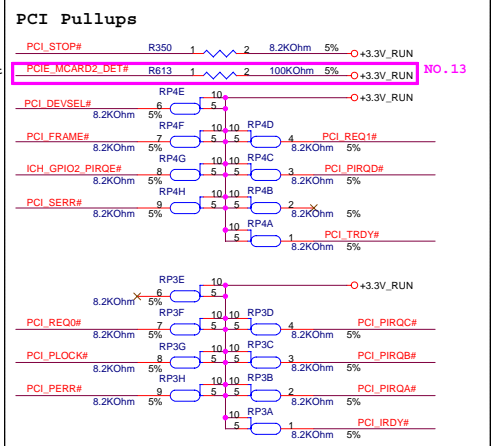
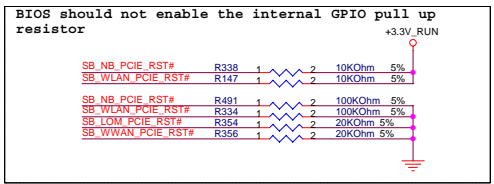
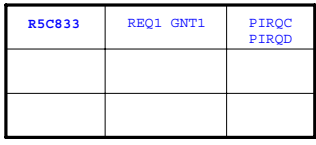
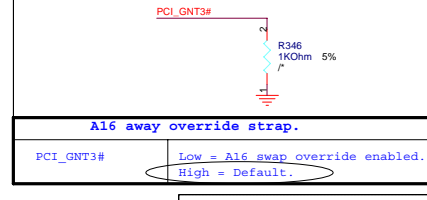
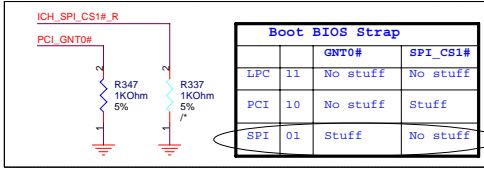
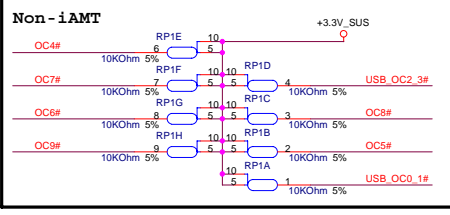
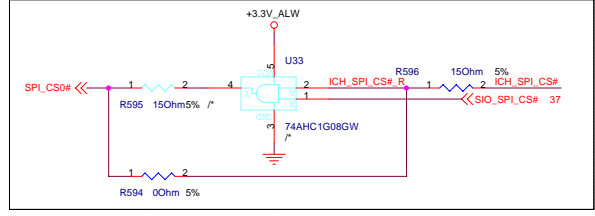
ICH_RSVD	ACZ_SDOUT	Description
0	0	RSVD
0	1	Enter XOR chain
1	0	Normal operation (Default)
1	1	Set PCIE port config bit 1

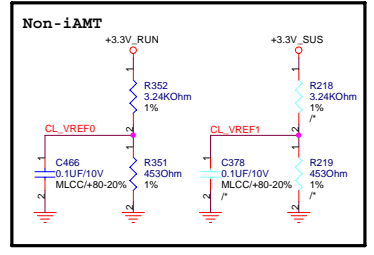
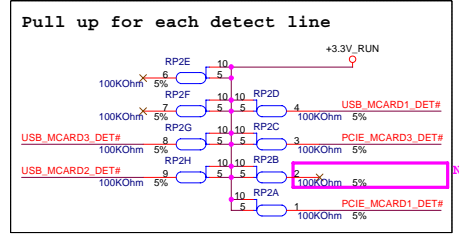
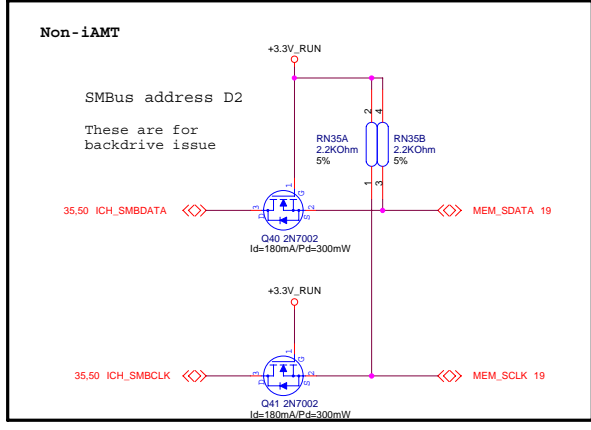
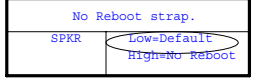
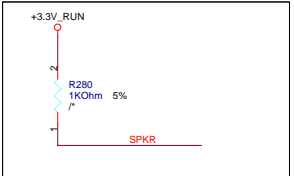
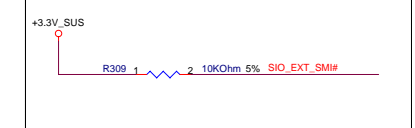
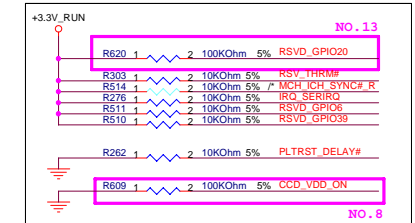
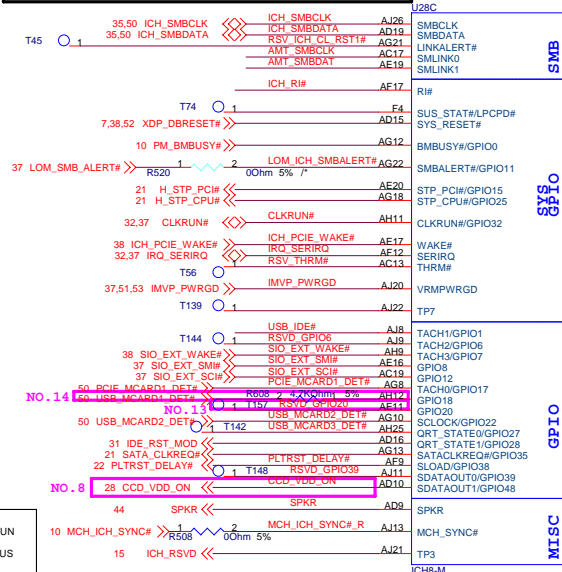
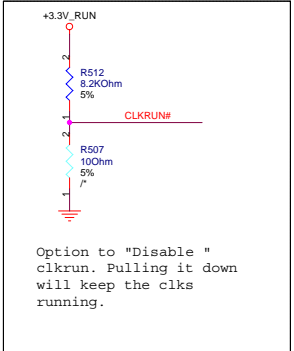
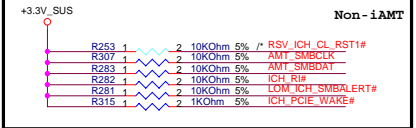
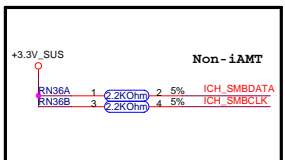


Variant Name:



Layout Note:
Place 15 ohm within
500 mils from ICH.





Variant Name:

PROJECT: Lanai

REVISION 1.2

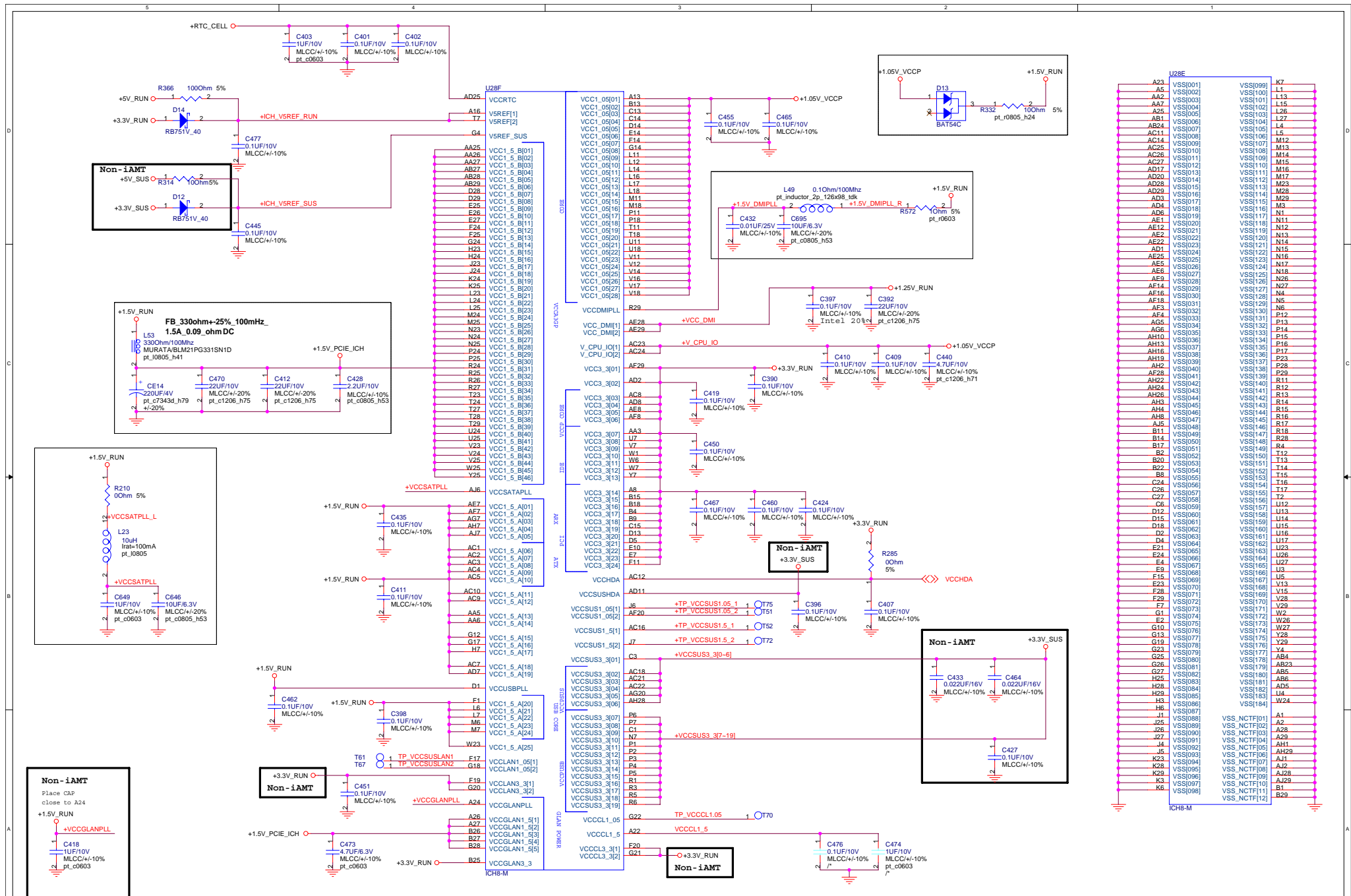
DATE: Monday, March 19, 2007
SHEET 17 OF 69

DESCRIPTION: ICH8: SMB/PWR/CLK/GPIO

SCHEMATIC FILE NAME: <OrgName>

DESIGN ENGINEER: Terry Lin

RELEASE DATE:



*Variant Name:

PROJECT: Lanai

REVISION: 1.2

DATE: Monday, March 19, 2007

DESCRIPTION: ICH8-M (POWER, GND)

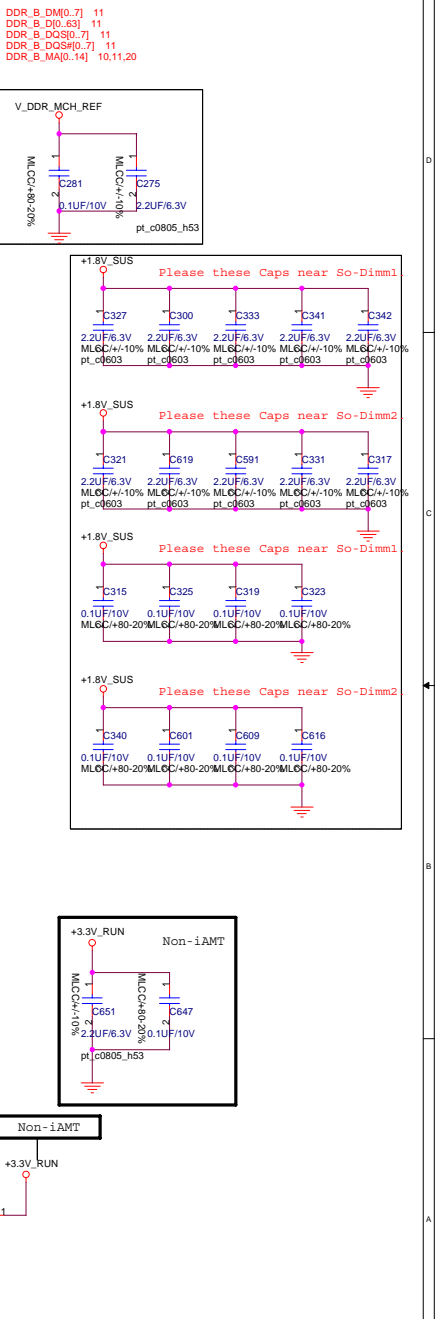
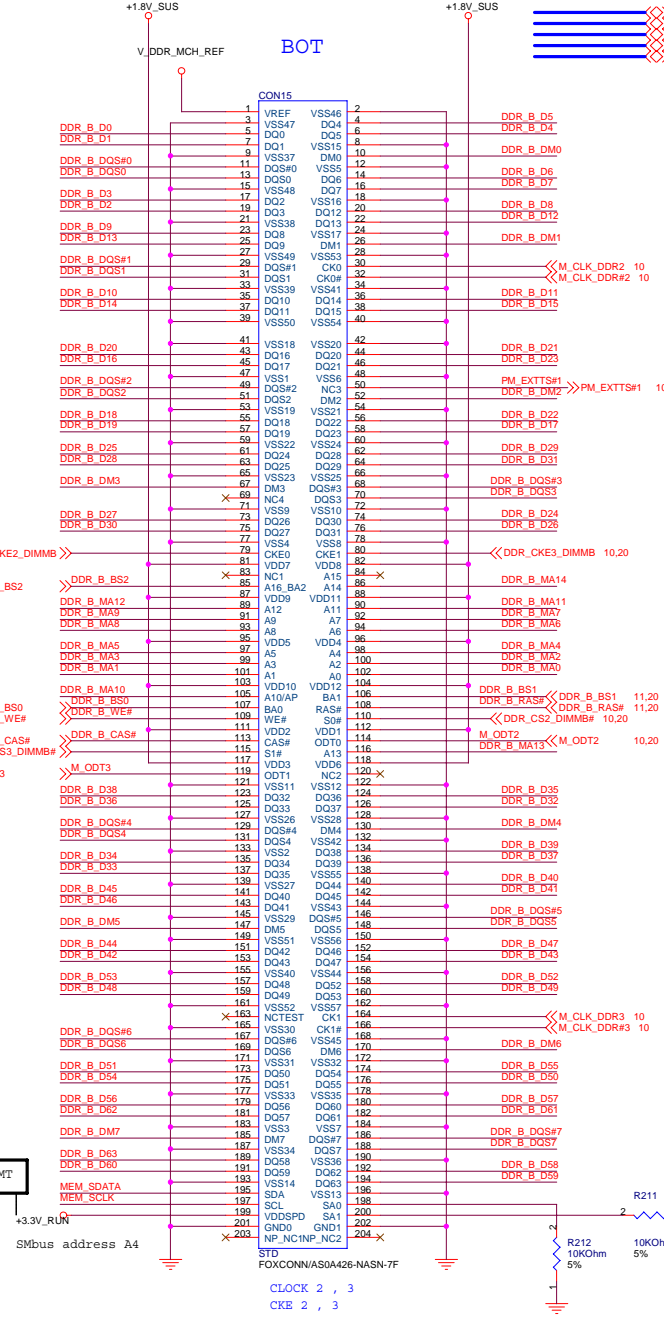
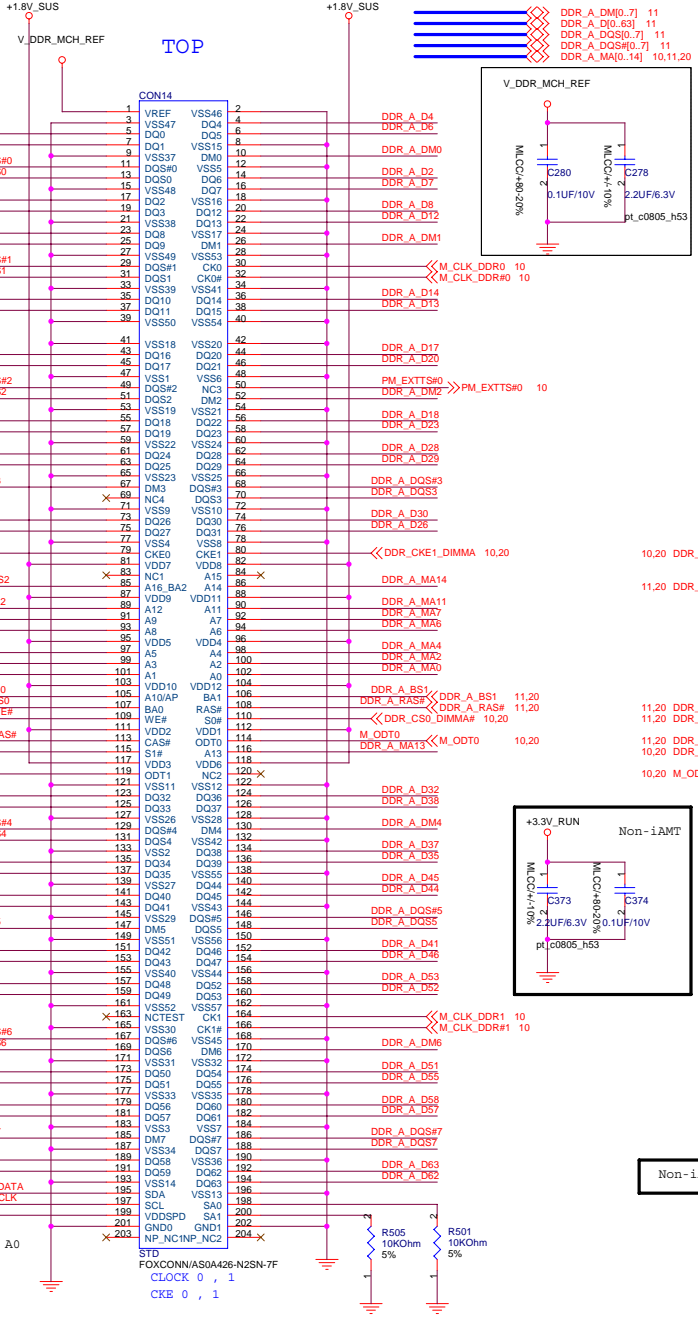
SCHEMATIC FILE NAME: <OrgName>

DESIGN ENGINEER: Terry Lin

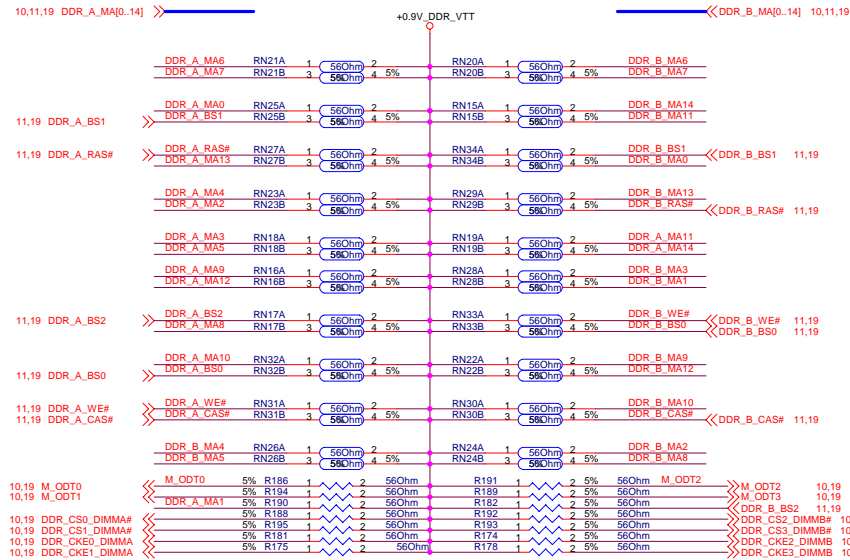
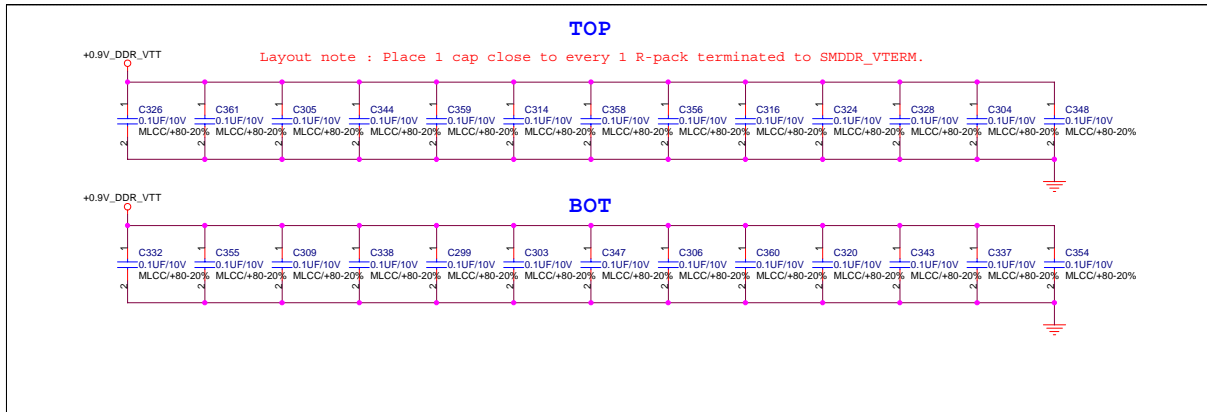
SHEET 18 OF 69

RELEASE DATE:

A is required to route to Top
SODIMM for AMT to function
Ch.A SODIMM needs to be
populated for Intel AMT support.



PROJECT: Lanai	REVISION: 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: DDR2 SO-DIMM (0)	SCHEMATIC FILE NAME: <OrgName>	DESIGN ENGINEER: STANLY HSU
	SHEET: 19	OF: 69		RELEASE DATE:	

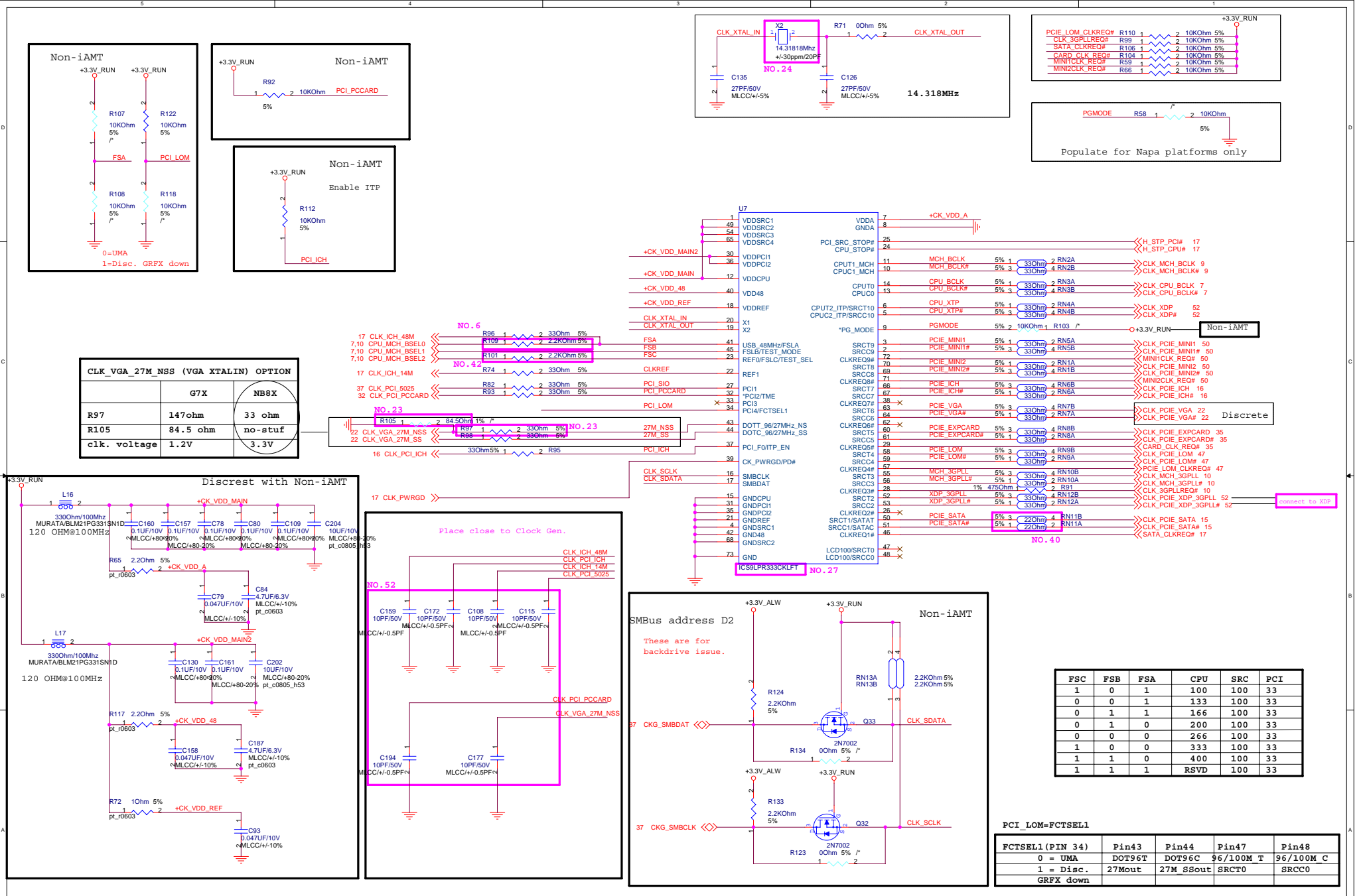


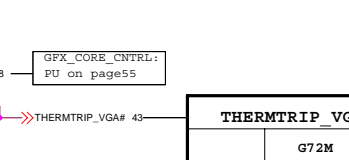
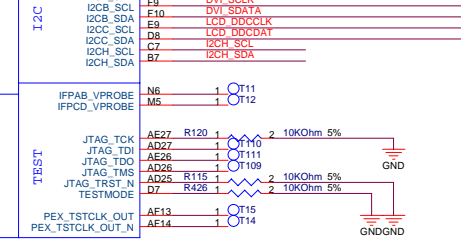
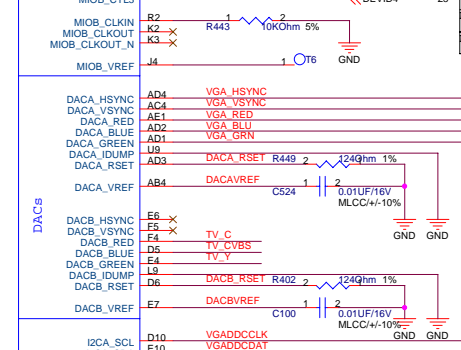
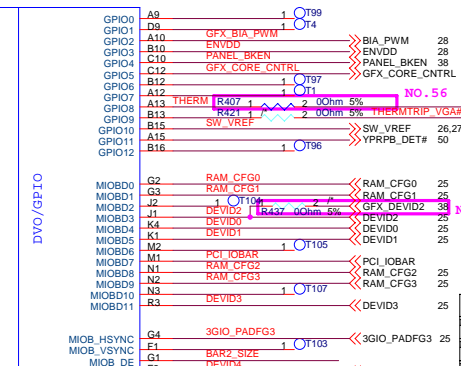
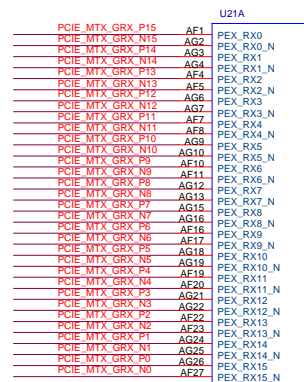
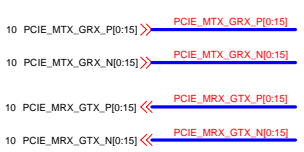
Please these resistor closely DIMMA, all trace length<750 mil.

Please these resistor closely DIMMB, all trace length<750 mil.

<Variant Name>

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHEMATIC FILE NAME:	DESIGN ENGINEER:
	1.2	SHEET 20 OF 69	DDR2 SO-DIMM (1)	<OrgName>	STANLY HSU
				RELEASE DATE:	

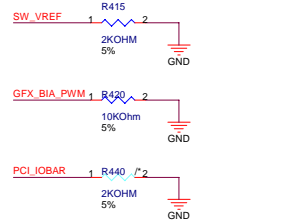




THERMTRIP_VGA# OPTIONS

	G72M	G86
Pop	R421,R405	R407
De-pop	R407	R421,R405

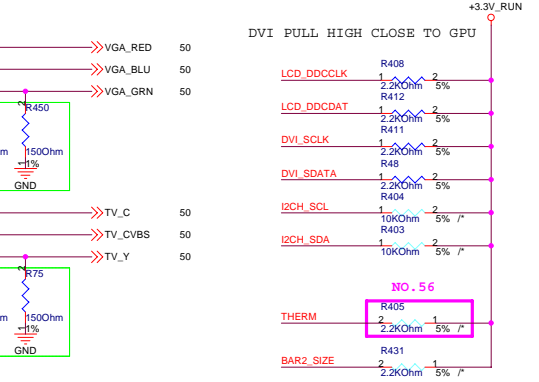
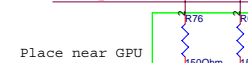
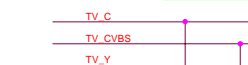
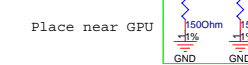
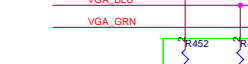
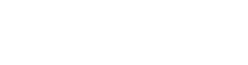
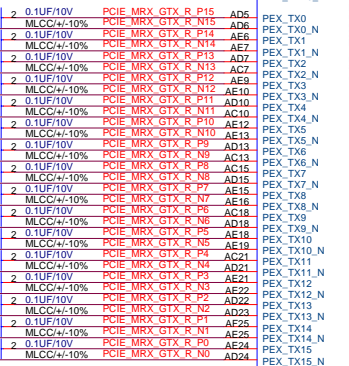
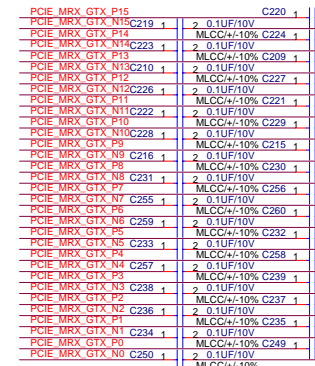
Note: Populate R421 for the platform that use internal G72 Thermal Sensor



	G72M	G8XM	DEFAULT	STRAP
MIOB2	CRYSTALA0	CRYSTAL	0	NOT REQUIRED
MIOB6	CRYSTALA1	TVMODE2	0	NOT REQUIRED
MIOB_HSYNC	-	3GIO_PADFG3	0	NOT REQUIRED
MIOB7	MIOBLE_GPIO	PC_IOBAR	1	NOT REQUIRED
MIOB_DE	-	BAR2_SIZE	0	NOT REQUIRED

G72xx/ G8x

	MIOBD11	MIOBD3	MIOBD5	MIOBD4
	DEVID3	DEVID2	DEVID1	DEVID0
G72GLM	1	1	0	0
G72M	1	0	0	0
G72MV	0	1	1	1
G86M	0	1	1	1

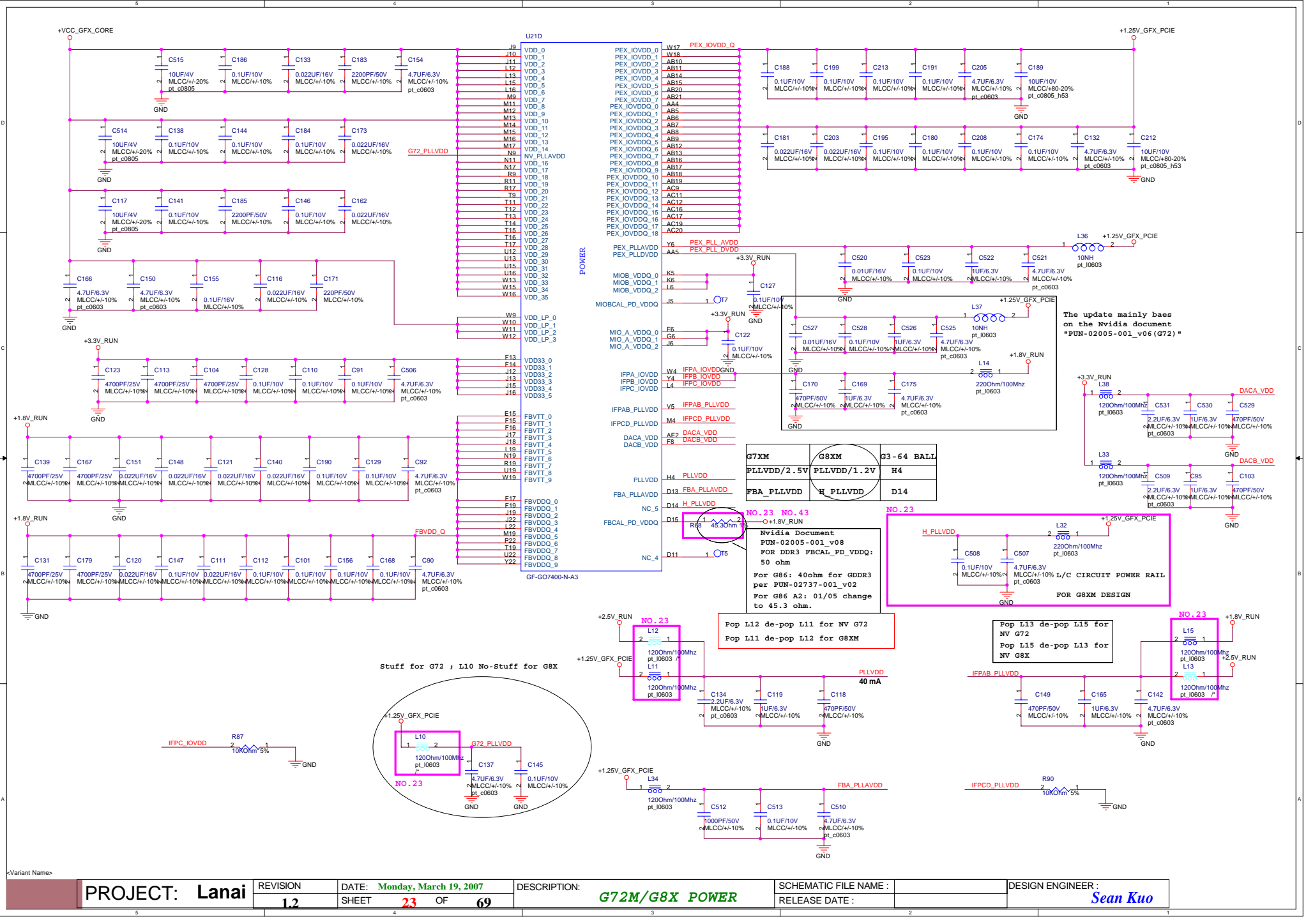


POPULATION OPTIONS

	CY28547+SS	CY28547+U5	CY28547 wo/SS
Pop	R414, R419, R98	R423, R417, U5	R416, R419
De-pop	U5, R423, R417, R416	R414, R416, R419, R98	U5, R98, R414, R417, R423

'U5' indicate all ockt.related to U5 in Page.25

Layout comments: Place R423,R419 as close as possible to C3. . Place R414,R416and R417 as close as possible to pin C1.



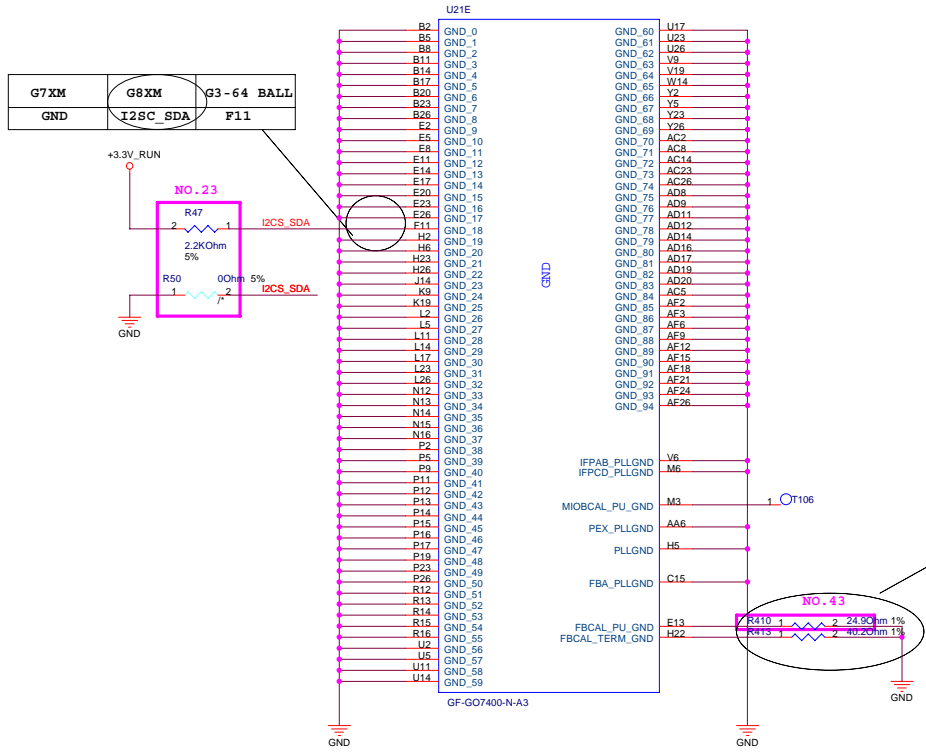
The update mainly bases on the Nvidia document "PUN-02005-001_v06 (G72) "

Nvidia Document
PUN-02005-001_v08
FOR DDR3 FBICAL_PD_VDDQ:
50 ohm
For G86: 40ohm for GDDR3
per PUN-02737-001_v02
For G86 A2: 01/05 change to 45.3 ohm.

Pop L12 de-pop L11 for NV G72
Pop L11 de-pop L12 for G8XM

Pop L13 de-pop L15 for NV G72
Pop L15 de-pop L13 for NV G8X

Stuff for G72 ; L10 No-Stuff for G8X



UPDATE FROM NVIDIA UPDATED NOTIFICATION
 PUN-02005-001_v08 (G72)
 FBCAL_PU_GND: 30 OHM
 FBCAL_TERM_GND: 40 OHM
 01/05 for G86 A2: change R410 to 24.9
 ohm from 30 ohm

<Variant Name>

PROJECT: Lanai

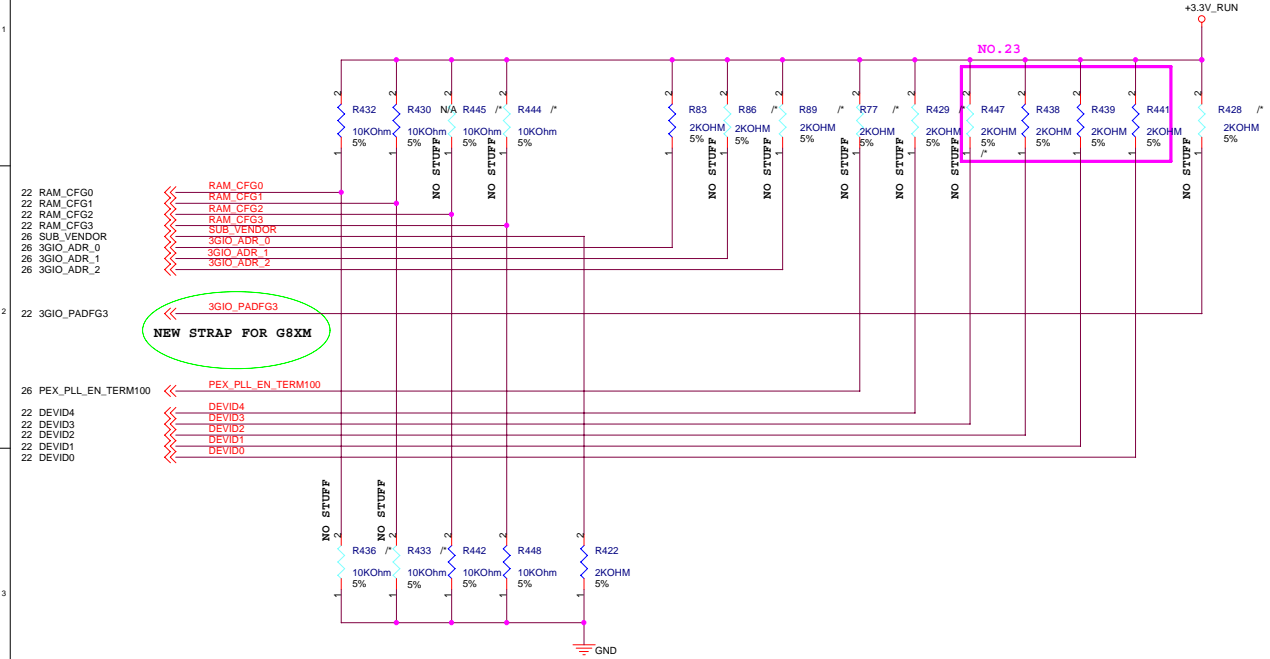
REVISION
 1.2

DATE: Monday, March 19, 2007
 SHEET 24 OF 69

DESCRIPTION:
 G7XM/G8X CORE GND

SCHEMATIC FILE NAME : <OrgName>
 RELEASE DATE :

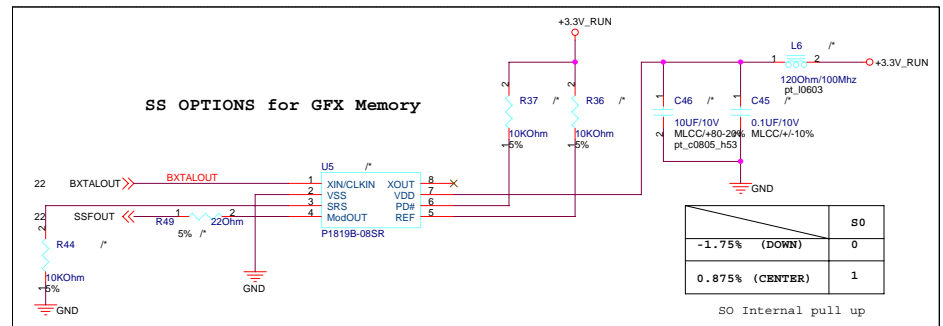
DESIGN ENGINEER :
 Sean Kuo



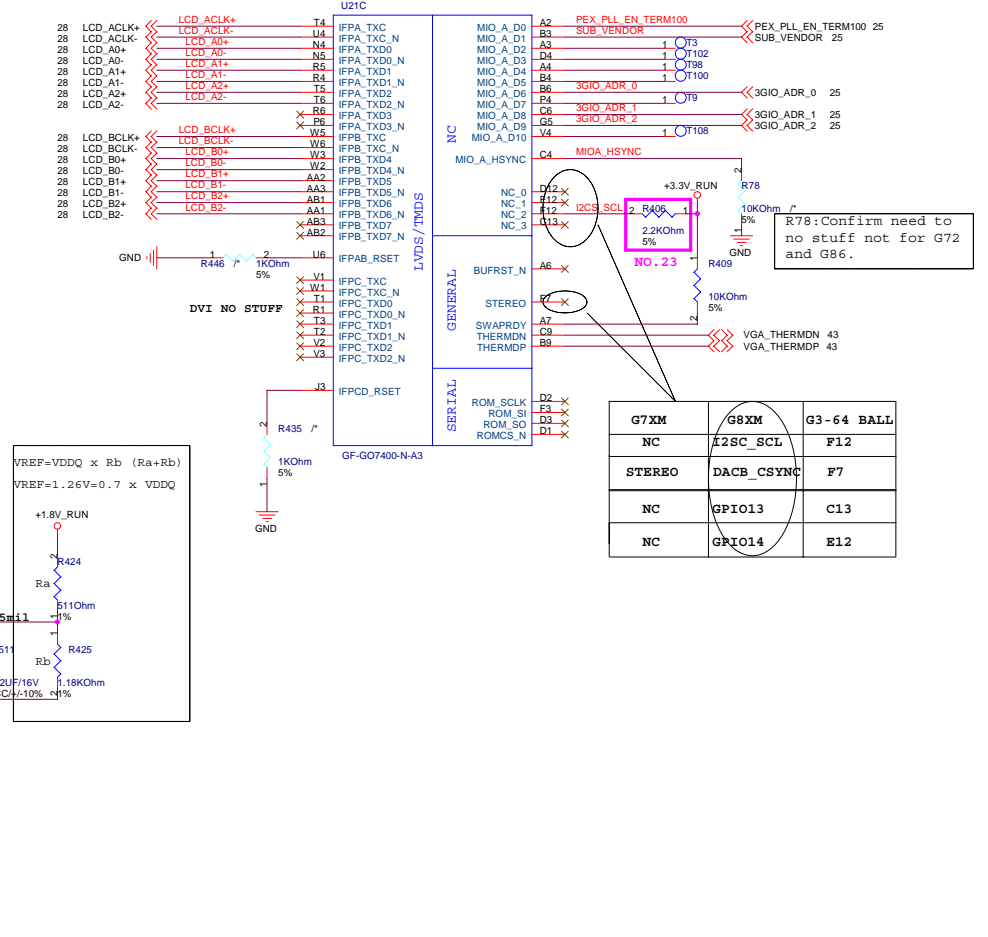
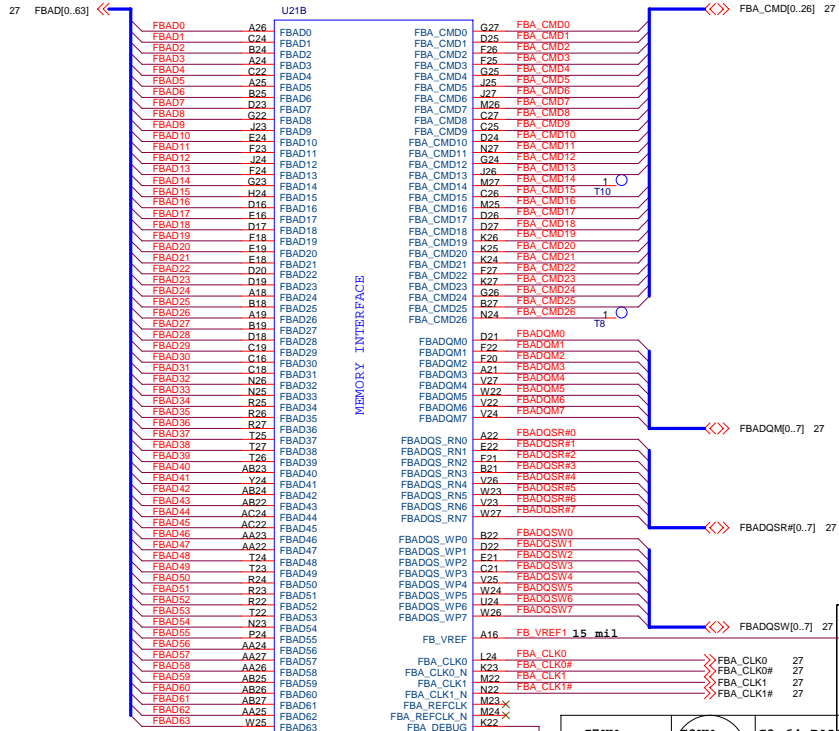
STRAPS	PIN	DESCRIPTION	Value
ROM_TYPE[1:0]	MIOBD10 MIOB_VSYNC	Parallel=00, SERIAL AT25F=01 DEFAULT,Serial SST45VF=10, LPC=11	01
SUB_VENDOR	MIOAD1		0
PEX_PLL_TERM	MIOAD0		0
RAM_CFG[3:0]	FOR GDDR1	8Mx32 DDR monolithic (32bit) 300MHz, 1.8V	1001
		4Mx32 DDR generic (64bit) 1.8V I/O	0100
		4Mx32 DDR generic (32bit) 1.8V I/O	1100
		Infineon 8Mx32 500MHz, 1.8V	0101
	FOR GDDR3	Hynix 8Mx32 500MHz, 1.8V	0111
		Samsung 8Mx32 500MHz, 1.8V	0110
		Infineon 16Mx32 GDDR3 ,1.8V	0001
		Hynix 16Mx32 GDDR3 1.8V	0010
		Samsung 16Mx32 GDDR3 1.8V	0011

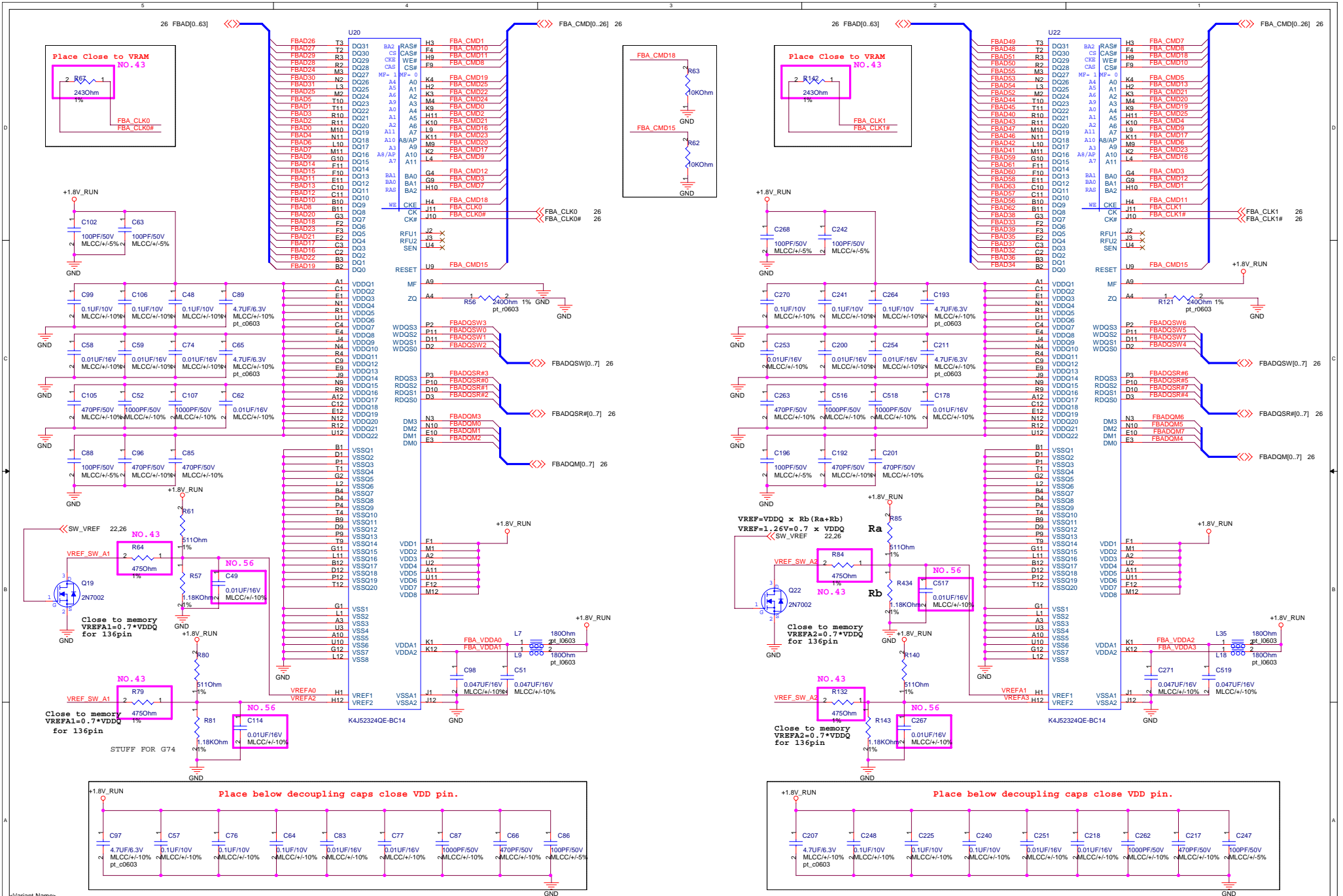
Internal Pull-down
MIOAD0, MIOAD6,
MIOAD8, MIOAD9

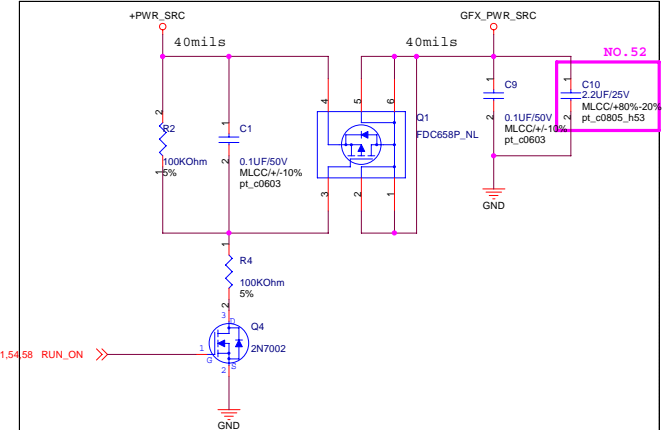
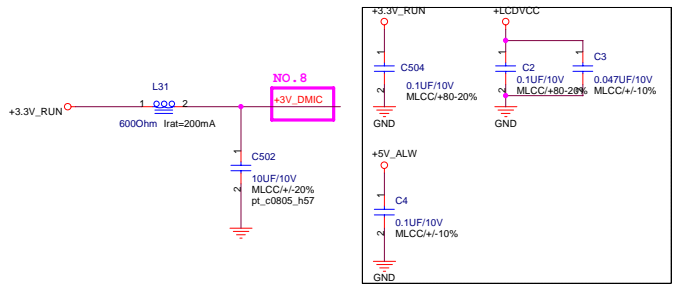
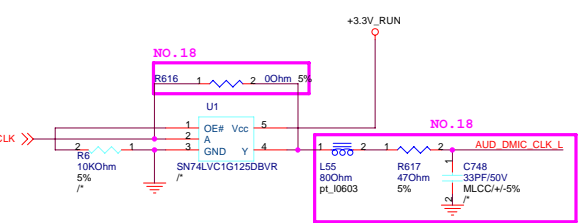
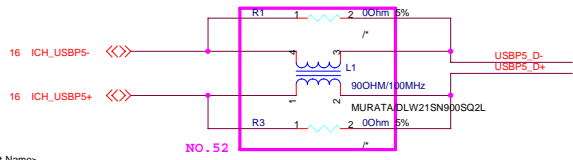
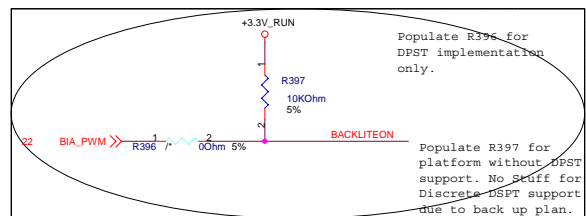
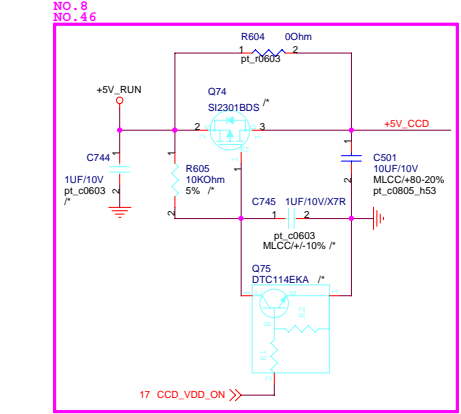
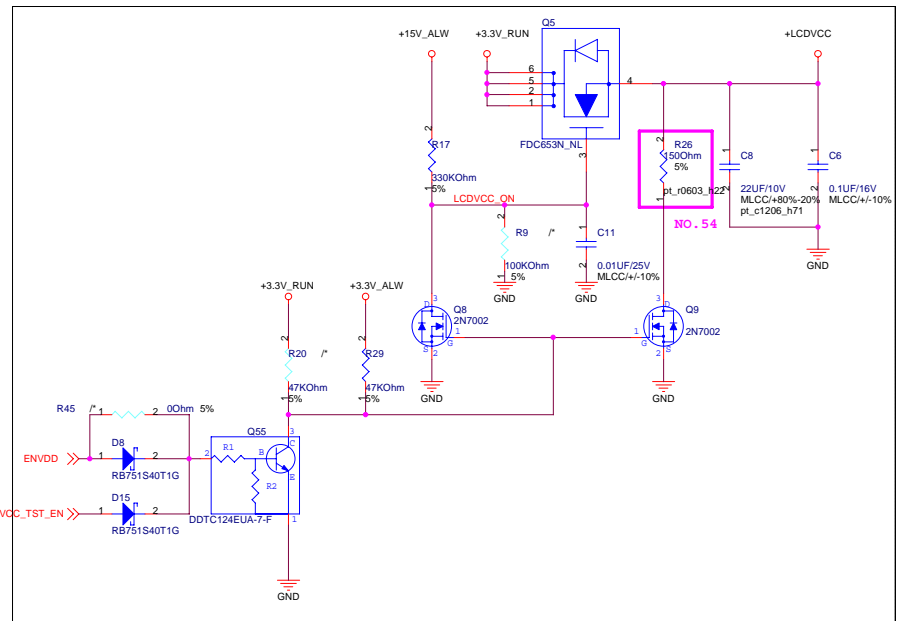
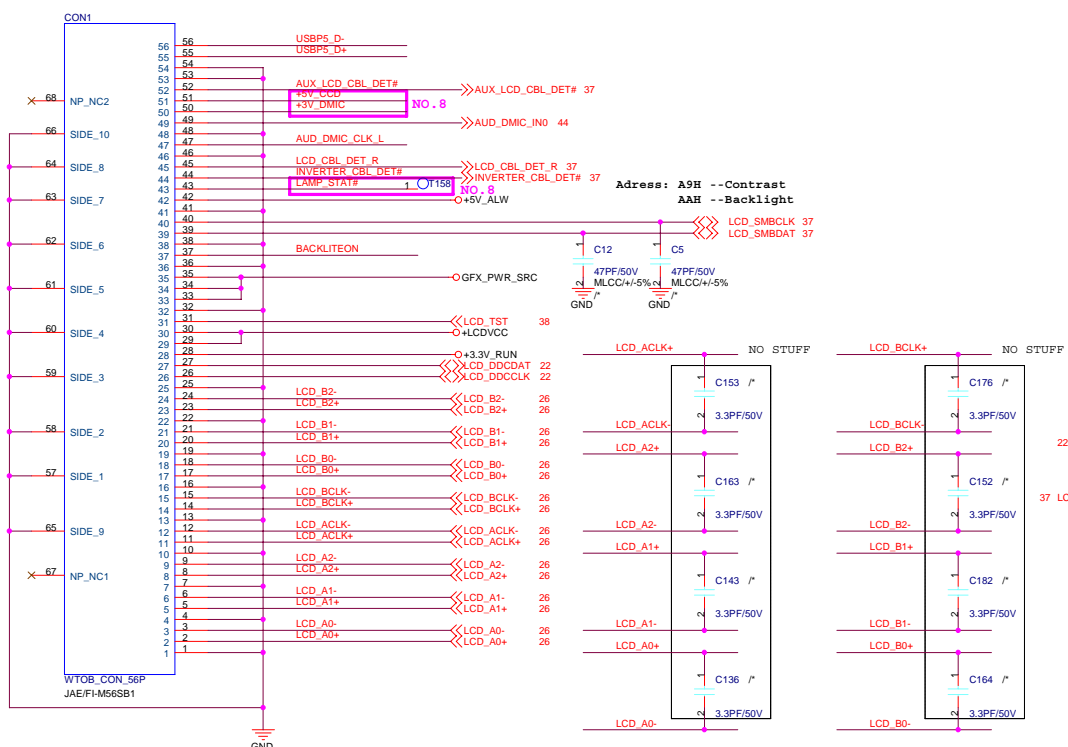
MIOAD1---SUB_VENDOR 0, SYSTEM BIOS MIOBD4----PCI_DEVID0 1000,G72M
MIOAD0---PEX_PLL_EN_TERM MIOBD5----PCI_DEVID1 0111,G72MV
MIOAD6---3GIO_ADR_0 [2:0] 001 for NV43/NV44 MIOBD3----PCI_DEVID2
MIOAD8---3GIO_ADR_1 010 for G7x, NV42 MIOBD11---PCI_DEVID3
MIOAD9---3GIO_ADR_2



M08 HAS REMOVED THIS PORTION
INSTALL OR NOT?







V_DMIC IS DEPENDENT ON MIC SELECTION (1.8V - 3.3V TYP)
Verify to ensure operability with chosen mic supplier.

Note1: If only 1 digital mic, use AUD_DMIC_IN0.

Note2: If using 2 dig mics, also use AUD_DMIC_IN0.
This input supports 2 digmics. AUD_DMIC_IN1 is only used to support 4 dig mics.

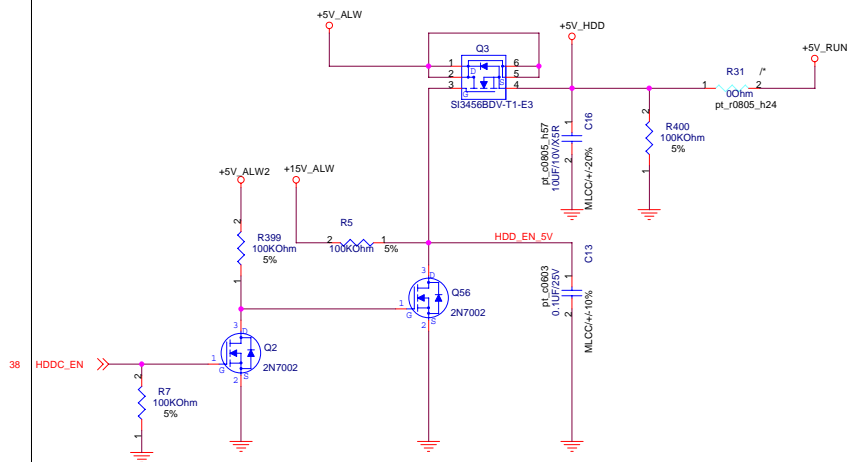
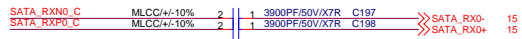
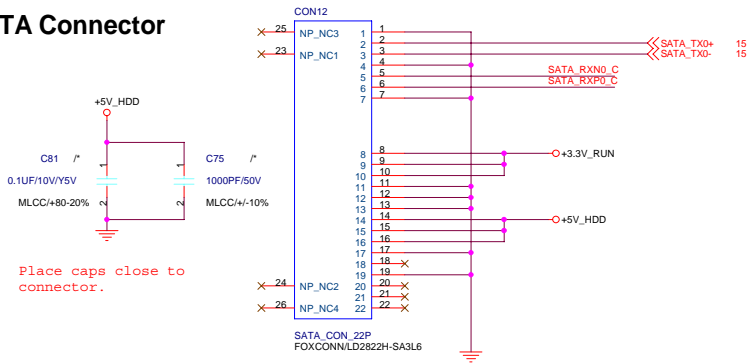


<Variant Name> PROJECT: Lanai	REVISION 12	DATE: <i>Monday, March 19, 2007</i> SHEET 29 OF 69	DESCRIPTION: VGA CRT CON	SCHEMATIC FILE NAME : RELEASE DATE :	DESIGN ENGINEER : <i>Sean Kuo</i>
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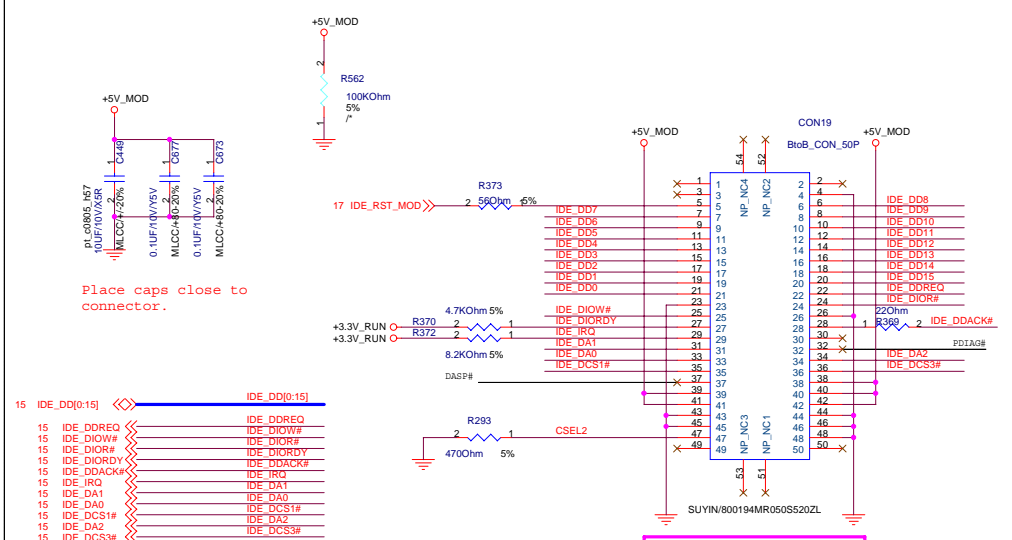


<Variant Name> PROJECT: Lanai	REVISION 12	DATE: <i>Monday, March 19, 2007</i> SHEET 30 OF 69	DESCRIPTION: <i>TV OUT CON</i>	SCHEMATIC FILE NAME : RELEASE DATE :	DESIGN ENGINEER : <i>Sean Kuo</i>
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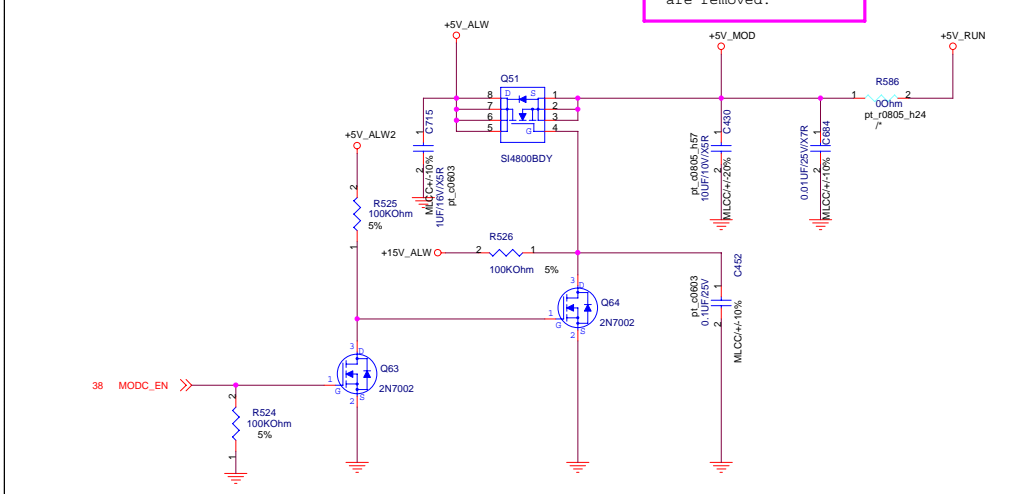
SATA Connector

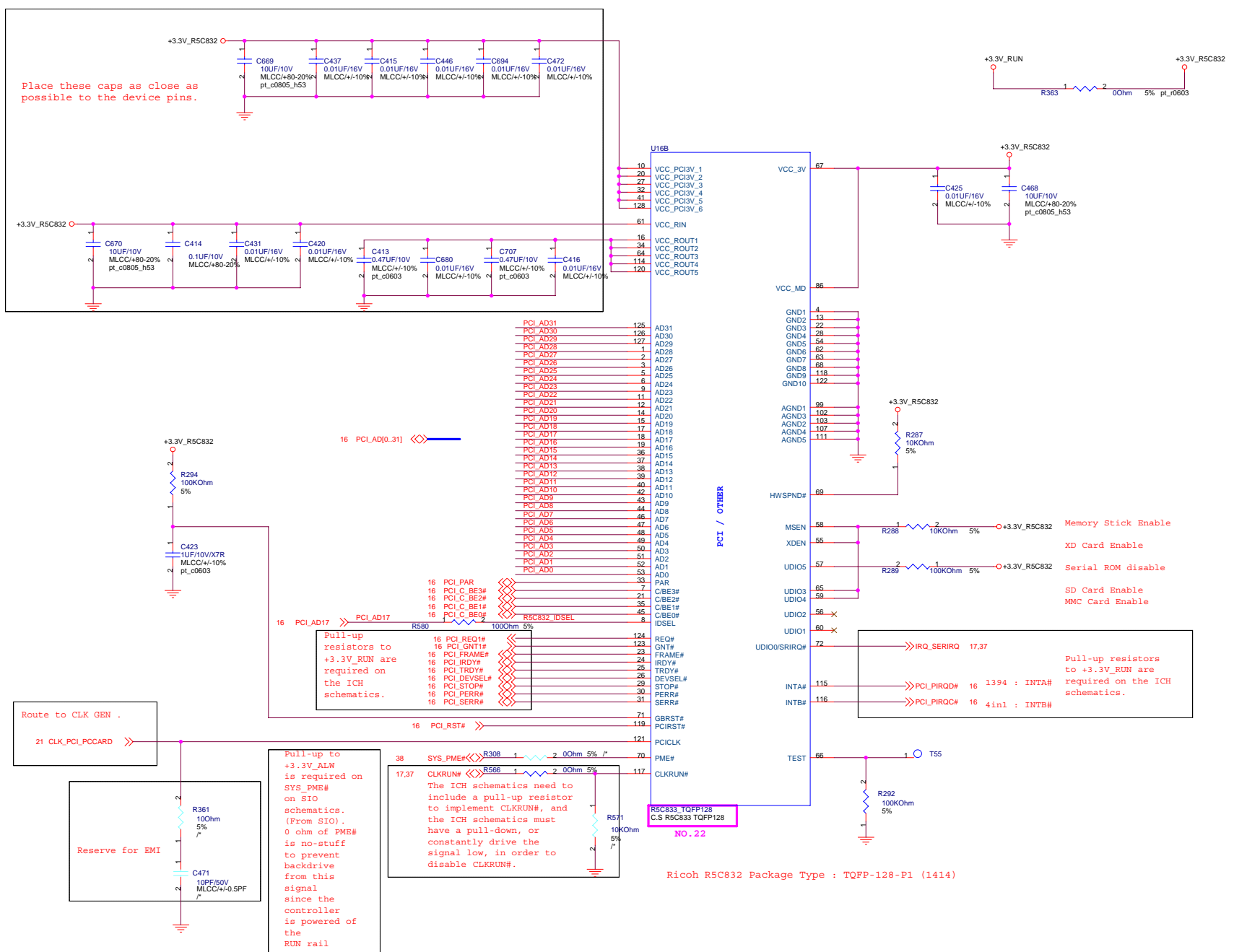


ODD Connector



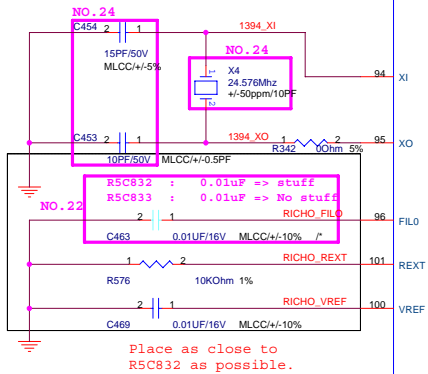
MODPRES# and USB_IDE# are removed.



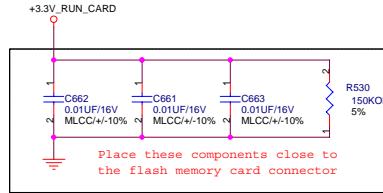


Recommended Crystal Specs from Data Sheet:

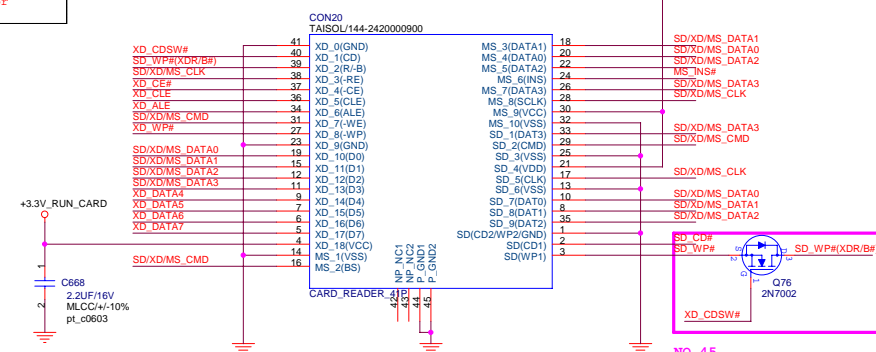
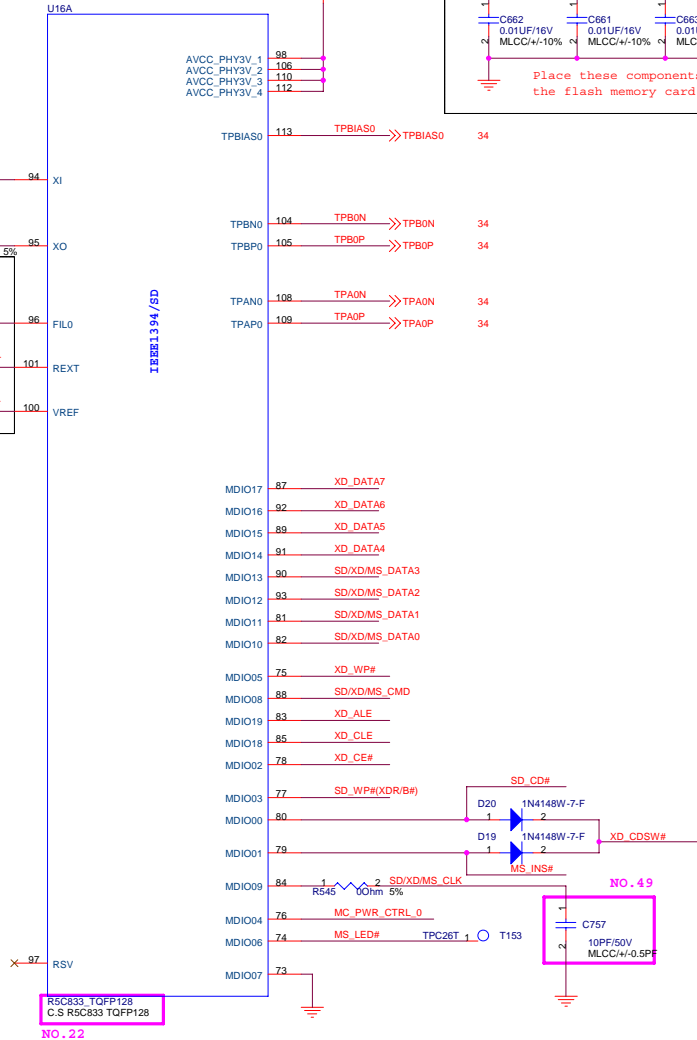
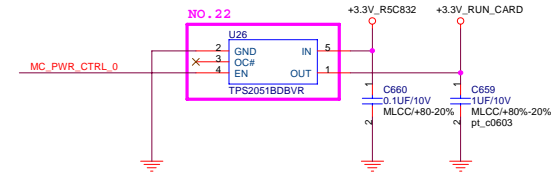
Normal Frequency : 24.576 Mhz
 Frequency Tolerance : +/- 50ppm @ 25C
 Driver Level : .1 mW
 Load capacitance : 10pF
 Equ. Resistance : 50 Ohm Max
 Shunt Capacitance : 7.0pF Max



Place as close to R5C832 as possible.

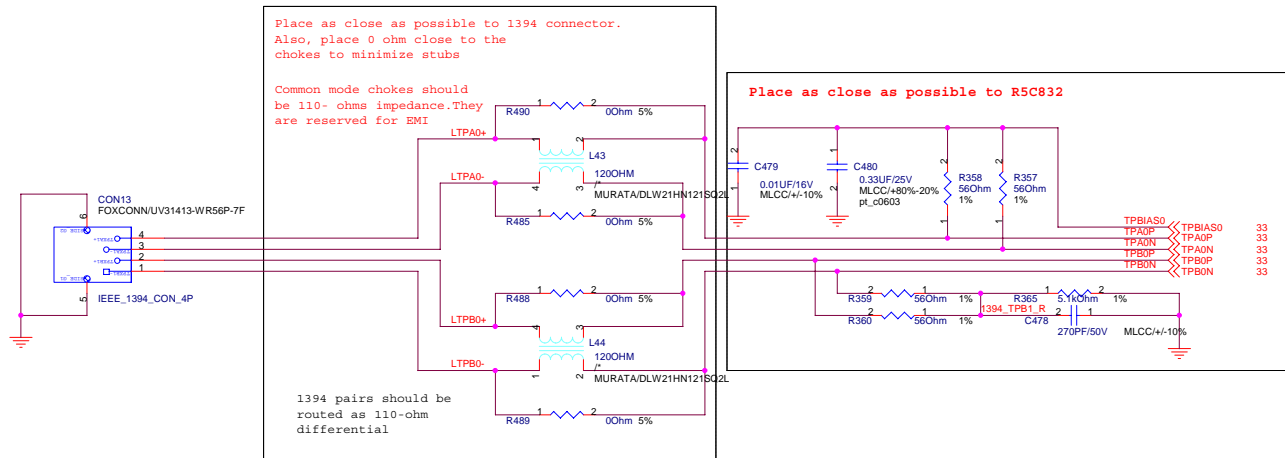
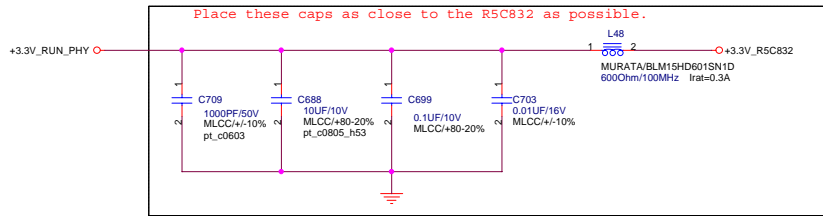


For SD/MS Card Power



<Variant Name>

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHEMATIC FILE NAME:	<OrgName>	DESIGN ENGINEER:
	1.2	SHEET 33 OF 69	R5C833 - FLASH MEMORY PART	RELEASE DATE:		Terry Lin



<Variant Name>

PROJECT: Lanai

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1.2

DATE: Monday, March 19, 2007
SHEET 34 OF 69

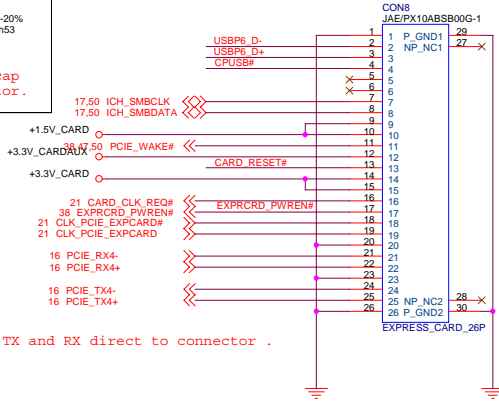
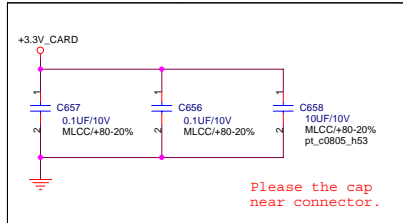
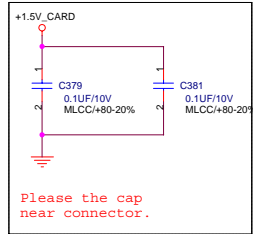
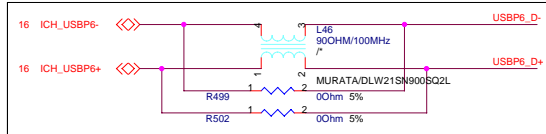
DESCRIPTION:
R5C833 - IEEE1394 PART

SCHEMATIC FILE NAME :
RELEASE DATE :

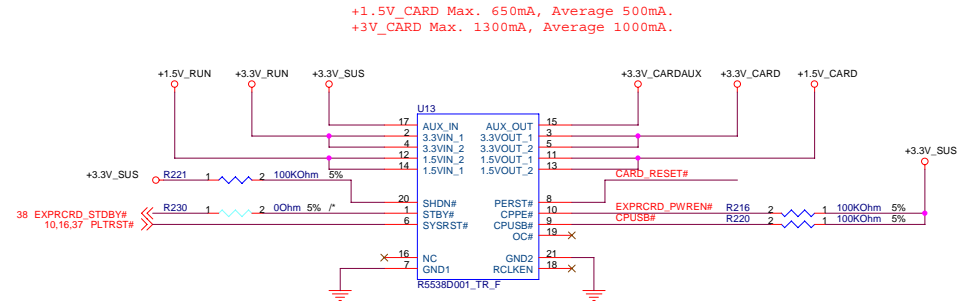
<OrgName>

DESIGN ENGINEER :
Terry Lin

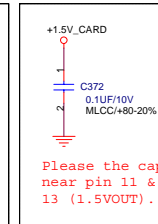
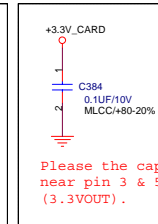
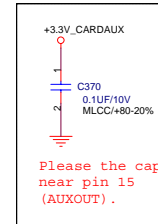
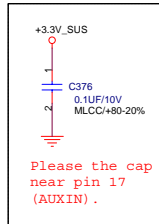
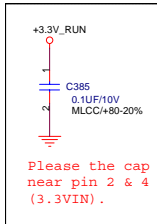
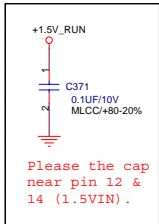
Express Card



PCI-Express TX and RX direct to connector .



+1.5V_CARD Max. 650mA, Average 500mA.
+3V_CARD Max. 1300mA, Average 1000mA.



<Variant Name>

PROJECT: Lanai

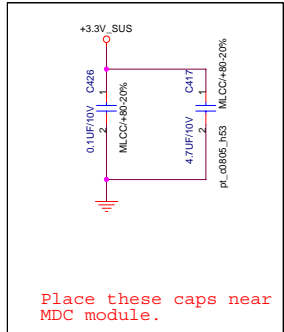
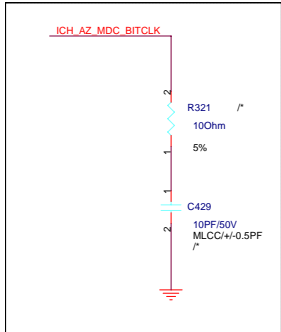
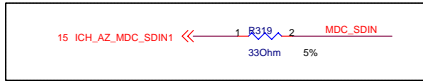
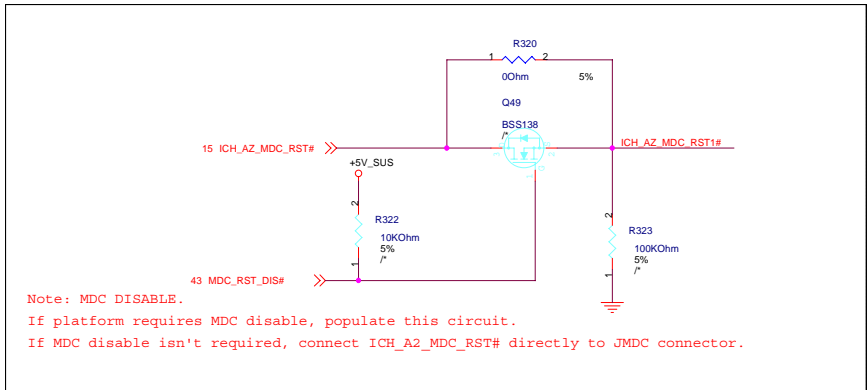
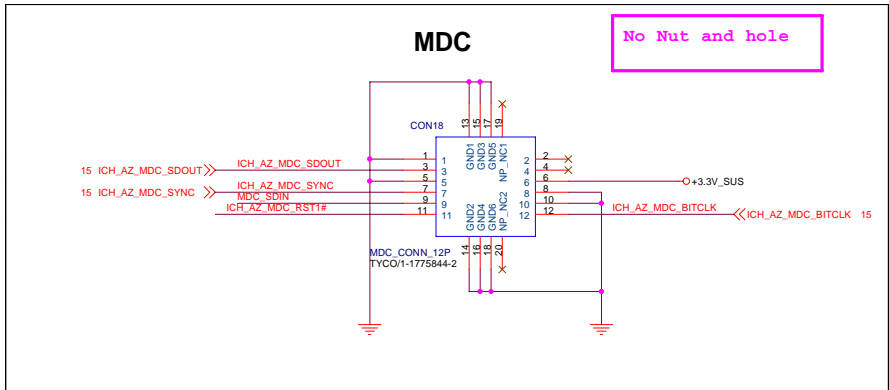
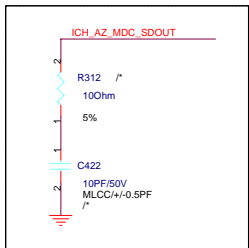
REVISION
1.2

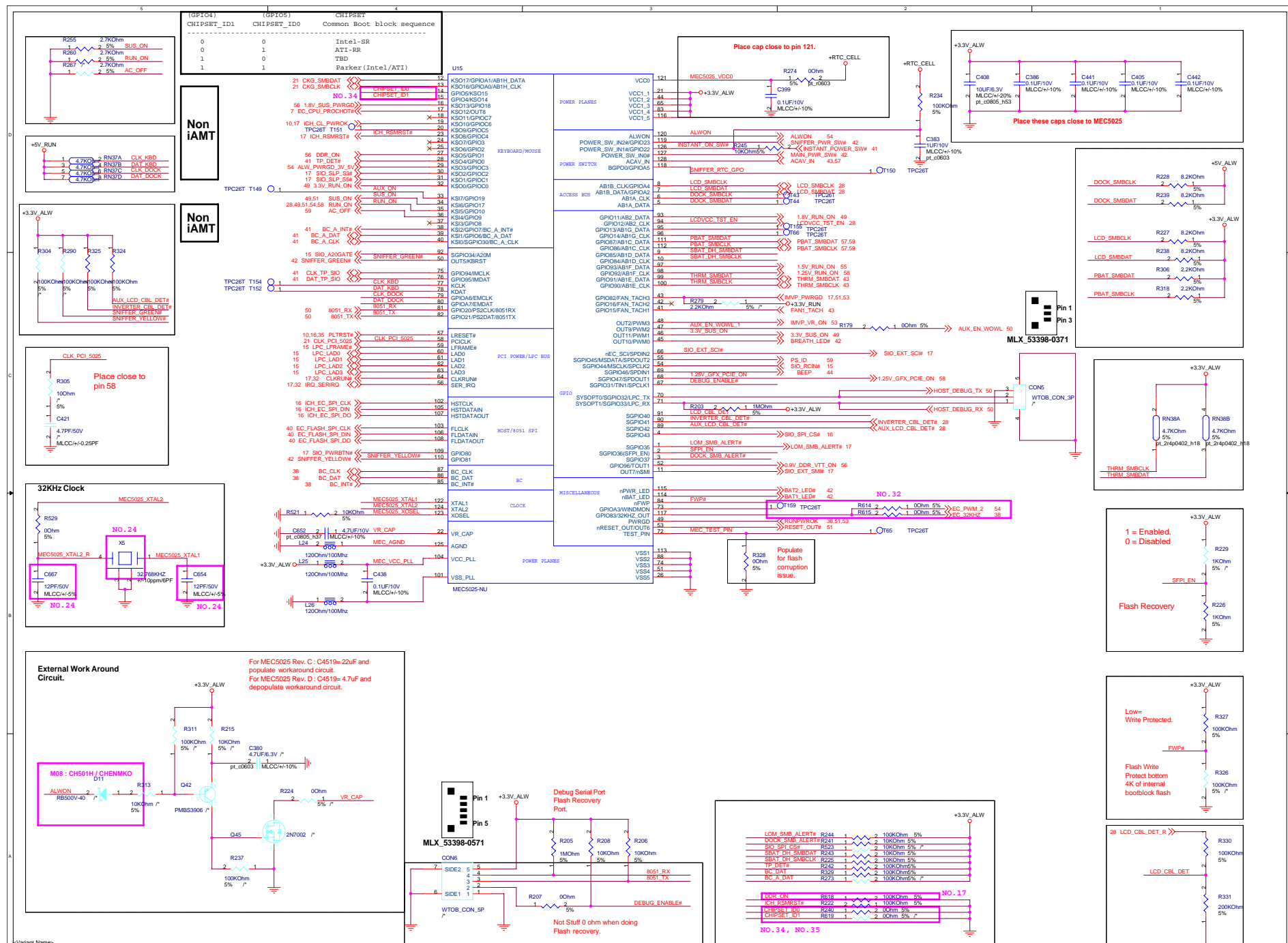
DATE: **Monday, March 19, 2007**
SHEET **35** OF **69**

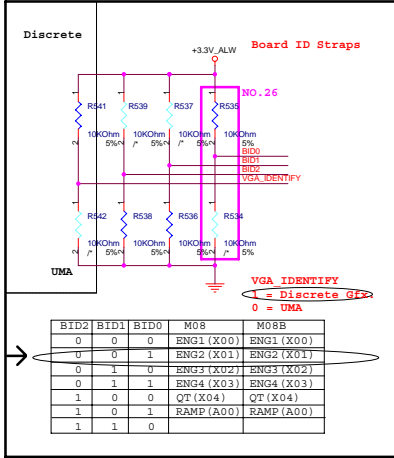
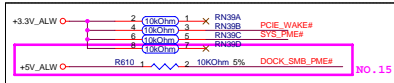
DESCRIPTION:
PCI-Express Card

SCHEMATIC FILE NAME : **<OrgName>**
RELEASE DATE :

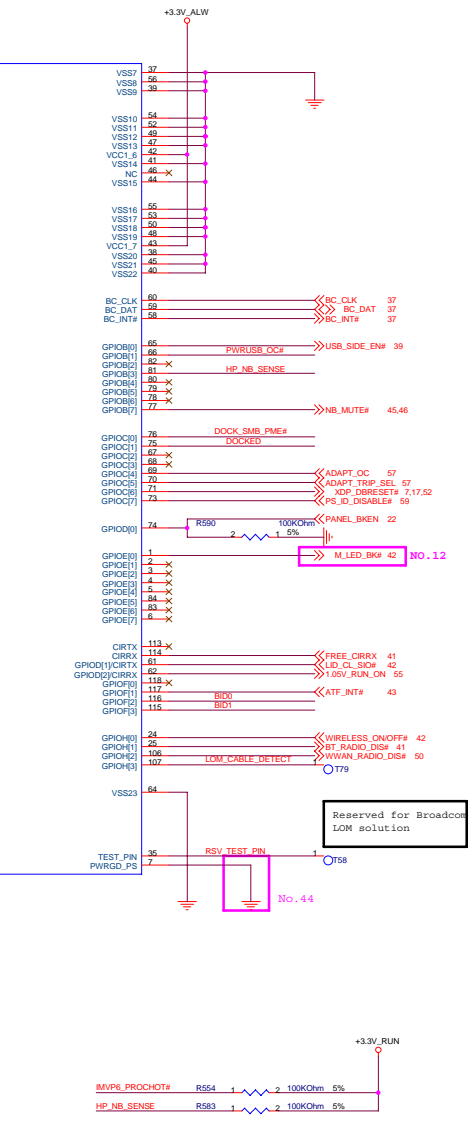
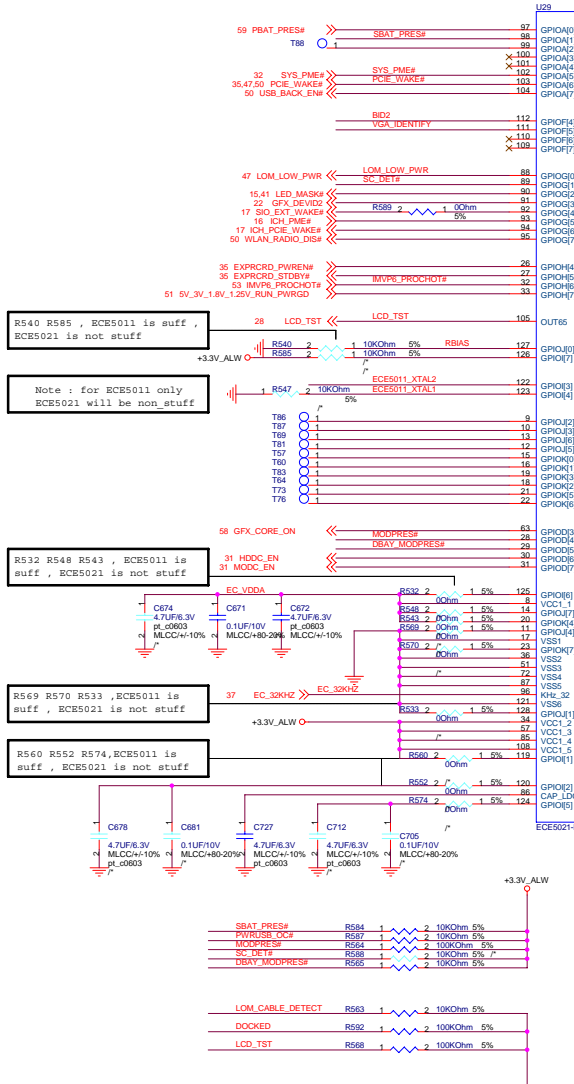
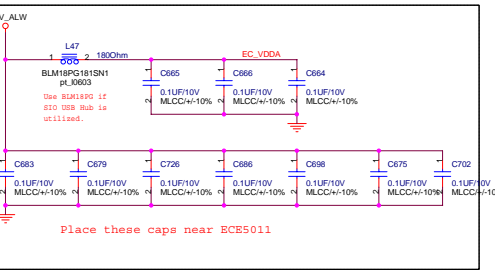
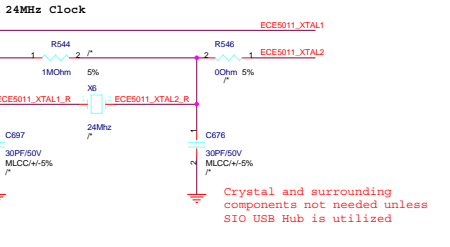
DESIGN ENGINEER :
Terry Lin

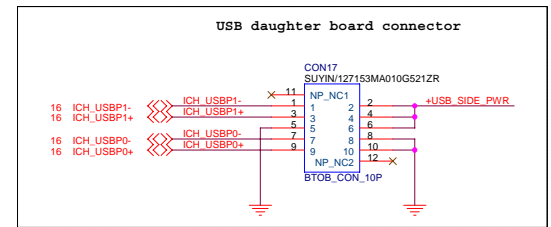
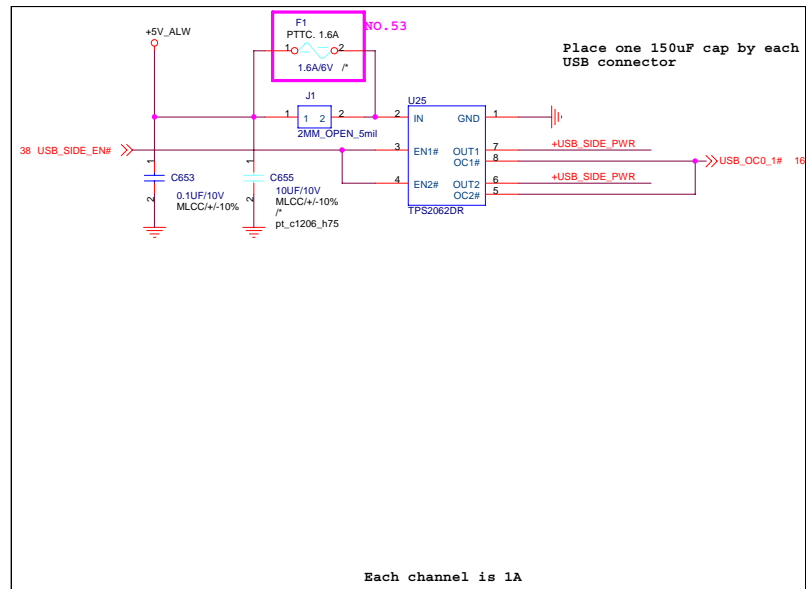






BID2	BID1	BID0	M08	M08B
0	0	0	ENG1 (X00)	ENG1 (X00)
0	0	1	ENG2 (X01)	ENG2 (X01)
0	1	0	ENG3 (X02)	ENG3 (X02)
0	1	1	ENG4 (X03)	ENG4 (X03)
1	0	0	QT (X04)	QT (X04)
1	0	1	RAMP (A00)	RAMP (A00)
1	1	0		

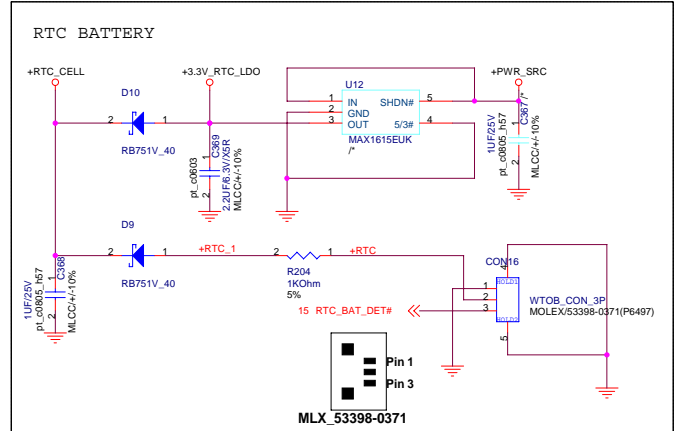
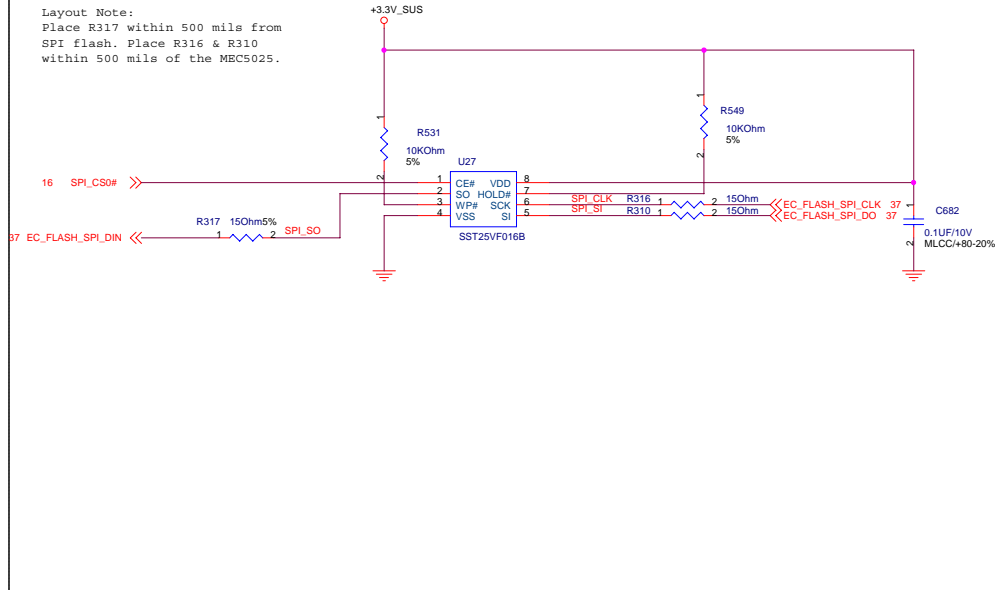




<Variant Name>

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHMATIC FILE NAME :	<OrgName>	DESIGN ENGINEER :
	1.2	SHEET 39 OF 69	USB PORT x 2	RELEASE DATE :		Terry Lin

Layout Note:
Place R317 within 500 mils from
SPI flash. Place R316 & R310
within 500 mils of the MEC5025.



<Variant Name>

PROJECT: Lanai

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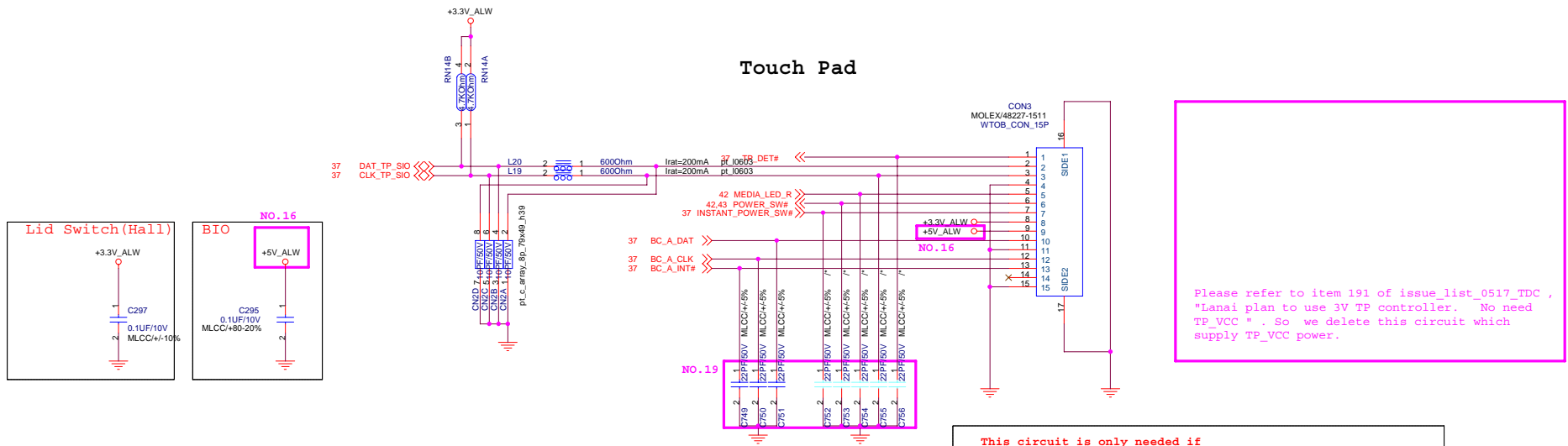
DESCRIPTION: FLASH & RTC

SCHEMATIC FILE NAME :
RELEASE DATE :

<OrgName>

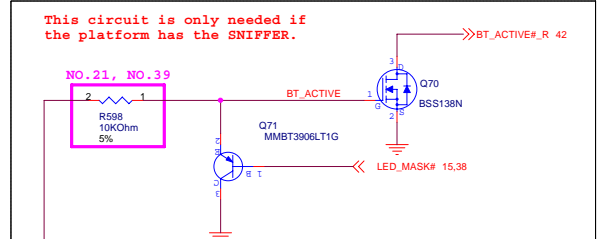
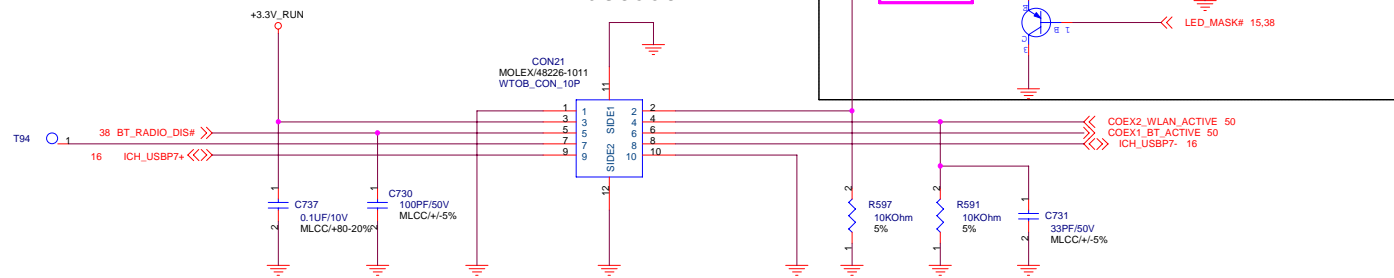
DESIGN ENGINEER :
C.L. Ho

Touch Pad

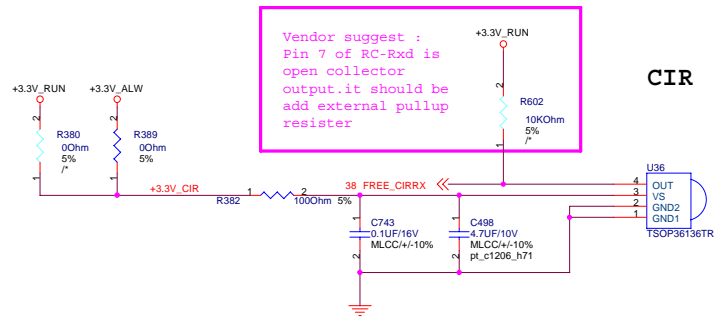


Please refer to item 191 of issue_list_0517_TDC , "Lanai plan to use 3V TP controller. No need TP_VCC ". So we delete this circuit which supply TP_VCC power.

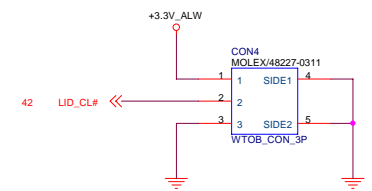
Bluetooth



CIR



HALL SENSOR



<Variant Name>

PROJECT: Lanai

REVISION
1.2

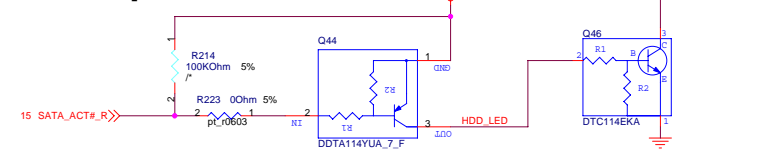
DATE: **Monday, March 19, 2007**
SHEET **41** OF **69**

DESCRIPTION:
TOUCH PAD & BT & CIR & LID

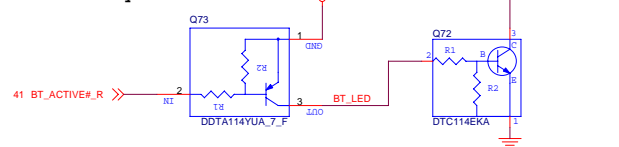
SCHEMATIC FILE NAME : **<OrgName>**
RELEASE DATE :

DESIGN ENGINEER :
Terry Lin

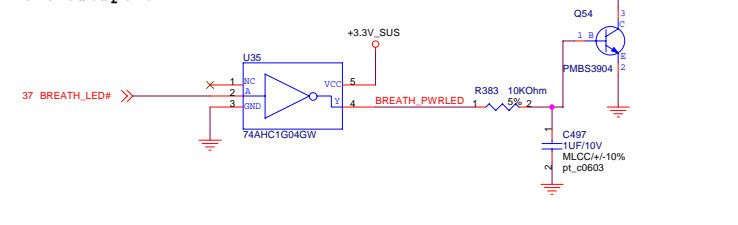
HDD activity LED



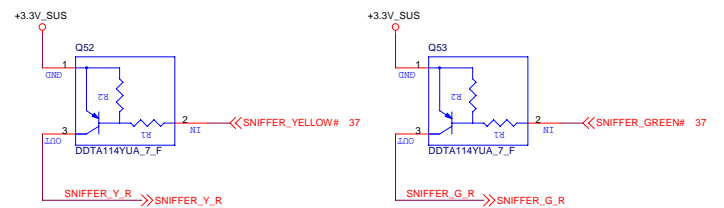
BT activity LED



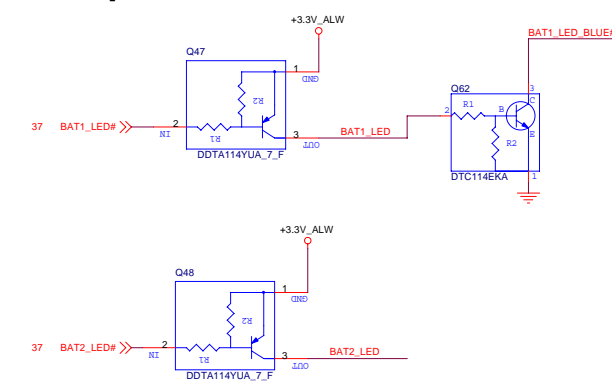
Power&Suspend



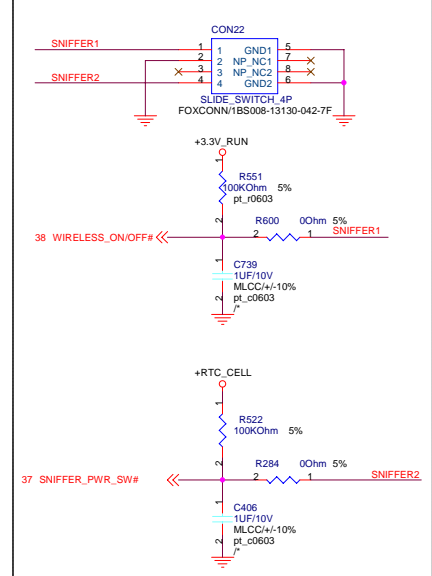
Sniffer LED driver circuit



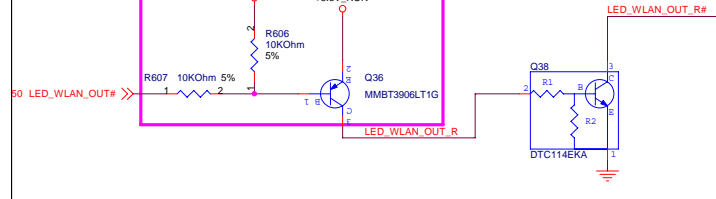
Battery status



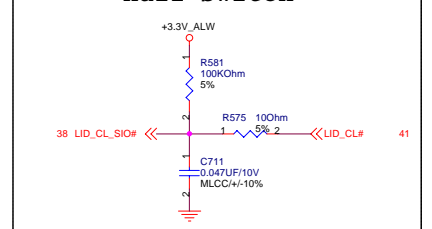
Sniffer Switch



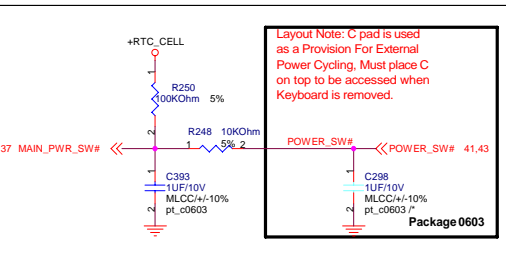
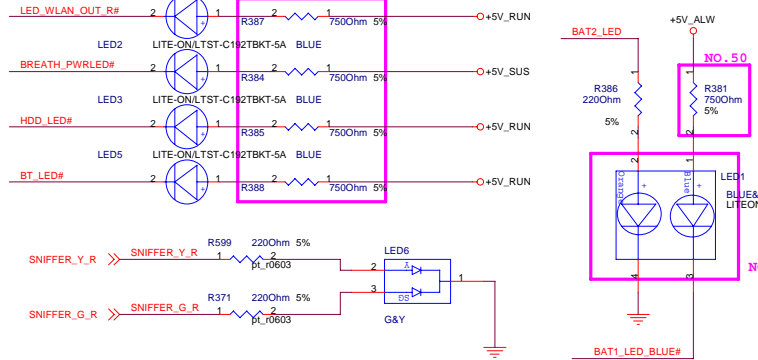
WLAN



Hall Switch

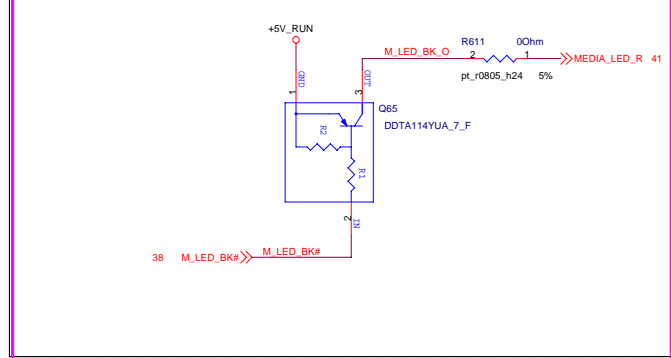


LED4 LITE-ON/LTST-C192TBKT-5A BLUE NO. 50



NO.12 NO.33

Media Bottom Board LED drive circuit



<Variant Name>

PROJECT: Lanai

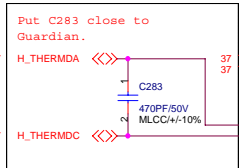
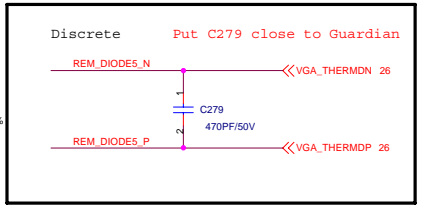
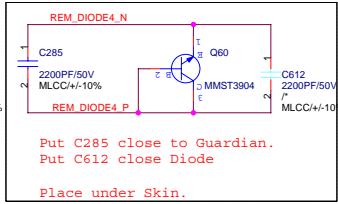
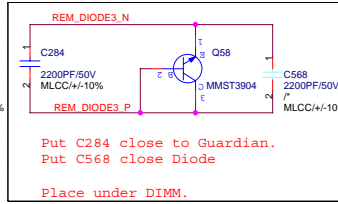
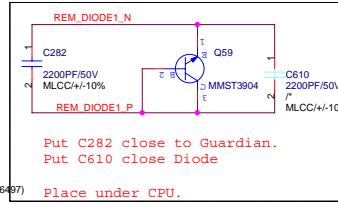
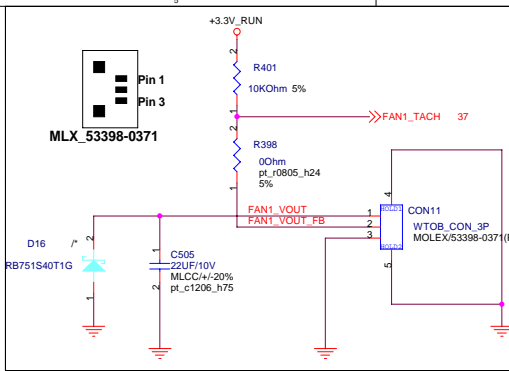
REVISION 1.2

DATE: Monday, March 19, 2007
SHEET 42 OF 69

DESCRIPTION: SWITCH & LED

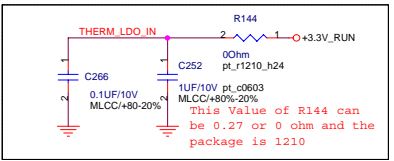
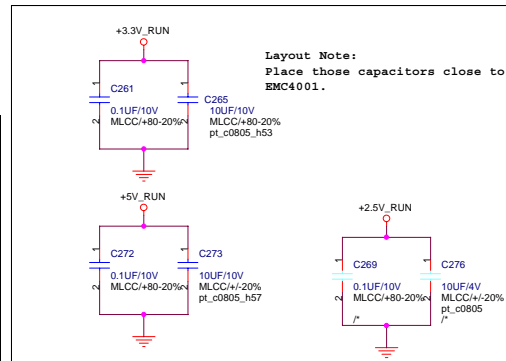
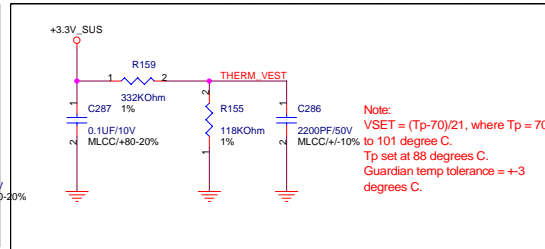
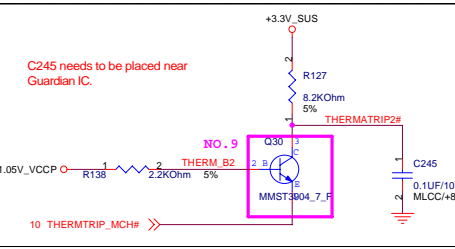
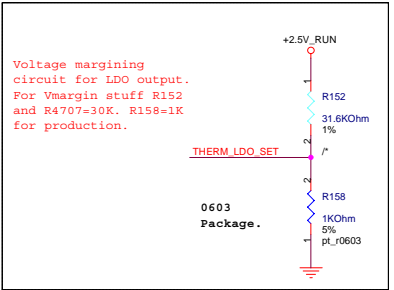
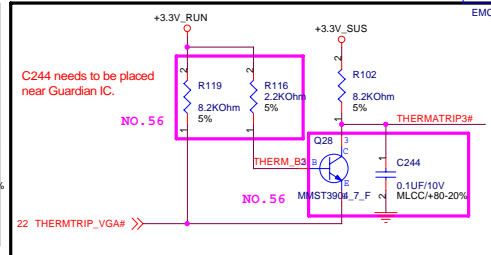
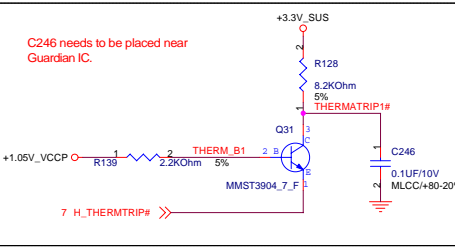
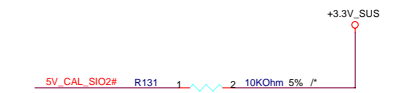
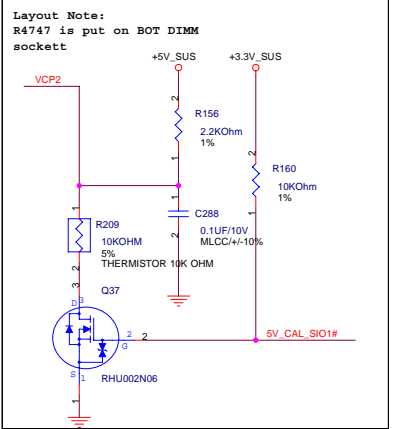
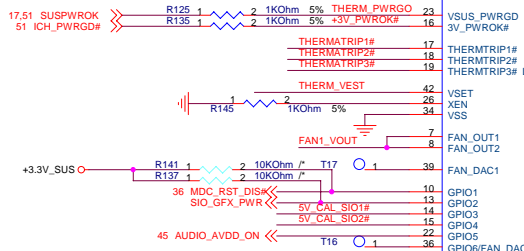
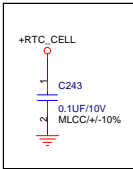
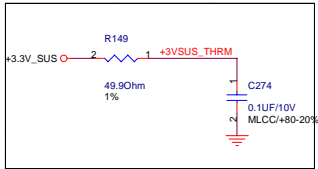
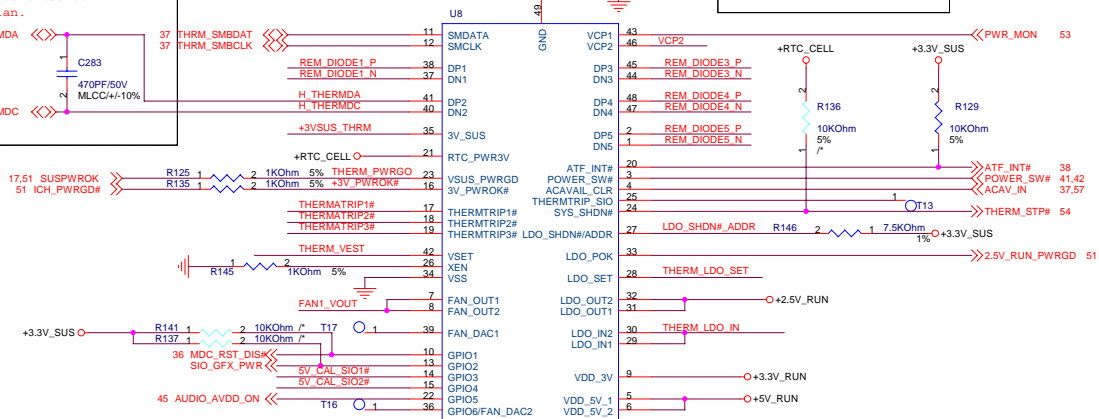
SCHEMATIC FILE NAME: <OrgName>
RELEASE DATE:

DESIGN ENGINEER: Ivan Chou



Guardian

Note: 150K input impedance on VCP1 (Pin 43)



*Variant Name:

PROJECT: Lanai

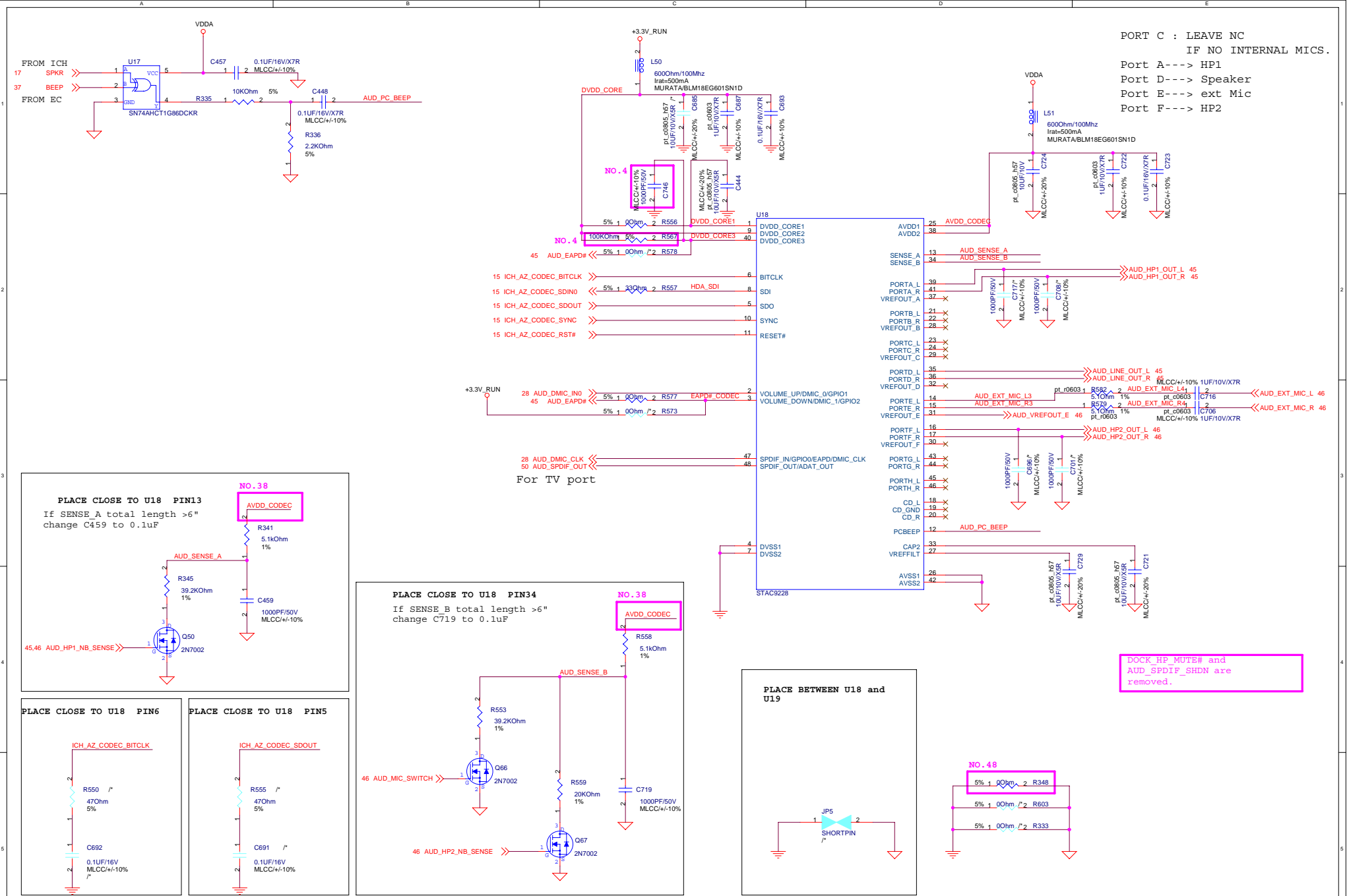
REVISION: 1.2

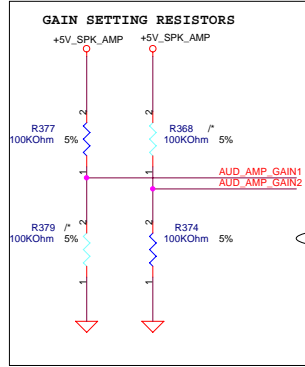
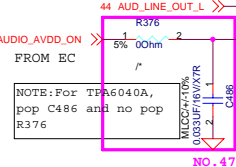
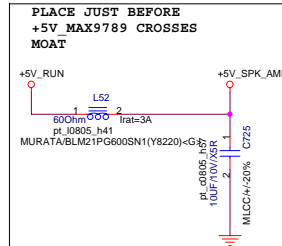
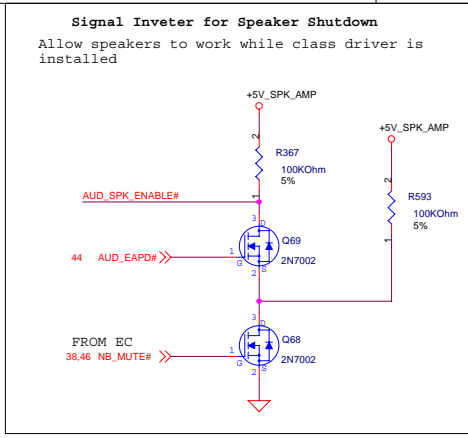
DATE: Monday, March 19, 2007

DESCRIPTION: EMC4001

SHEET: 43 OF 69

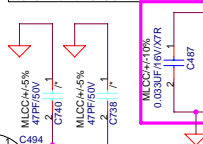
DESIGN ENGINEER: STANLY HSU





Gain1	Gain2	Gain
0	0	6 dB
0	1	10 dB
1	0	15.6 dB
1	1	21.6 dB

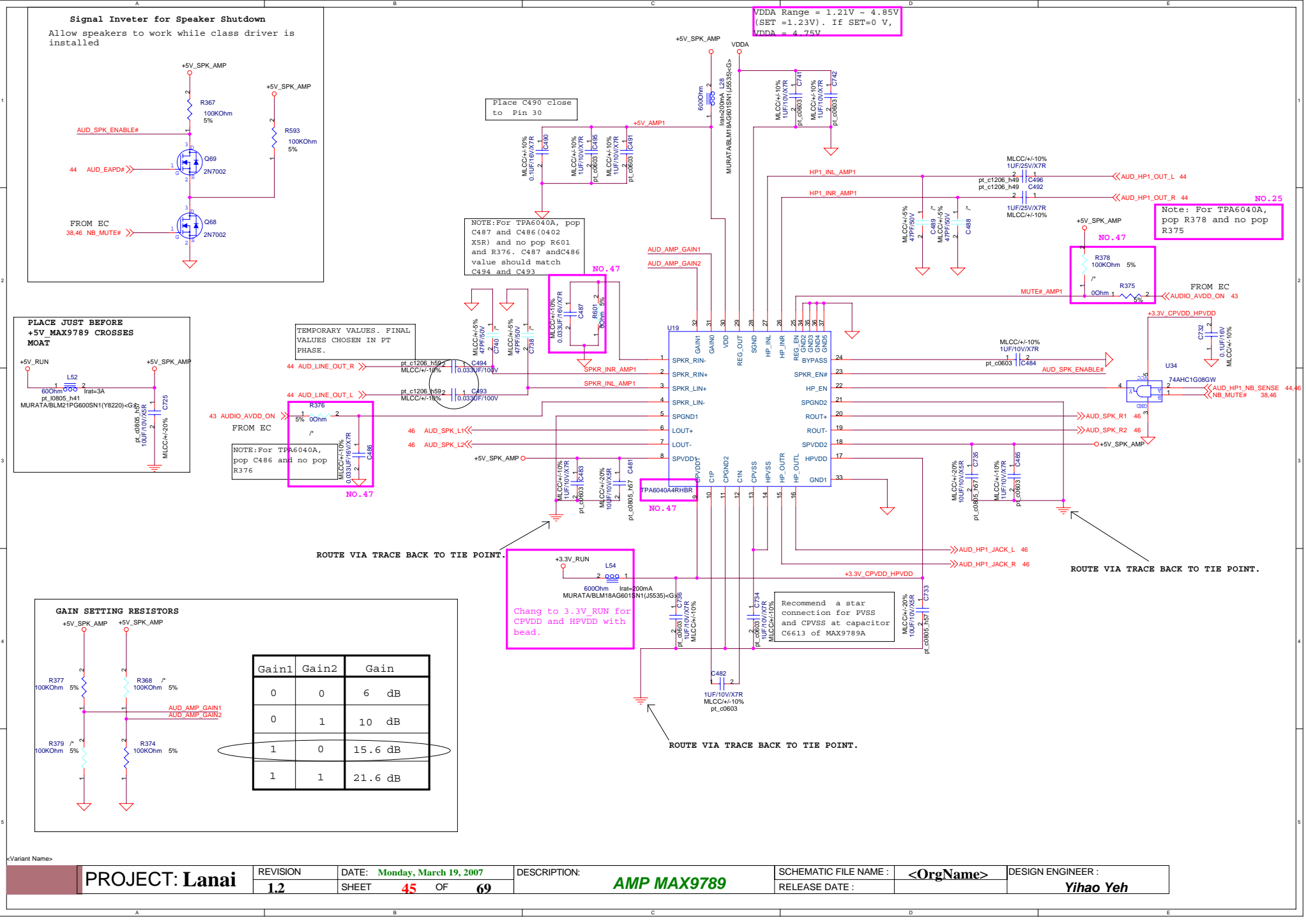
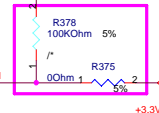
NOTE: For TPA6040A, pop C487 and C486 (0402 X5R) and no pop R601 and R376. C487 and C486 value should match C494 and C493

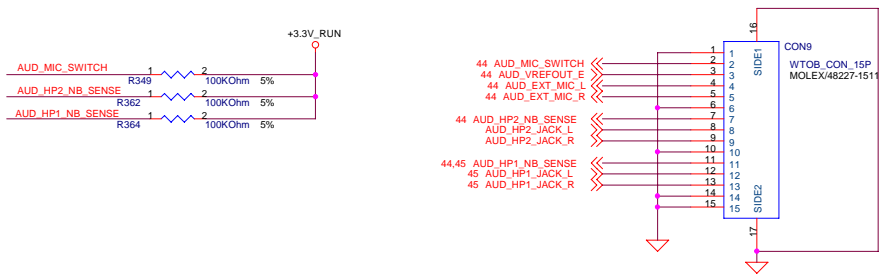
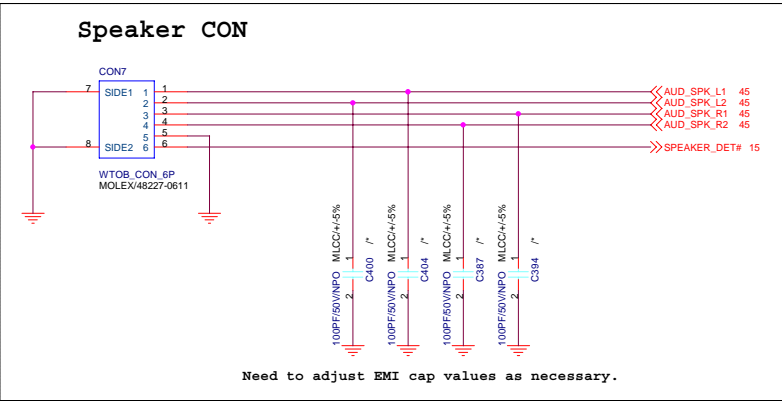
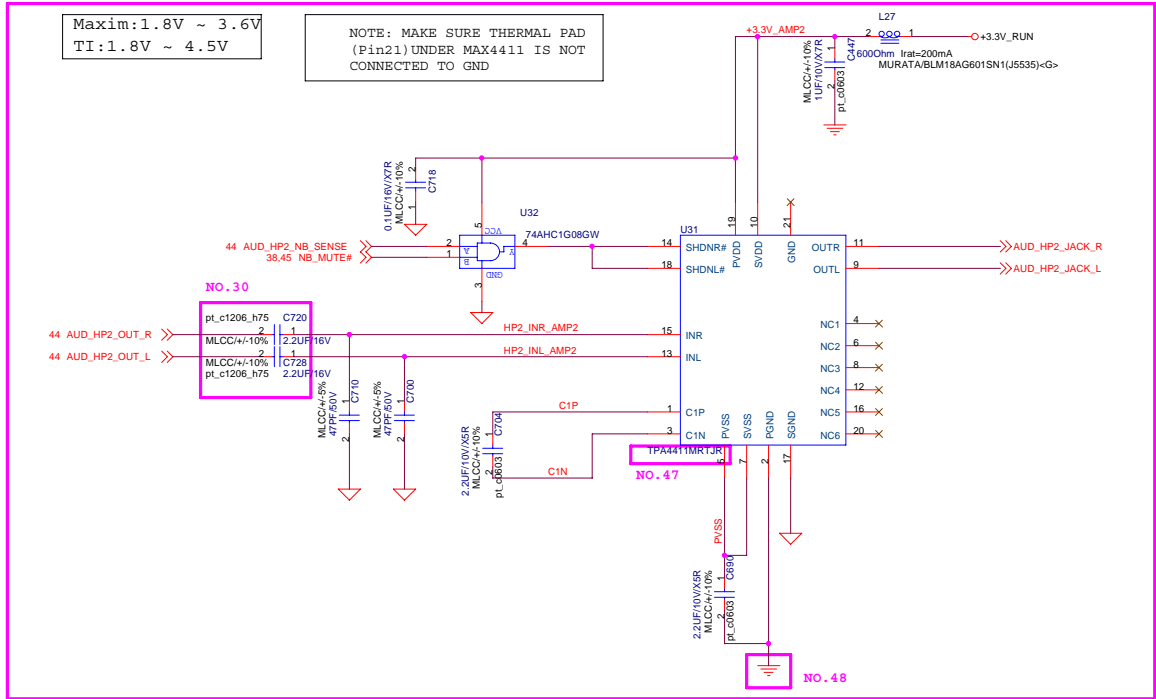


Change to 3.3V_RUN for CPVDD and HPVDD with bead.

VDDA Range = 1.21V ~ 4.85V (SET = 1.23V). If SET = 0V, VDDA = 4.75V

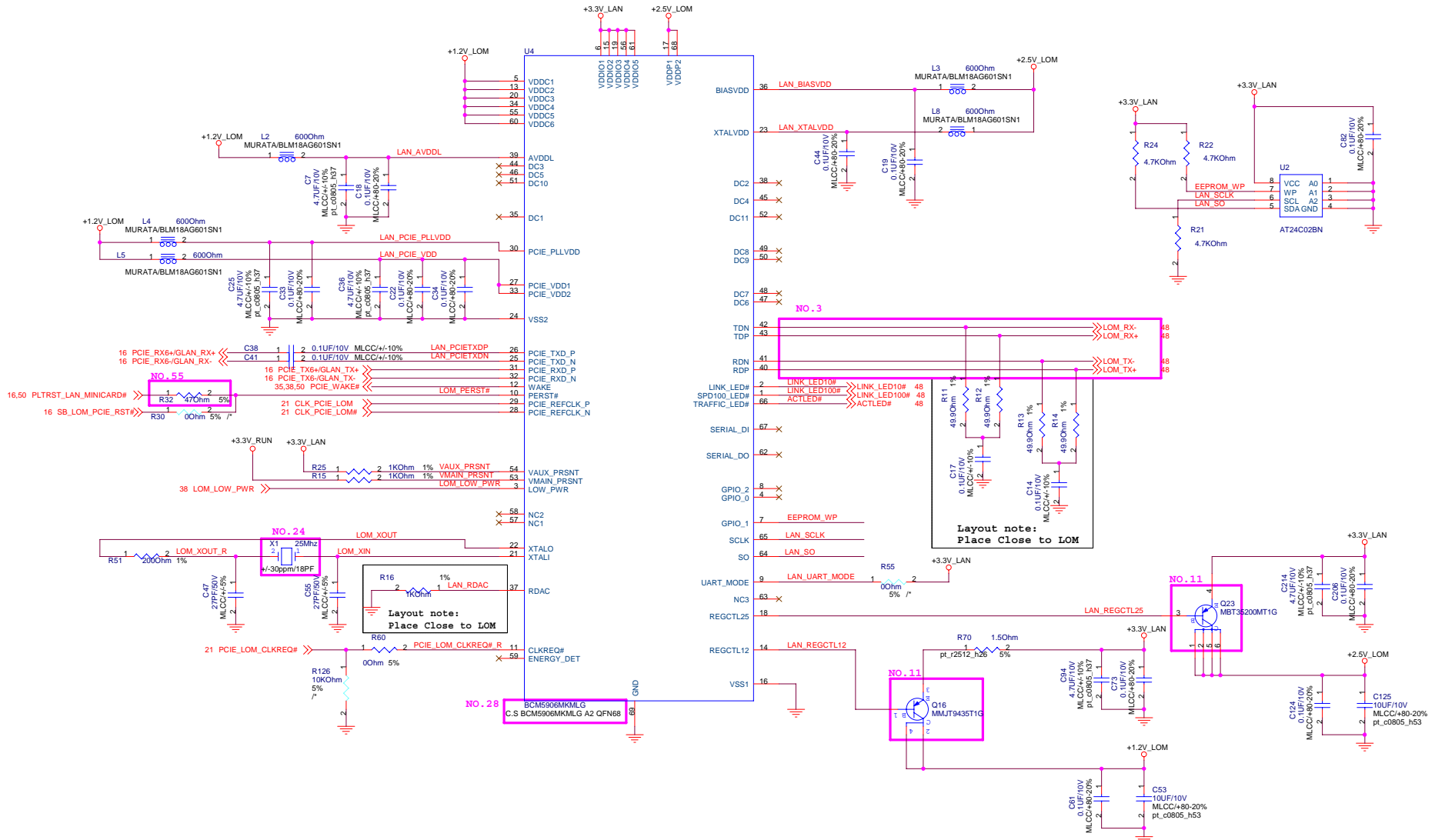
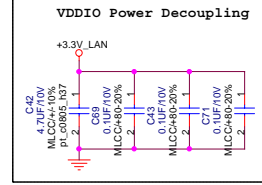
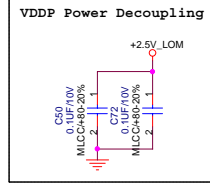
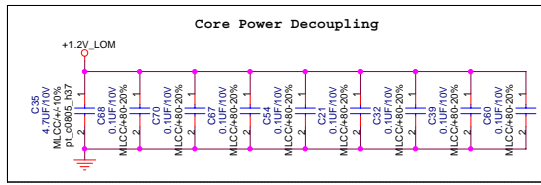
Note: For TPA6040A, pop R378 and no pop R375





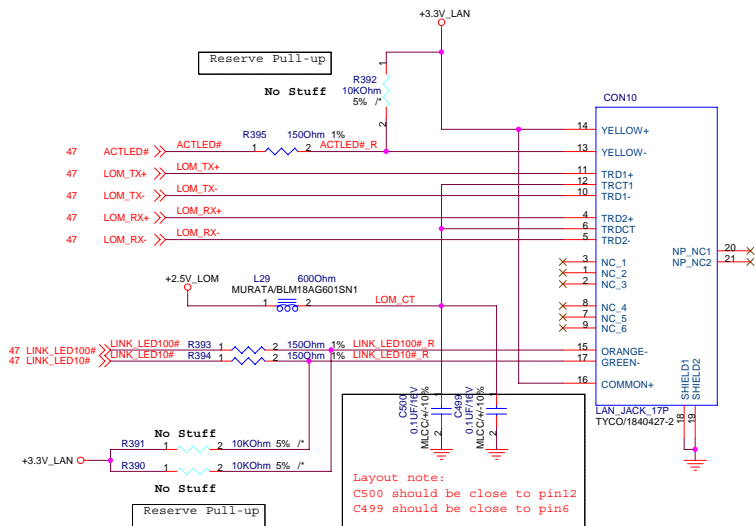
<Variant Name>

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHMATIC FILE NAME :	DESIGN ENGINEER :
	1.2	SHEET 46 OF 69	AMP MAX4411 & AUDIO JACKS	<OrgName>	Yihao Yeh



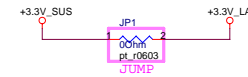
<Variant Name>

PROJECT: Lanai	REVISION	DATE: Monday, March 19, 2007	DESCRIPTION:	SCHEMATIC FILE NAME:	DESIGN ENGINEER:
	1.2	SHEET 47 OF 69	LAN BCM5906MKMLG(QFN-68)	<OrgName>	Ivan Chou
				RELEASE DATE:	



+3.3V LAN Source Guideline:

1. Use +3.3V_SUS if Wake-on-LAN is NOT required out of S4, S5
2. Use +3.3V_SRC if Wake-on-LAN is required out of S4, S5



Per EE schematic checklist item.87: Only support wake up from S3

<Variant Name>

PROJECT: Lanai

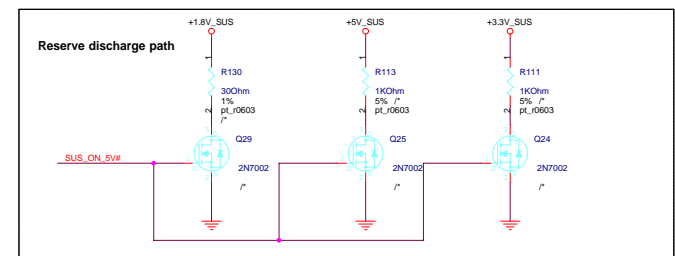
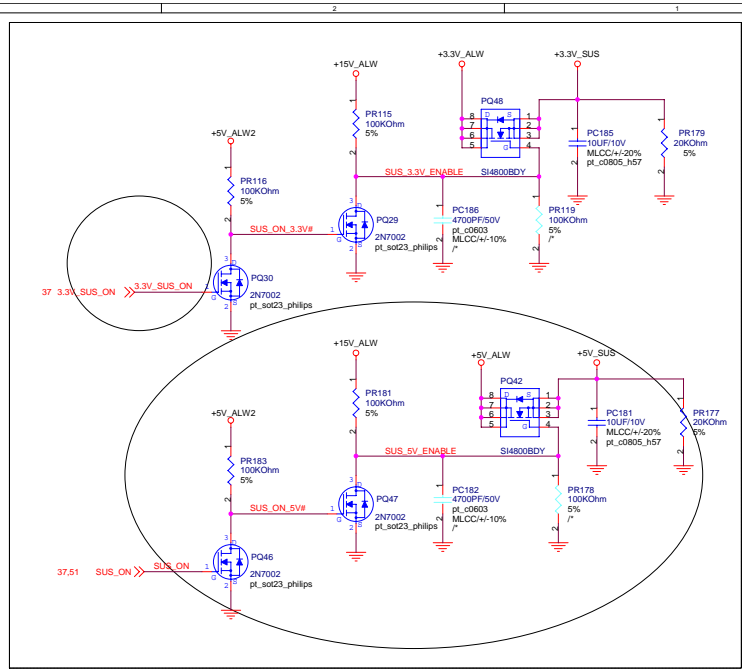
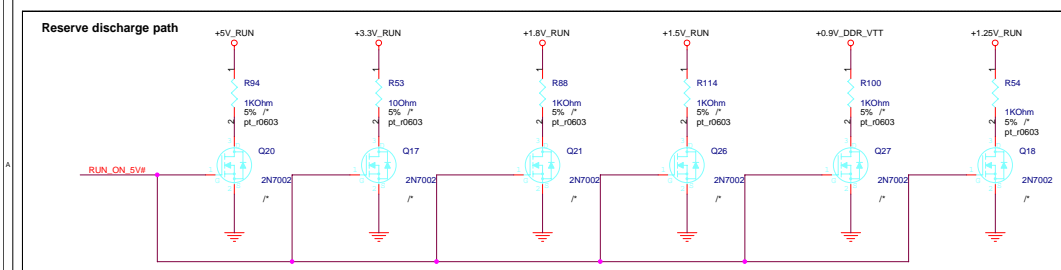
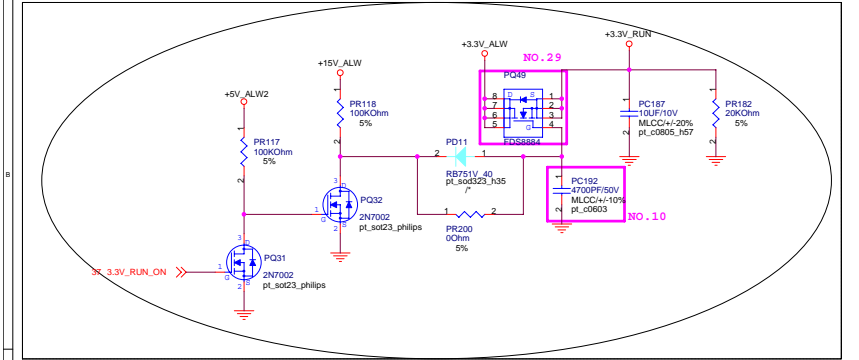
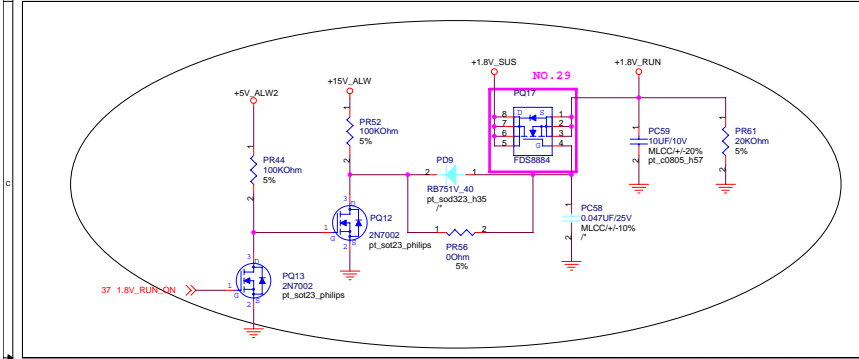
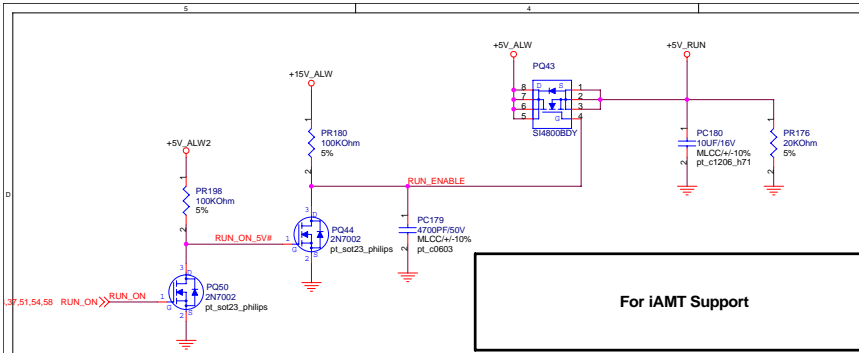
REVISION
1.2

DATE: **Monday, March 19, 2007**
SHEET **48** OF **69**

DESCRIPTION: **Magnetics and RJ-45**

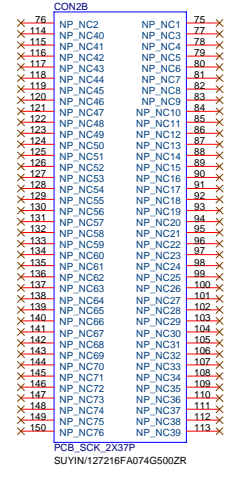
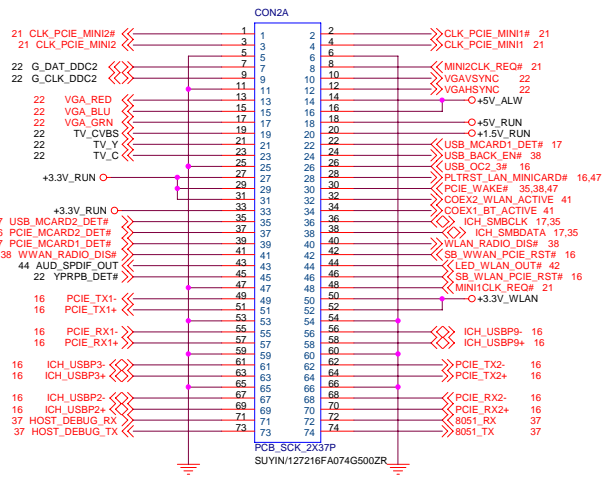
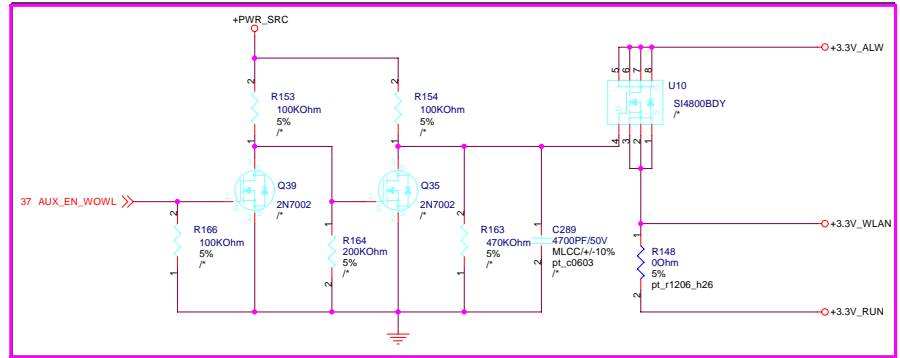
SCHEMATIC FILE NAME : **<OrgName>**
RELEASE DATE :

DESIGN ENGINEER :
Ivan Chou

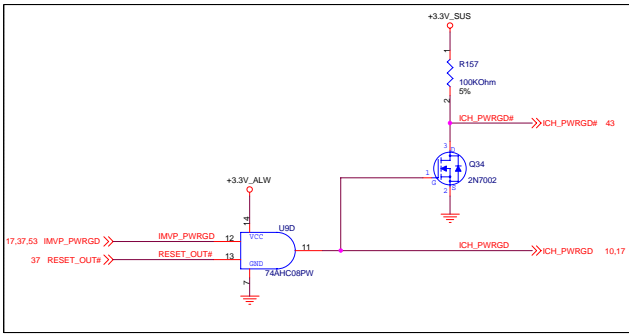
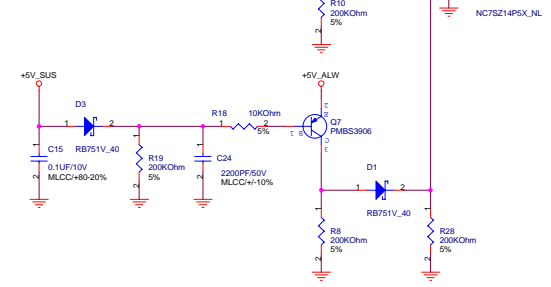
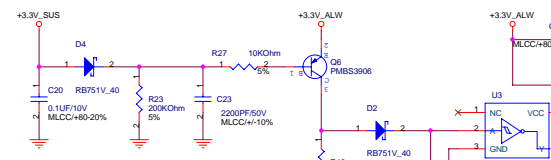
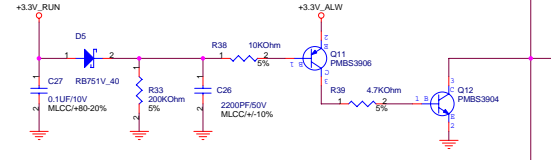
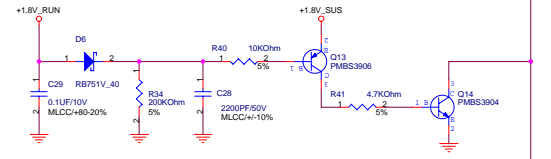
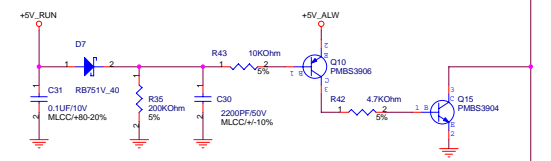


Variant Name:	PROJECT: Lanai	REVISION: 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: Power Control Switch	SCHEMATIC FILE NAME:	DESIGN ENGINEER: Eric Ko
		SHEET: 49	OF: 69		RELEASE DATE:	

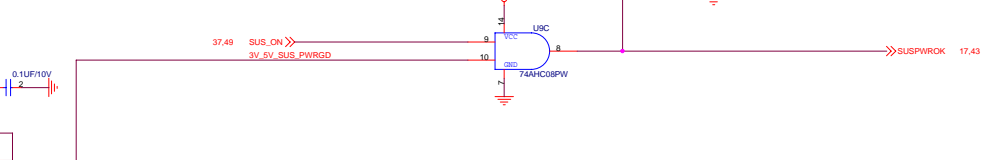
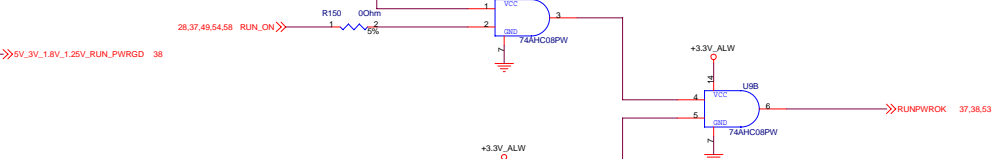
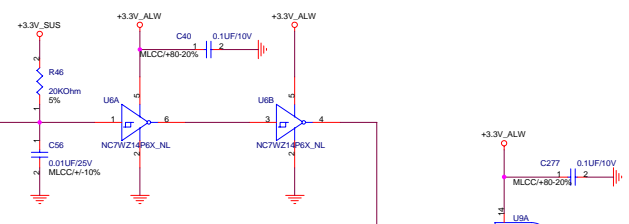
NO. 20



Discrete

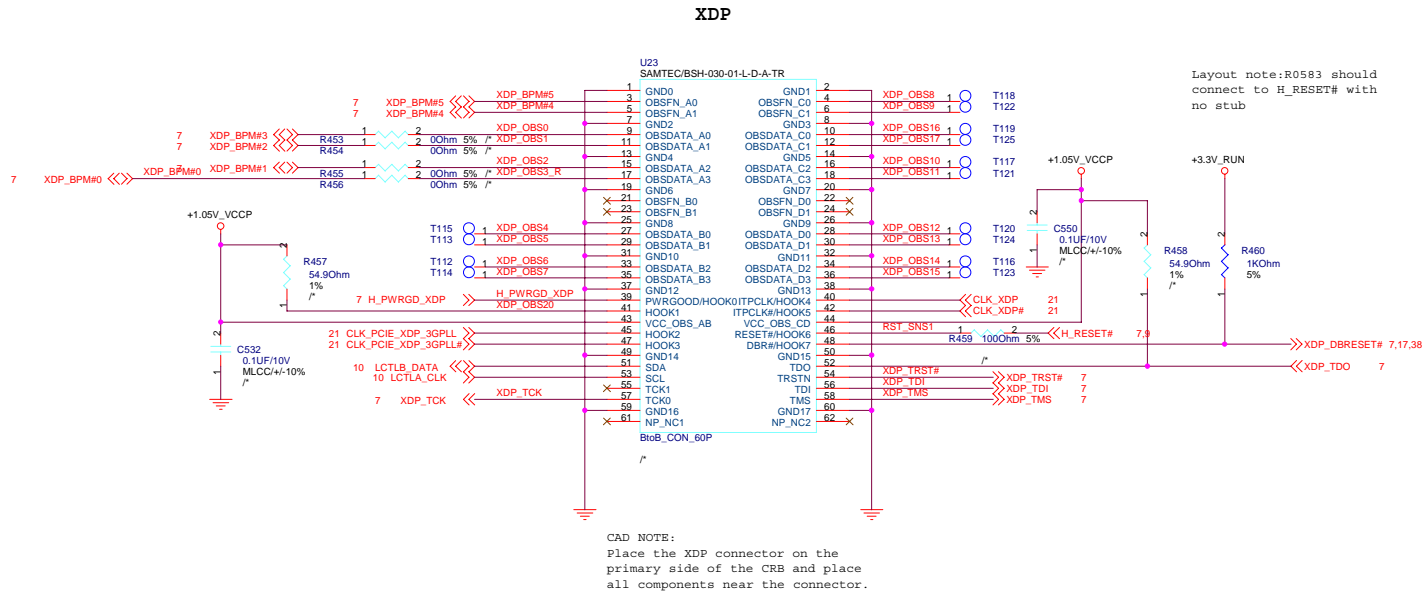


Keep Away from high speed buses



*Variant Name:

PROJECT: Lanai	REVISION: 1.2	DATE: Monday, March 19, 2007	DESCRIPTION: Power Sequence Logic	SCHEMATIC FILE NAME:	DESIGN ENGINEER: C.L. Ho
	SHEET: 51	OF: 69		RELEASE DATE:	



<Variant Name>

PROJECT: Lanai

REVISION
1.2

DATE: **Monday, March 19, 2007**
SHEET **52** OF **69**

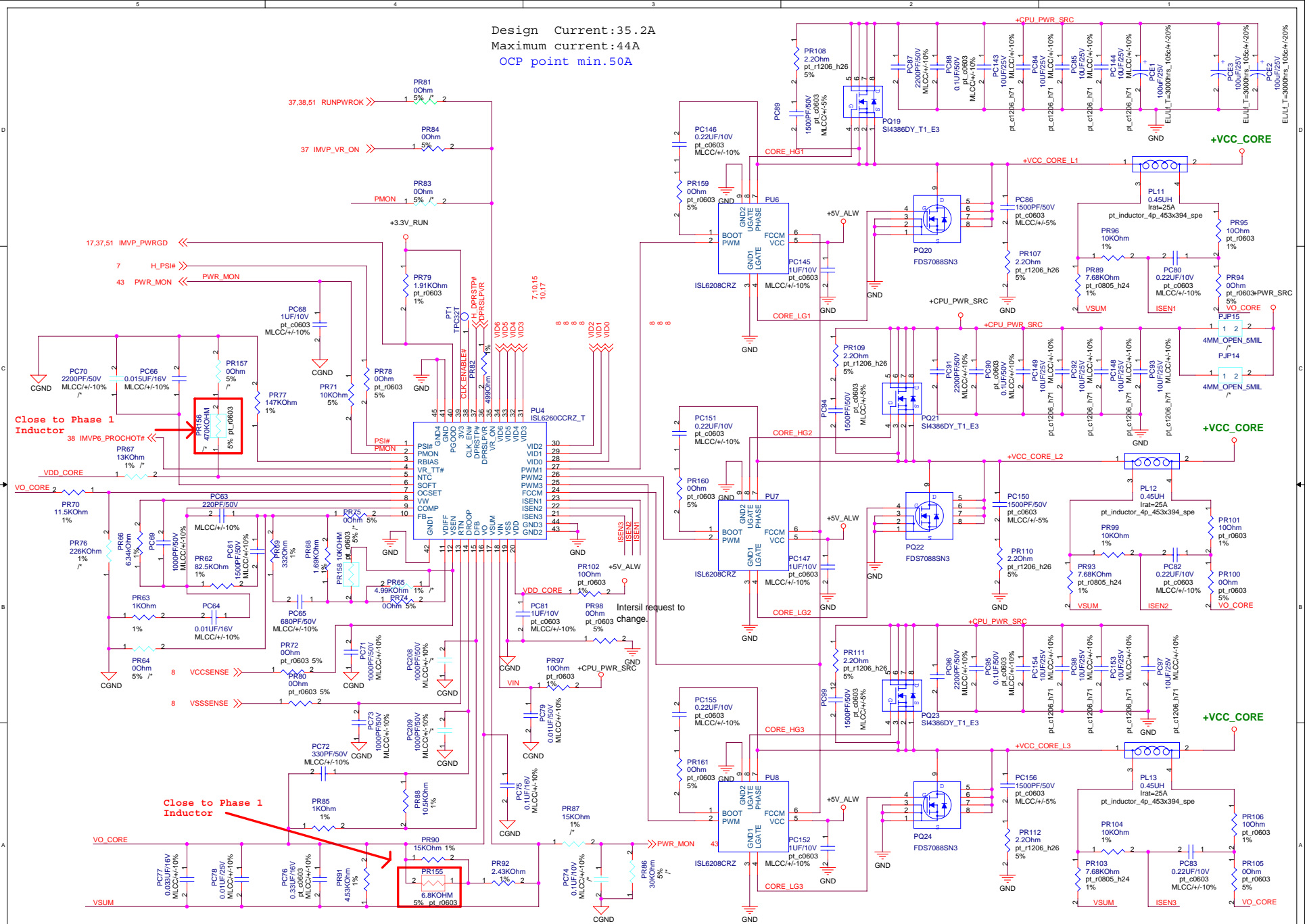
DESCRIPTION: **XDP**

SCHEMATIC FILE NAME :
RELEASE DATE :

<OrgName>

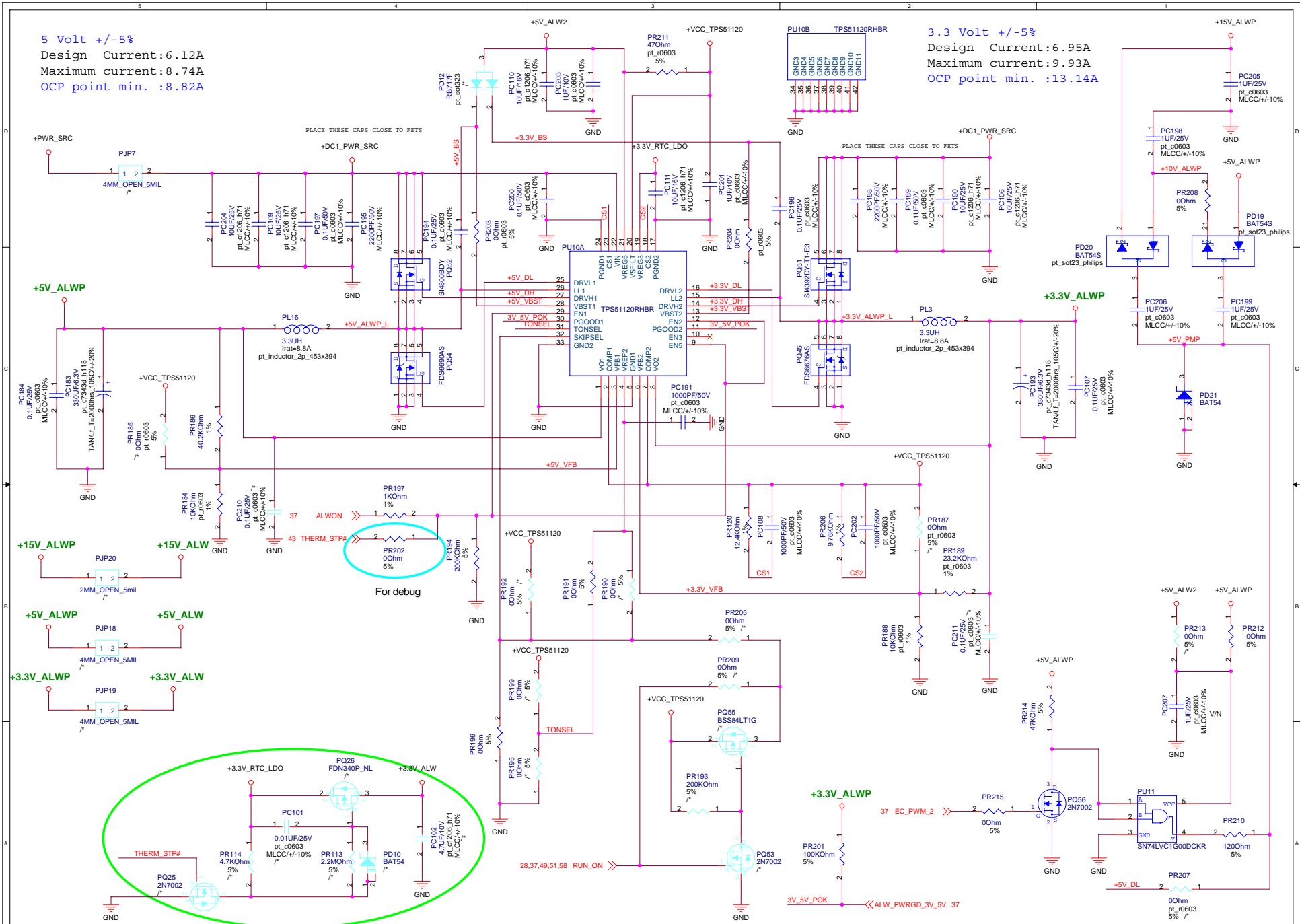
DESIGN ENGINEER :
Terry Lin

Design Current: 35.2A
 Maximum current: 44A
 OCP point min. 50A

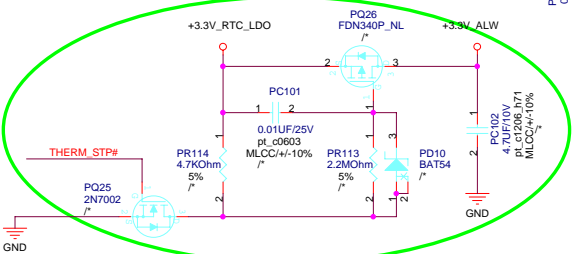


5 Volt +/-5%
 Design Current:6.12A
 Maximum current:8.74A
 OCP point min. :8.82A

3.3 Volt +/-5%
 Design Current:6.95A
 Maximum current:9.93A
 OCP point min. :13.14A

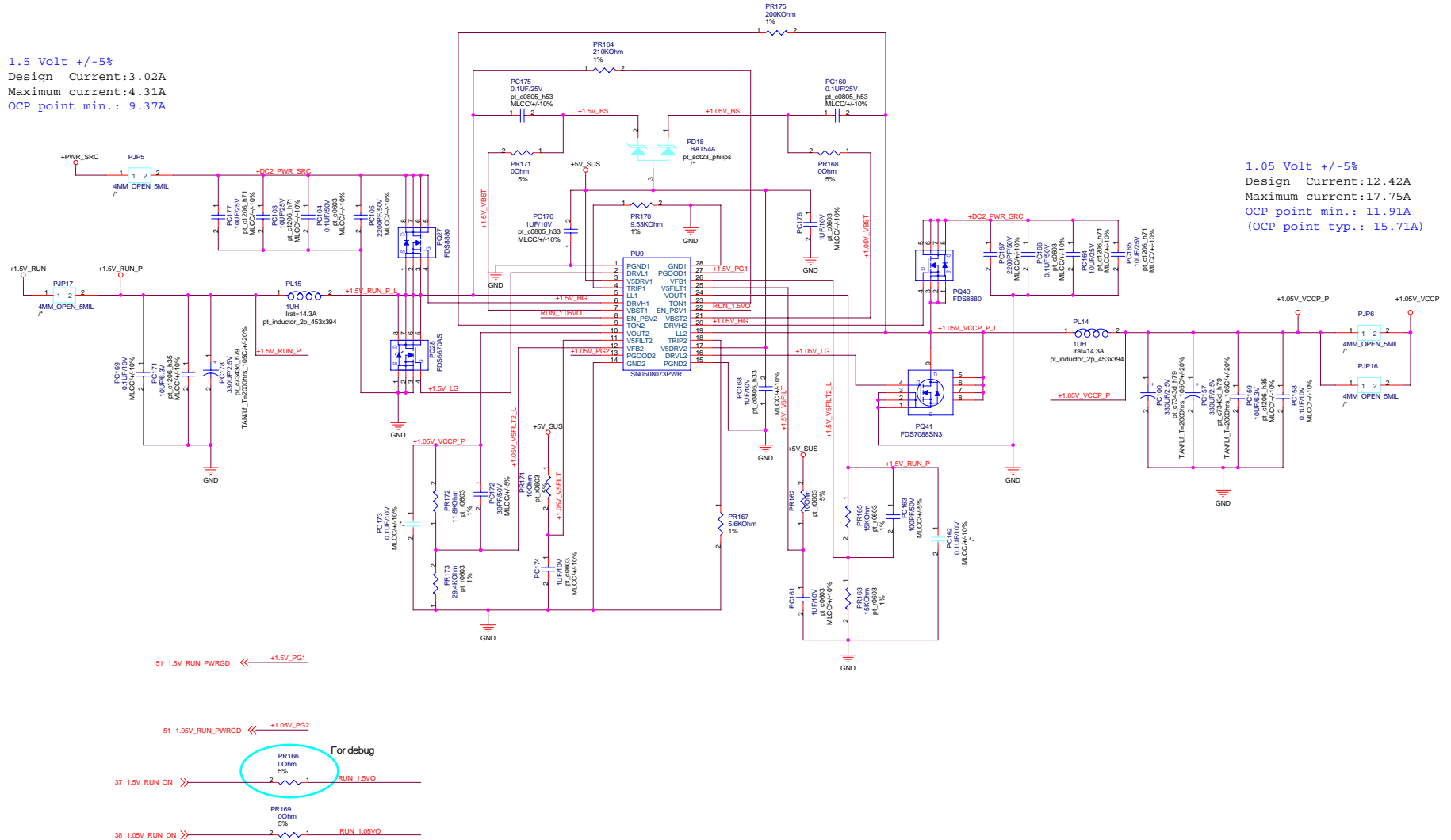


For debug



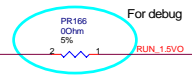
1.5 Volt +/-5%
 Design Current:3.02A
 Maximum current:4.31A
 OCP point min.: 9.37A

1.05 Volt +/-5%
 Design Current:12.42A
 Maximum current:17.75A
 OCP point min.: 11.91A
 (OCP point typ.: 15.71A)



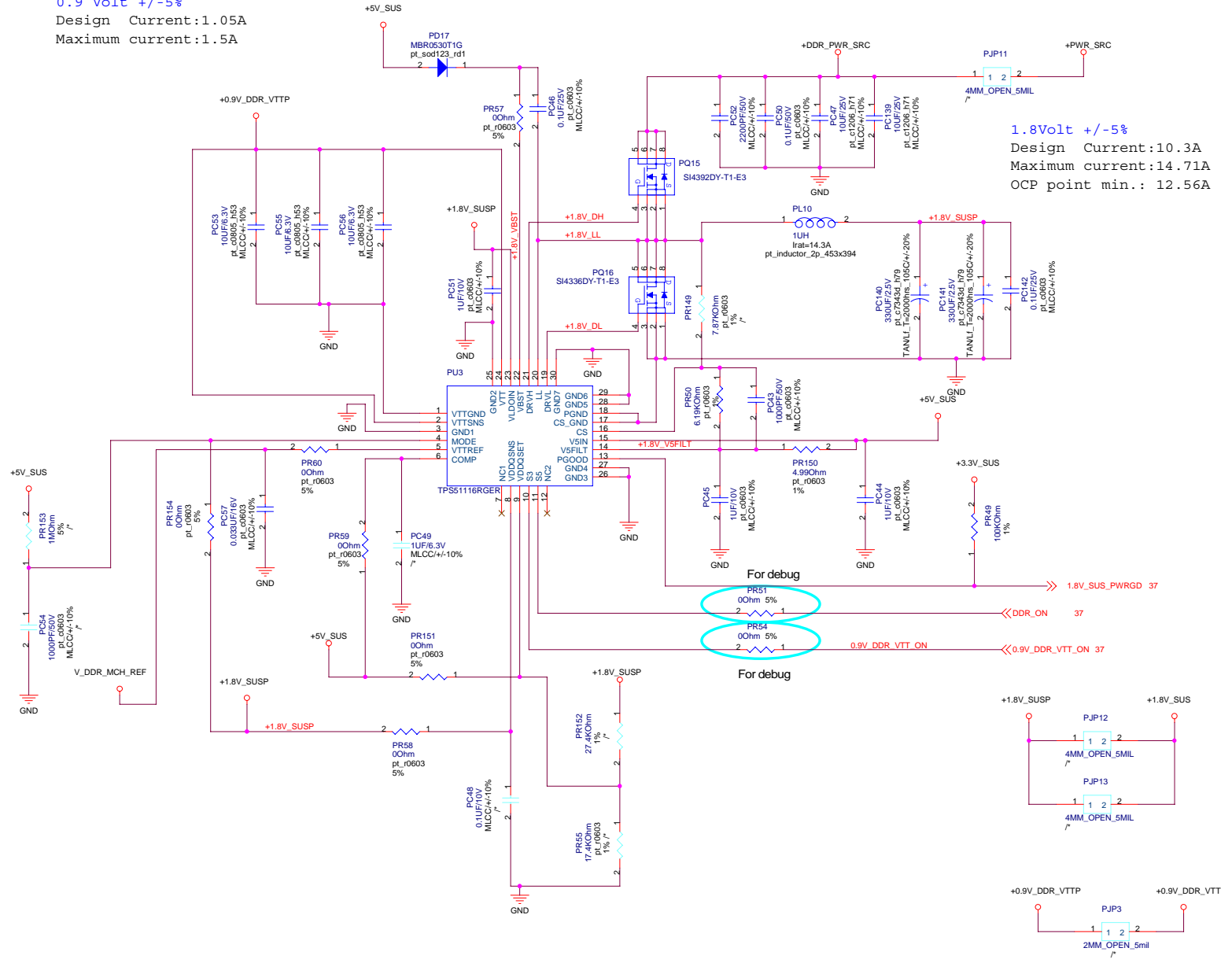
51 1.5V_RUN_PWRGD << +1.5V_PG1

51 1.05V_RUN_PWRGD << +1.05V_PG2



0.9 Volt +/-5%
 Design Current:1.05A
 Maximum current:1.5A

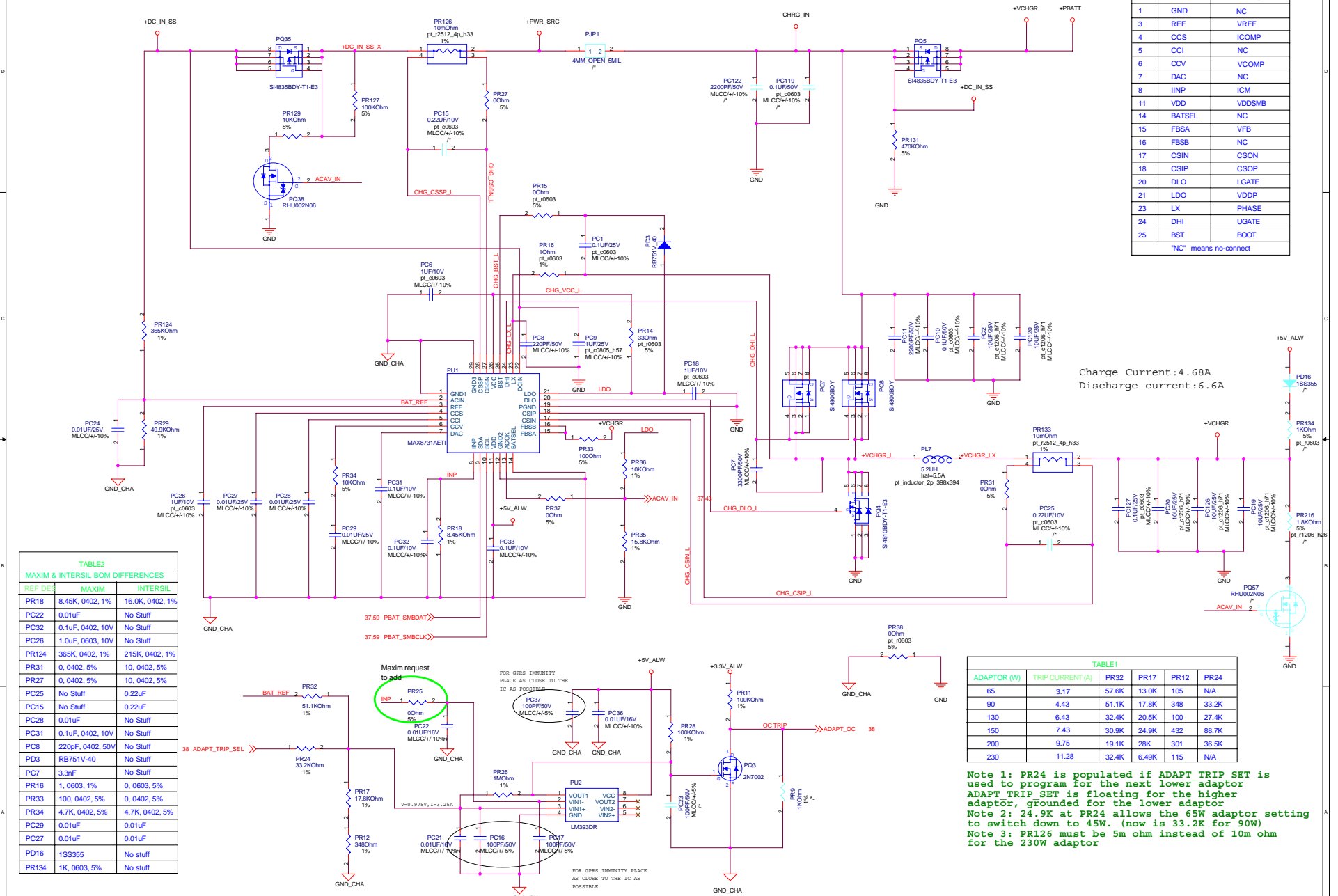
1.8Volt +/-5%
 Design Current:10.3A
 Maximum current:14.71A
 OCP point min.: 12.56A



TOTAL POWER=90W
-->4.62A

TABLE3		
PIN NAME DIFFERENCES		
PIN	MAXIM	INTERSIL
1	GND	NC
3	REF	VREF
4	CCS	ICOMP
5	CCI	NC
6	CCV	VCOMP
7	DAC	NC
8	IINP	ICM
11	VDD	VDDSMB
14	BATSEL	NC
15	FBSA	VFB
16	FBSB	NC
17	CSIN	CSON
18	CSIP	CSOP
20	DLO	LGATE
21	LDO	VDDP
23	LX	PHASE
24	DHI	LGATE
25	BST	BOOT

"NC" means no-connect



Charge Current:4.68A
Discharge current:6.6A

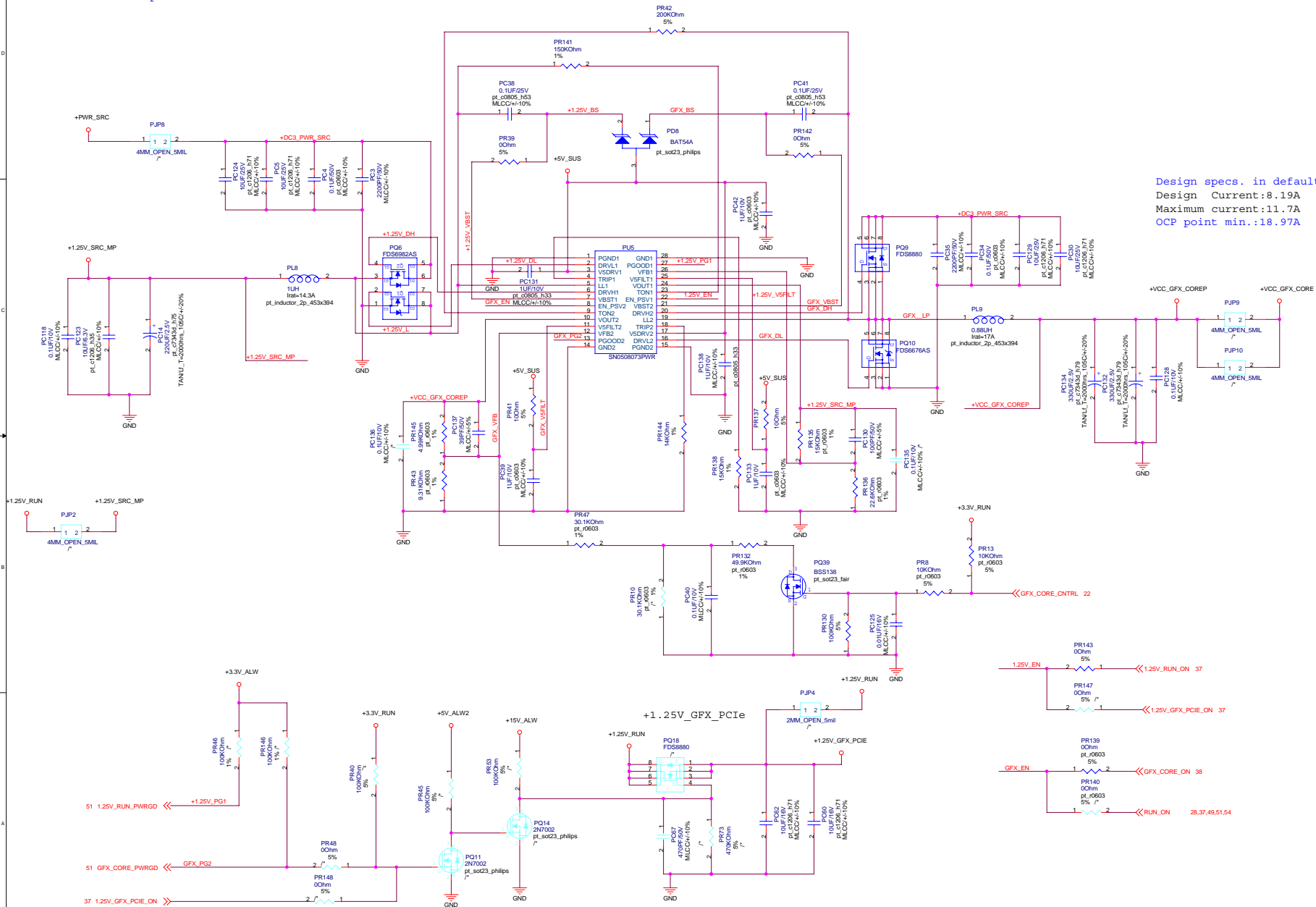
TABLE2		
MAXIM & INTERSIL BOM DIFFERENCES		
REF DES	MAXIM	INTERSIL
PR18	8.45K, 0.402, 1%	16.0K, 0.402, 1%
PC22	0.01uF	No Stuff
PC32	0.1uF, 0.402, 10V	No Stuff
PC26	1.0uF, 0.603, 10V	No Stuff
PR124	365K, 0.402, 1%	215K, 0.402, 1%
PR31	0, 0.402, 5%	10, 0.402, 5%
PR27	0, 0.402, 5%	10, 0.402, 5%
PC25	No Stuff	0.22uF
PC15	No Stuff	0.22uF
PC28	0.01uF	No Stuff
PC31	0.1uF, 0.402, 10V	No Stuff
PC8	220pF, 0.402, 50V	No Stuff
PD3	RB751V-40	No Stuff
PC7	3.3nF	No Stuff
PR16	1, 0.603, 1%	0, 0.603, 5%
PR33	100, 0.402, 5%	0, 0.402, 5%
PR34	4.7K, 0.402, 5%	4.7K, 0.402, 5%
PC29	0.01uF	0.01uF
PC27	0.01uF	0.01uF
PD16	1SS355	No stuff
PR134	1K, 0.603, 5%	No stuff

TABLE1					
ADAPTOR (W)	TRIP CURRENT (A)	PR32	PR17	PR12	PR24
65	3.17	57.6K	13.0K	105	N/A
90	4.43	51.1K	17.8K	348	33.2K
130	6.43	32.4K	20.5K	100	27.4K
150	7.43	30.9K	24.9K	432	88.7K
200	9.75	19.1K	28K	301	36.5K
230	11.28	32.4K	6.49K	115	N/A

Note 1: PR24 is populated if ADAPT TRIP SET is used to program for the next lower adaptor
ADAPT TRIP SET is floating for the higher adaptor, grounded for the lower adaptor
Note 2: 24.9K at PR24 allows the 65W adaptor setting to switch down to 45W. (now is 33.2K for 90W)
Note 3: PR126 must be 5m ohm instead of 10m ohm for the 230W adaptor

1.25Volt +/-5%
Design Current: 2.26A
Maximum current: 3.23A
OCP point min.: 9.59A

Design specs. in default:
Design Current: 8.19A
Maximum current: 11.7A
OCP point min.: 18.97A



PROJECT: Lanai

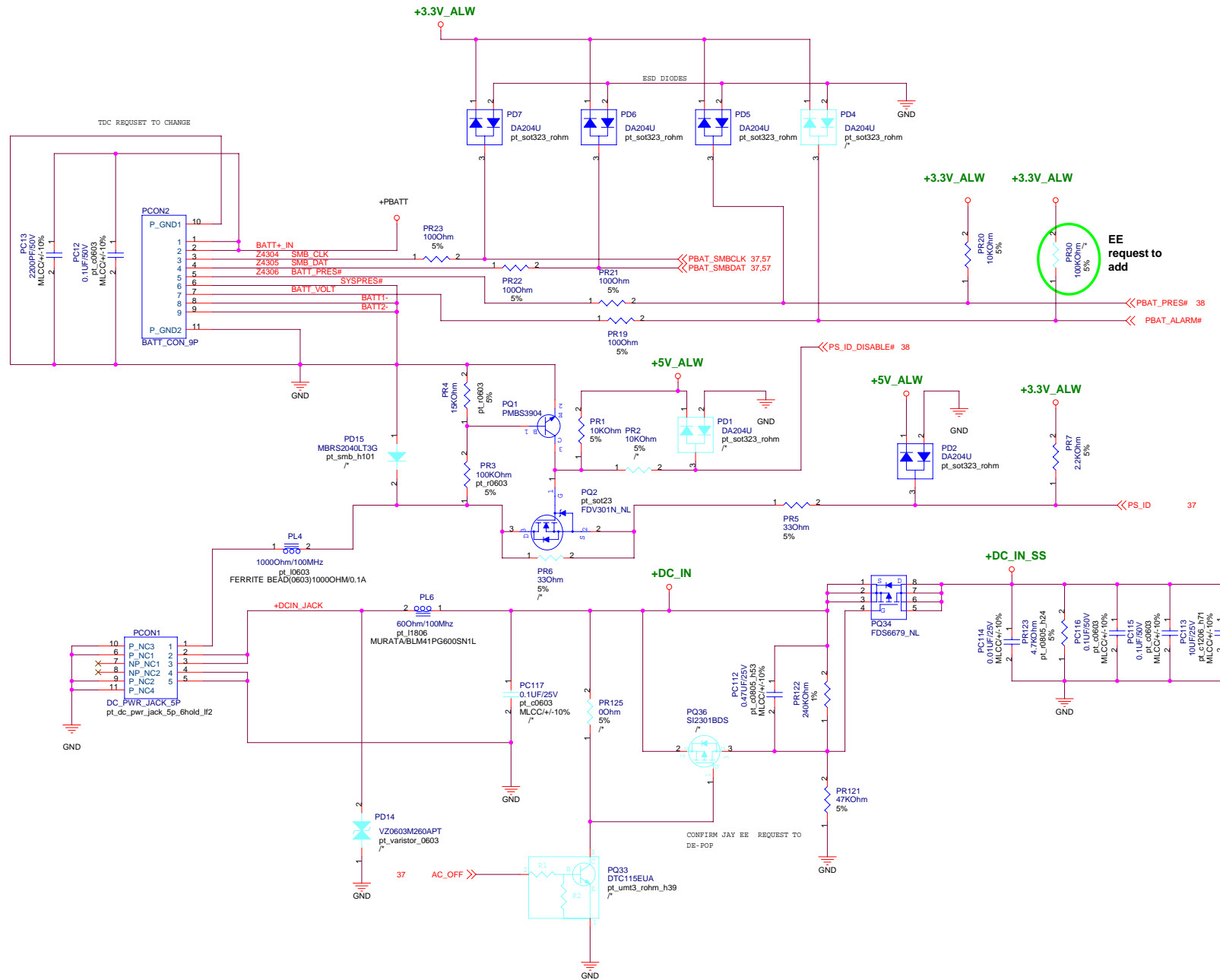
REVISION 1.1

DATE: Monday, March 19, 2007
SHEET 58 OF 69

DESCRIPTION: POWER VGA 1.25V & VCC GFX

SCHEMATIC FILE NAME : <OrgName>
RELEASE DATE :

DESIGN ENGINEER : JEFF



PROJECT: Lanai

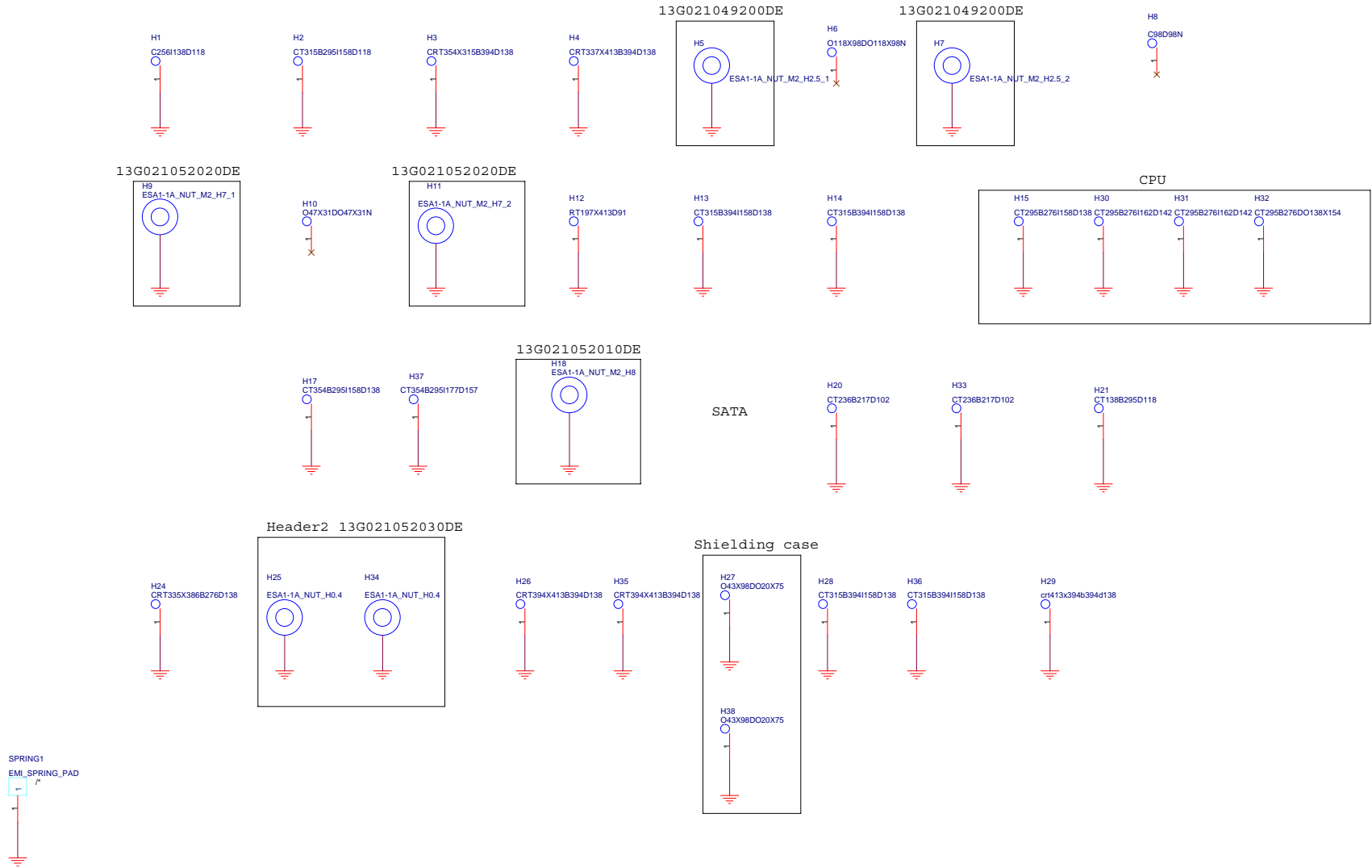
REVISION: 1.1
 DATE: Monday, March 19, 2007
 SHEET: 59 OF 69

DESCRIPTION: POWER_CONNECTOR

SCHEMATIC FILE NAME: <OrgName>
 RELEASE DATE:

DESIGN ENGINEER: JEFF

PM screw pad



PROJECT: Lanai

REVISION
1.2

DATE: Monday, March 19, 2007
SHEET 60 OF 69

DESCRIPTION: SCREW PAD

SCHEMATIC FILE NAME :
RELEASE DATE :

DESIGN ENGINEER : Sean Kuo

ASUS CONFIDENTIAL

MODEL NAME : *Elsa*

PCB NO : ???

ASUS P/N : ???

Lanai USB Board

REV :1.1(DELL: X01)

MB PCB

Part Number	Description
DA80004H0L	PCB 00B LA-3071P REV0 M/B

BOM NO. ???

PCB P/N: ???

PROJECT: **Lanai**

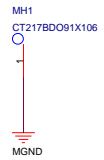
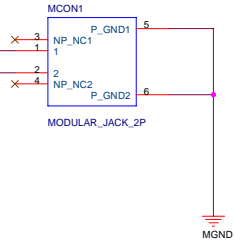
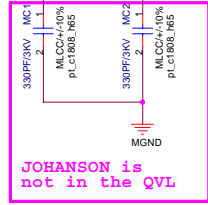
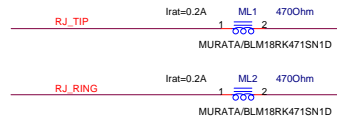
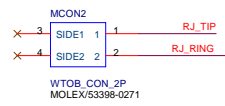
REVISION
1.2

DATE: **Monday, March 19, 2007**
SHEET **65** OF **69**

DESCRIPTION: **Cover Page**

SCHEMATIC FILE NAME :
RELEASE DATE :

DESIGN ENGINEER :
Terry Lin

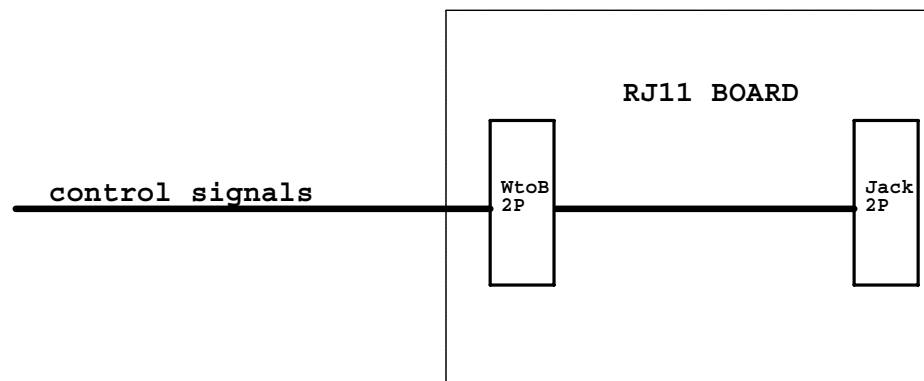


ASUS CONFIDENTIAL

MODEL NAME : *Elsa*

Lanai Modem Board

REV :1.1(DELL: X01)



PROJECT: **Lanai**

REVISION
1.2

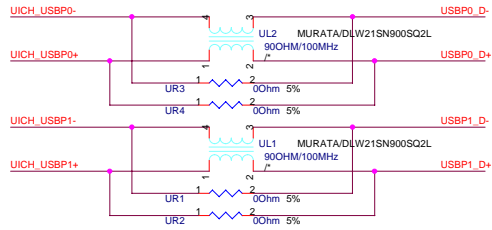
DATE: *Monday, March 19, 2007*
SHEET **68** OF **69**

DESCRIPTION:
BLOCK DIAGRAM

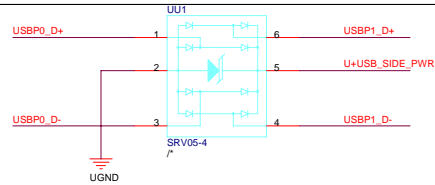
SCHEMATIC FILE NAME :
RELEASE DATE :

DESIGN ENGINEER :
Stanly Hsu

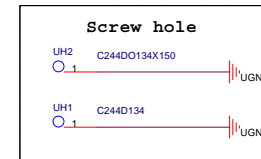
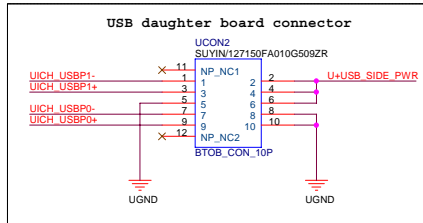
External USB PORT hookup reference. Your design may need more or less external ports and may be mapped differently .



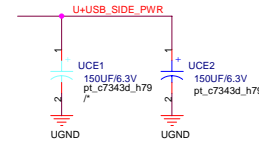
Platforms should put in PADS for the USB chokes if they have the room. Chokes should be NOPOP.



Place ESD diodes as close as USB connector. Semtech SRV05-4 can also be used but the Philips IP42220CZ6 have a lower input C (1pf vs 3pf) .



Place one 150uF cap by each USB connector



Each channel is 1A

Consult you ESD Engineer if you think you may need to add ESD Supression Components to your USB lines. Add PADS ONLY until proven diodes are really needed.

